

# TPS6521835 Power Management IC (PMIC) for NXP i.MX 6ULL, 6ULZ, and 6UltraLite

## 1 Features

- Three Adjustable Step-Down Converters With Integrated Switching FETs (DCDC1, DCDC2, and DCDC3):
  - DCDC1: 1.28-V Default, up to 1.8 A
  - DCDC2: 1.35-V Default, up to 1.8 A
  - DCDC3: 3.3-V Default, up to 1.8 A
  - VIN Range From 2.7 V to 5.5 V
  - Adjustable Output Voltage Range 0.85 V to 1.675 V (DCDC1 and DCDC2)
  - Adjustable Output Voltage Range 0.9 V to 3.4 V (DCDC3)
  - Power Save Mode at Light Load Current
  - 100% Duty Cycle for Lowest Dropout
  - Active Output-Discharge When Disabled
- One Adjustable Buck-Boost Converter With Integrated Switching FETs (DCDC4):
  - DCDC4: 1.8-V Default, up to 1.6 A
  - VIN Range from 2.7 V to 5.5 V
  - Adjustable Output Voltage Range from 1.175 V to 3.4 V
  - Active Output-Discharge When Disabled
- Two Low-Quiescent Current, High Efficiency Step-Down Converters for Battery Backup Domain (DCDC5, DCDC6)
  - DCDC5: 1-V Output
  - DCDC6: 1.8-V Output
  - VIN Range from 2.2 V to 5.5 V
  - Supplied From System Power or Coin-Cell Backup Battery
- Adjustable General-Purpose LDO (LDO1)
  - LDO1: 2.8-V Default up to 400 mA
  - VIN Range from 1.8 V to 5.5 V
  - Adjustable Output Voltage Range from 0.9 V to 3.4 V
  - Active Output-Discharge When Disabled
- Low-Voltage Load Switch (LS1) With 350-mA Current Limit
  - VIN Range From 1.2 V to 3.6 V
  - 110-mΩ (Max) Switch Impedance at 1.35 V
- 5-V Load Switch (LS2) With 100-mA or 500-mA Selectable Current Limit
  - VIN Range From 4 V to 5.5 V
  - 500-mΩ (Max) Switch Impedance at 5 V
- High-Voltage Load Switch (LS3) With 100-mA or 500-mA Selectable Current Limit
  - VIN Range From 1.8 V to 10 V
  - 500-mΩ (Max) Switch Impedance
- Supervisor With Built-in Supervisor Function Monitors

- DCDC1, DCDC2  $\pm 4\%$  Tolerance
- DCDC3, DCDC4  $\pm 5\%$  Tolerance
- LDO1  $\pm 5\%$  Tolerance
- Protection, Diagnostics, and Control:
  - Undervoltage Lockout (UVLO)
  - Always-on Push-Button Monitor
  - Overtemperature Warning and Shutdown
  - Separate Power-Good Output for Backup and Main Supplies
  - I<sup>2</sup>C Interface (Address 0x24) (See [Timing Requirements](#) for I<sup>2</sup>C Operation at 400 kHz)

## 2 Applications

- [Human-Machine Interface \(HMI\)](#)
- [Industrial Automation](#)
- [Electronic Point of Sale \(ePOS\)](#)
- [Test and Measurement](#)
- [Personal Navigation](#)

## 3 Description

The TPS6521835 is a single chip power management IC, specifically designed to support both portable (Li-Ion battery) and non-portable (5-V adapter) applications. The device is characterized across a –40°C to +105°C temperature range, making it suitable for a wide range of industrial applications.

### Device Information<sup>(1)</sup>

| PART NUMBER | PACKAGE   | BODY SIZE (NOM)   |
|-------------|-----------|-------------------|
| TPS6521835  | VQFN (48) | 6.00 mm × 6.00 mm |

- (1) For all available packages, see the orderable addendum at the end of the data sheet.



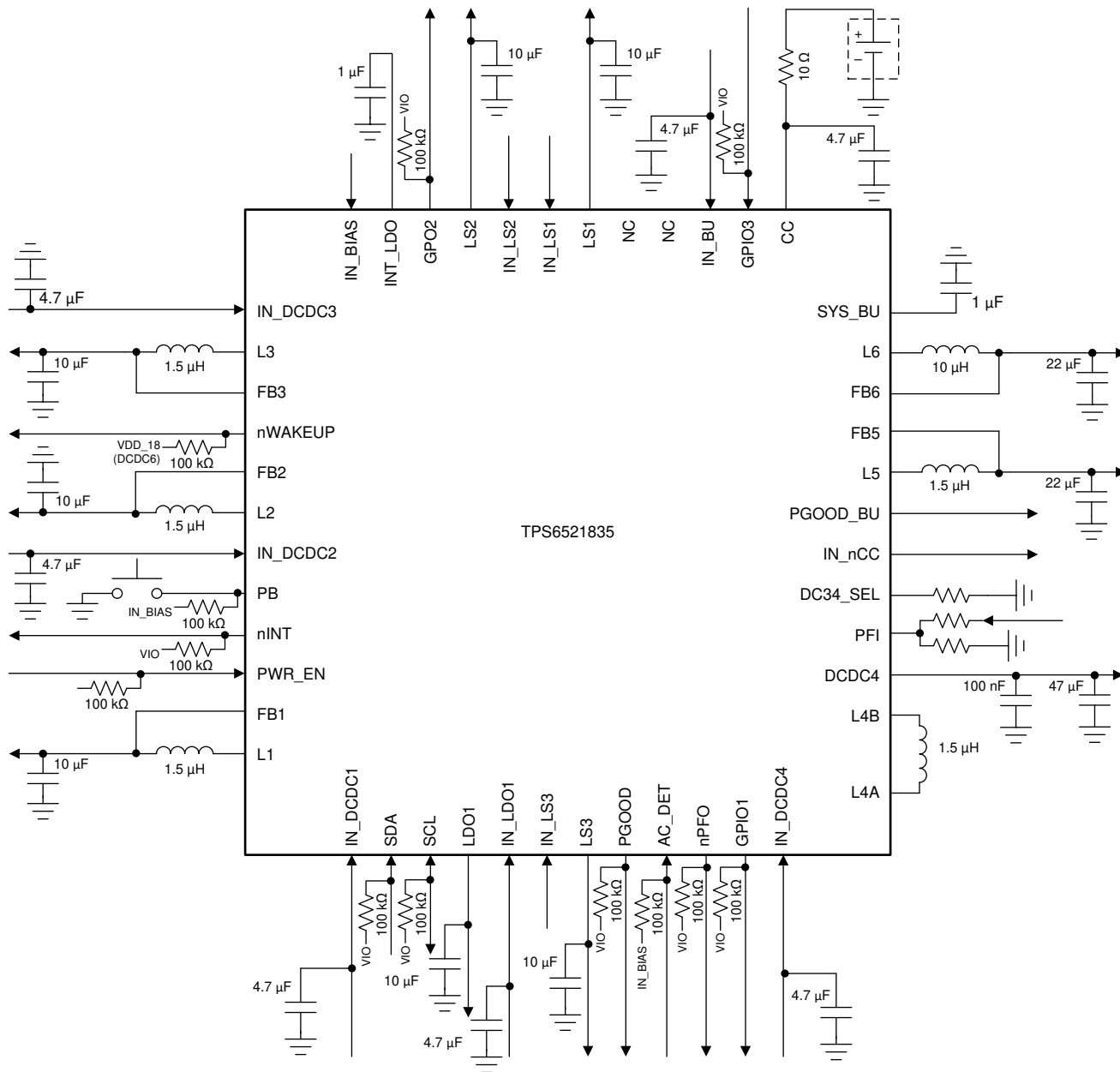


Figure 3-1. Simplified Schematic

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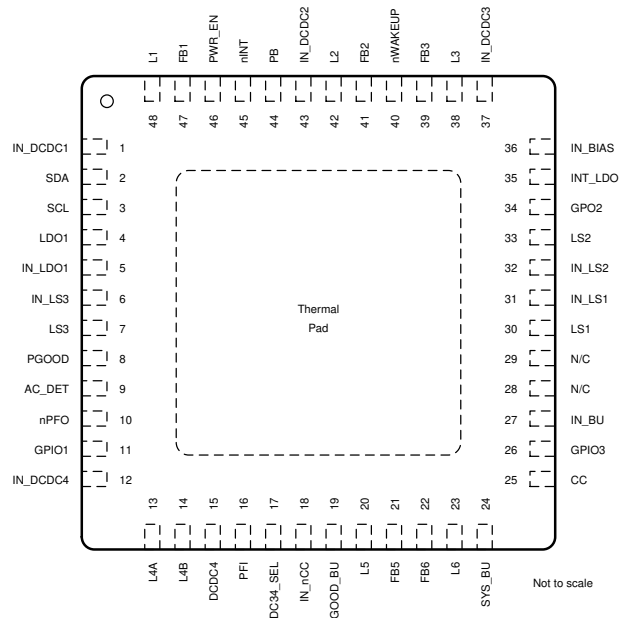
## 4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

| <b>Changes from Revision * (November 2020) to Revision A (August 2021)</b> | <b>Page</b> |
|----------------------------------------------------------------------------|-------------|
| • Changed DCDC1 default voltage from 1.1-V to 1.28-V.....                  | <b>1</b>    |
| • Changed DCDC2 default voltage from 1.1-V to 1.35-V.....                  | <b>1</b>    |
| • Changed DCDC3 default voltage from 1.2-V to 3.3-V.....                   | <b>1</b>    |
| • Changed DCDC4 default voltage from 3.3-V to 1.8-V.....                   | <b>1</b>    |
| • Changed LDO1 voltage from 1.8-V to 2.8-V.....                            | <b>1</b>    |

## 5 Pin Configuration and Functions

Figure 5-1 shows the 48-pin RSL Plastic Quad Flatpack No-Lead.



**Figure 5-1. 48-Pin RSL VQFN With Exposed Thermal Pad (Top View, 6 mm × 6 mm × 1 mm With 0.4-mm Pitch)**

**Table 5-1. Pin Functions**

| PIN<br>NO. | NAME     | TYPE | DESCRIPTION                                                                                                                                                                     |
|------------|----------|------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
|            |          |      |                                                                                                                                                                                 |
| 1          | IN_DCDC1 | P    | Input supply pin for DCDC1.                                                                                                                                                     |
| 2          | SDA      | I/O  | Data line for the I <sup>2</sup> C interface. Connect to pullup resistor.                                                                                                       |
| 3          | SCL      | I    | Clock input for the I <sup>2</sup> C interface. Connect to pullup resistor.                                                                                                     |
| 4          | LDO1     | O    | Output voltage pin for LDO1. Connect to capacitor.                                                                                                                              |
| 5          | IN_LDO1  | P    | Input supply pin for LDO1.                                                                                                                                                      |
| 6          | IN_LS3   | P    | Input supply pin for load switch 3.                                                                                                                                             |
| 7          | LS3      | O    | Output voltage pin for load switch 3. Connect to capacitor.                                                                                                                     |
| 8          | PGOOD    | O    | Power-good output (configured as open drain). Pulled low when either DCDC1-4 or LDO1 are out of regulation. Load switches and DCDC5-6 do not affect PGOOD pin.                  |
| 9          | AC_DET   | I    | AC monitor input and enable for DCDC1-4, LDO1 and load switches. See <a href="#">Section 7.4.1</a> for details. Tie pin to IN_BIAS if not used.                                 |
| 10         | nPFO     | O    | Power-fail comparator output, deglitched (open drain). Pin is pulled low when PFI input is below power-fail threshold.                                                          |
| 11         | GPIO1    | I/O  | Pin configured as DDR reset-input (driving GPO2) or as general-purpose, open-drain output. See <a href="#">Section 7.3.1.14</a> for more information.                           |
| 12         | IN_DCDC4 | P    | Input supply pin for DCDC4.                                                                                                                                                     |
| 13         | L4A      | P    | Switch pin for DCDC4. Connect to inductor.                                                                                                                                      |
| 14         | L4B      | P    | Switch pin for DCDC4. Connect to inductor.                                                                                                                                      |
| 15         | DCDC4    | P    | Output voltage pin for DCDC4. Connect to capacitor.                                                                                                                             |
| 16         | PFI      | I    | Power-fail comparator input. Connect to resistor divider.                                                                                                                       |
| 17         | DC34_SEL | I    | Power-up default selection pin for DCDC3 or DCDC4. Power-up default is programmed by a resistor connected to ground. See <a href="#">Section 7.3.1.13</a> for resistor options. |

**Table 5-1. Pin Functions (continued)**

| PIN |             | TYPE | DESCRIPTION                                                                                                                                                                                                                                         |
|-----|-------------|------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| NO. | NAME        |      |                                                                                                                                                                                                                                                     |
| 18  | IN_nCC      | O    | Output pin indicates if DCDC5 and DCDC6 are powered from main supply (IN_BU) or coin-cell battery (CC). Pin is push-pull output. Pulled low when PMIC is powered from coin cell battery. Pulled high when PMIC is powered from main supply (IN_BU). |
| 19  | PGOOD_BU    | O    | Power-good, push-pull output for DCDC5 and DCDC6. Pulled low when either DCDC5 or DCDC6 is out of regulation. Pulled high (to DCDC6 output voltage) when both rails are in regulation.                                                              |
| 20  | L5          | P    | Switch pin for DCDC5. Connect to inductor.                                                                                                                                                                                                          |
| 21  | FB5         | I    | Feedback voltage pin for DCDC5. Connect to output capacitor.                                                                                                                                                                                        |
| 22  | FB6         | I    | Feedback voltage pin for DCDC6. Connect to output capacitor.                                                                                                                                                                                        |
| 23  | L6          | P    | Switch pin for DCDC6. Connect to inductor.                                                                                                                                                                                                          |
| 24  | SYS_BU      | P    | System voltage pin for battery-backup supply power path. Connect to 1-μF capacitor. Connecting any external load to this pin is not recommended.                                                                                                    |
| 25  | CC          | P    | Coin cell battery input. Serves as the supply to DCDC5 and DCDC6 if no voltage is applied to IN_BU. Tie this pin to ground if it is not in use.                                                                                                     |
| 26  | GPIO3       | I/O  | Pin can be configured as warm reset (negative edge) for DCDC1 and DCDC2 or as a general-purpose, open-drain output. See <a href="#">Section 7.3.1.14</a> for more details.                                                                          |
| 27  | IN_BU       | P    | Default input supply pin for battery backup supplies (DCDC5 and DCDC6).                                                                                                                                                                             |
| 28  | N/C         | —    | No connect. Leave pin floating.                                                                                                                                                                                                                     |
| 29  | N/C         |      |                                                                                                                                                                                                                                                     |
| 30  | LS1         | O    | Output voltage pin for load switch 1. Connect to capacitor.                                                                                                                                                                                         |
| 31  | IN_LS1      | P    | Input supply pin for load switch 1.                                                                                                                                                                                                                 |
| 32  | IN_LS2      | P    | Input supply pin for load switch 2.                                                                                                                                                                                                                 |
| 33  | LS2         | O    | Output voltage pin for load switch 2. Connect to capacitor.                                                                                                                                                                                         |
| 34  | GPO2        | O    | Pin configured as DDR reset signal (controlled by GPIO1) or as general-purpose output. Buffer can be configured as push-pull or open-drain.                                                                                                         |
| 35  | INT_LDO     | P    | Internal bias voltage. Connecting any external load to this pin is not recommended.                                                                                                                                                                 |
| 36  | IN_BIAS     | P    | Input supply pin for reference system.                                                                                                                                                                                                              |
| 37  | IN_DCDC3    | P    | Input supply pin for DCDC3.                                                                                                                                                                                                                         |
| 38  | L3          | P    | Switch pin for DCDC3. Connect to inductor.                                                                                                                                                                                                          |
| 39  | FB3         | I    | Feedback voltage pin for DCDC3. Connect to output capacitor.                                                                                                                                                                                        |
| 40  | nWAKEUP     | O    | Signal to SOC to indicate a power on event (active low, open-drain output).                                                                                                                                                                         |
| 41  | FB2         | I    | Feedback voltage pin for DCDC2. Connect to output capacitor.                                                                                                                                                                                        |
| 42  | L2          | P    | Switch pin for DCDC2. Connect to inductor.                                                                                                                                                                                                          |
| 43  | IN_DCDC2    | P    | Input supply pin for DCDC2.                                                                                                                                                                                                                         |
| 44  | PB          | I    | Push-button monitor input. Typically connected to a momentary switch to ground (active low). See <a href="#">Section 7.4.1</a> for details.                                                                                                         |
| 45  | nINT        | O    | Interrupt output (active low, open drain). Pin is pulled low if an interrupt bit is set. The pin returns to Hi-Z state after the bit causing the interrupt has been read. Interrupts can be masked.                                                 |
| 46  | PWR_EN      | I    | Power enable input for DCDC1-4, LDO1 and load switches. See <a href="#">Section 7.4.1</a> for details.                                                                                                                                              |
| 47  | FB1         | I    | Feedback voltage pin for DCDC1. Connect to output capacitor.                                                                                                                                                                                        |
| 48  | L1          | P    | Switch pin for DCDC1. Connect to inductor.                                                                                                                                                                                                          |
| —   | Thermal Pad | P    | Power ground and thermal relief. Connect to ground plane.                                                                                                                                                                                           |

## 6 Specifications

### 6.1 Absolute Maximum Ratings

Operating under free-air temperature range (unless otherwise noted).<sup>(1)</sup>

|                        |                                                                  | MIN  | MAX  | UNIT |
|------------------------|------------------------------------------------------------------|------|------|------|
| Supply voltage         | IN_BIAS, IN_LDO1, IN_LS2, IN_DCDC1, IN_DCDC2, IN_DCDC3, IN_DCDC4 | −0.3 | 7    | V    |
|                        | IN_LS1, CC                                                       | −0.3 | 3.6  |      |
|                        | IN_LS3                                                           | −0.3 | 11.2 |      |
|                        | IN_BU                                                            | −0.3 | 5.8  |      |
| Input voltage          | DC34_SEL                                                         | −0.3 | 3.6  | V    |
|                        | All pins unless specified separately                             | −0.3 | 7    |      |
| Output voltage         | DC34_SEL                                                         | −0.3 | 3.6  | V    |
|                        | All pins unless specified separately                             | −0.3 | 7    |      |
| Source or sink current | GPO2                                                             |      | 6    | mA   |
|                        | PGOOD_BU, IN_nCC                                                 |      | 1    |      |
| Sink current           | PGOOD, nWAKEUP, nINT, nPFO, SDA, GPIO1, GPIO3                    |      | 6    | mA   |
| T <sub>A</sub>         | Operating ambient temperature                                    | −40  | 105  | °C   |
| T <sub>J</sub>         | Junction temperature                                             | −40  | 125  | °C   |
| T <sub>stg</sub>       | Storage temperature                                              | −65  | 150  | °C   |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### 6.2 ESD Ratings

|                    |                         |                                                                                | VALUE | UNIT |
|--------------------|-------------------------|--------------------------------------------------------------------------------|-------|------|
| V <sub>(ESD)</sub> | Electrostatic discharge | Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>              | ±2000 | V    |
|                    |                         | Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup> | ±500  |      |

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.  
 (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

## 6.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted).

|                                                  | MIN               | NOM | MAX   | UNIT |
|--------------------------------------------------|-------------------|-----|-------|------|
| Supply voltage, IN_BIAS                          | 2.7               |     | 5.5   | V    |
| Input voltage for DCDC1, DCDC2, DCDC3, and DCDC4 | 2.7               |     | 5.5   | V    |
| Supply voltage, IN_BU                            | 2.2               |     | 5.5   | V    |
| Supply voltage, CC                               | 2.2               |     | 3.3   | V    |
| Input voltage for LDO1                           | 1.8               |     | 5.5   | V    |
| Input voltage for LS1                            | 1.2               |     | 3.6   | V    |
| Input voltage for LS2                            | 3                 |     | 5.5   | V    |
| Input voltage for LS3                            | 1.8               |     | 10    | V    |
| Output voltage for DCDC1                         | 0.85              |     | 1.675 | V    |
| Output voltage for DCDC2                         | 0.85              |     | 1.675 | V    |
| Output voltage for DCDC3                         | 0.9               |     | 3.4   | V    |
| Output voltage for DCDC4                         | 1.175             |     | 3.4   | V    |
| Output voltage for DCDC5                         |                   | 1   |       | V    |
| Output voltage for DCDC6                         |                   | 1.8 |       | V    |
| Output voltage for LDO1                          | 0.9               |     | 3.4   | V    |
| Output current for DCDC1, DCDC2, and DCDC3       | 0                 |     | 1.8   | A    |
| Output current for DCDC4                         | VIN_DCDC4 = 2.8 V |     | 1     | A    |
|                                                  | VIN_DCDC4 = 3.6 V |     | 1.3   |      |
|                                                  | VIN_DCDC4 = 5 V   |     | 1.6   |      |
| Output current for DCDC5 and DCDC6               | 0                 |     | 25    | mA   |
| Output current for LDO1                          | 0                 |     | 400   | mA   |
| Output current for LS1                           | 0                 |     | 300   | mA   |
| Output current for LS2                           | 0                 |     | 920   | mA   |
| Output current for LS3                           | VIN_LS3 > 2.3 V   | 0   | 900   | mA   |
|                                                  | VIN_LS3 ≤ 2.3 V   | 0   | 475   |      |

## 6.4 Thermal Information

| THERMAL METRIC <sup>(1)</sup> |                                                                       | TPS6521835 | UNIT |
|-------------------------------|-----------------------------------------------------------------------|------------|------|
|                               |                                                                       | RSL (VQFN) |      |
|                               |                                                                       | 48 PINS    |      |
| R <sub>θJC(top)</sub>         | Junction-to-case (top)                                                | 17.2       | °C/W |
| R <sub>θJB</sub>              | Junction-to-board                                                     | 5.8        | °C/W |
| R <sub>θJA</sub>              | Thermal resistance, junction-to-ambient. JEDEC 4-layer, high-K board. | 30.6       | °C/W |
| Ψ <sub>JT</sub>               | Junction-to-package top                                               | 0.2        | °C/W |
| Ψ <sub>JB</sub>               | Junction-to-board                                                     | 5.6        | °C/W |
| R <sub>θJC(bot)</sub>         | Junction-to-case (bottom)                                             | 1.5        | °C/W |

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 6.5 Electrical Characteristics

Over operating free-air temperature range (unless otherwise noted).

| PARAMETER                  |                                                                                 | TEST CONDITIONS                                                                                                                                                                                                                                                 |                 | MIN   | TYP  | MAX   | UNIT |
|----------------------------|---------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------|-------|------|-------|------|
| INPUT VOLTAGE AND CURRENTS |                                                                                 |                                                                                                                                                                                                                                                                 |                 |       |      |       |      |
| V <sub>IN_BIAS</sub>       | Input supply voltage range                                                      | Normal operation                                                                                                                                                                                                                                                |                 | 2.7   |      | 5.5   | V    |
|                            |                                                                                 | EEPROM programming                                                                                                                                                                                                                                              |                 | 4.5   |      | 5.5   |      |
| V <sub>UVLO</sub>          | Undervoltage lockout                                                            | Supply falling; measured in respect to V <sub>IN_BIAS</sub>                                                                                                                                                                                                     | UVLO[1:0] = 00b | 2.7   | 2.75 | 2.8   | V    |
|                            |                                                                                 |                                                                                                                                                                                                                                                                 | UVLO[1:0] = 01b | 2.85  | 2.95 | 3.05  | V    |
|                            |                                                                                 |                                                                                                                                                                                                                                                                 | UVLO[1:0] = 10b | 3.15  | 3.25 | 3.35  | V    |
|                            |                                                                                 |                                                                                                                                                                                                                                                                 | UVLO[1:0] = 11b | 3.25  | 3.35 | 3.45  | V    |
| V <sub>UVLO</sub>          | Hysteresis                                                                      | Supply rising; V <sub>IN_BIAS</sub> slew rate < 30 V/s                                                                                                                                                                                                          | UVLOHYS = 0b    |       | 200  |       | mV   |
|                            |                                                                                 |                                                                                                                                                                                                                                                                 | UVLOHYS = 1b    |       | 400  |       | mV   |
|                            |                                                                                 | Supply rising; V <sub>IN_BIAS</sub> slew rate > 30 V/s                                                                                                                                                                                                          | UVLOHYS = 0b    |       | 0    |       | mV   |
|                            |                                                                                 |                                                                                                                                                                                                                                                                 | UVLOHYS = 1b    |       | 0    |       | mV   |
| Deglitch time              |                                                                                 |                                                                                                                                                                                                                                                                 |                 |       | 5    |       | ms   |
| I <sub>OFF</sub>           | OFF state current, total current into IN_BIAS, IN_DCDCx, IN_LDO1, IN_LSx, IN_BU | V <sub>IN</sub> = 3.6 V; All rails disabled. T <sub>J</sub> = 0°C to 85°C                                                                                                                                                                                       |                 |       | 5    |       | μA   |
| I <sub>SUSPEND</sub>       | SUSPEND current, total current into IN_BIAS, IN_DCDCx, IN_LDO1, IN_LSx, IN_BU   | V <sub>IN</sub> = 3.6 V; DCDC3 enabled, low-power mode, no load. All other rails disabled. T <sub>J</sub> = 0°C to 105°C                                                                                                                                        |                 |       | 220  |       | μA   |
| SYS_BU                     |                                                                                 |                                                                                                                                                                                                                                                                 |                 |       |      |       |      |
| V <sub>SYS_BU</sub>        | SYS_BU voltage range                                                            | Powered from V <sub>IN_BU</sub> or V <sub>CC</sub>                                                                                                                                                                                                              |                 | 2.2   |      | 5.5   | V    |
| C <sub>SYS_BU</sub>        | Recommended SYS_BU capacitor                                                    | Ceramic, X5R or X7R, see <a href="#">Table 8-3</a> .                                                                                                                                                                                                            |                 |       | 1    |       | μF   |
|                            | Tolerance                                                                       | Ceramic, X5R or X7R, rated voltage ≥ 6.3 V                                                                                                                                                                                                                      |                 | –20%  |      | 20%   |      |
| INT_LDO                    |                                                                                 |                                                                                                                                                                                                                                                                 |                 |       |      |       |      |
| V <sub>INT_LDO</sub>       | Output voltage                                                                  |                                                                                                                                                                                                                                                                 |                 |       | 2.5  |       | V    |
|                            | DC accuracy                                                                     | I <sub>OUT</sub> < 10 mA                                                                                                                                                                                                                                        |                 | –2%   |      | 2%    |      |
| I <sub>OUT</sub>           | Output current range                                                            | Maximum allowable external load                                                                                                                                                                                                                                 |                 | 0     |      | 10    | mA   |
| I <sub>LIMIT</sub>         | Short circuit current limit                                                     | Output shorted to GND                                                                                                                                                                                                                                           |                 |       | 23   |       | mA   |
| t <sub>HOLD</sub>          | Hold-up time                                                                    | Measured from V <sub>INT_LDO</sub> = 2.5 V to V <sub>INT_LDO</sub> = 1.8 V<br>All rails enabled before power off, V <sub>IN_BIAS</sub> = 2.8 V to 0 V in < 1 μs<br>No external load on INT_LDO<br>C <sub>INT_LDO</sub> = 22 μF, see <a href="#">Table 8-3</a> . |                 | 150   |      |       | ms   |
| C <sub>OUT</sub>           | Nominal output capacitor value                                                  | Ceramic, X5R or X7R, see <a href="#">Table 8-3</a> .                                                                                                                                                                                                            |                 | 0.1   | 1    | 22    | μF   |
|                            | Tolerance                                                                       | Ceramic, X5R or X7R, rated voltage ≥ 6.3 V                                                                                                                                                                                                                      |                 | –20%  |      | 20%   |      |
| DCDC1 (1.1-V BUCK)         |                                                                                 |                                                                                                                                                                                                                                                                 |                 |       |      |       |      |
| V <sub>IN_DCDC1</sub>      | Input voltage range                                                             | V <sub>IN_BIAS</sub> > V <sub>UVLO</sub>                                                                                                                                                                                                                        |                 | 2.7   |      | 5.5   | V    |
| V <sub>DCDC1</sub>         | Output voltage range                                                            | Adjustable through I <sup>2</sup> C                                                                                                                                                                                                                             |                 | 0.85  |      | 1.675 | V    |
|                            | DC accuracy                                                                     | 2.7 V ≤ V <sub>IN</sub> ≤ 5.5 V; 0 A ≤ I <sub>OUT</sub> ≤ 1.8 A                                                                                                                                                                                                 |                 | –2%   |      | 2%    |      |
|                            | Dynamic accuracy                                                                | In respect to nominal output voltage<br>I <sub>OUT</sub> = 50 mA to 450 mA in < 1 μs<br>C <sub>OUT</sub> ≥ 10 μF, over full input voltage range.                                                                                                                |                 | –2.5% |      | 2.5%  |      |
| I <sub>OUT</sub>           | Continuous output current                                                       | V <sub>IN_DCDC1</sub> > 2.7 V                                                                                                                                                                                                                                   |                 |       |      | 1.8   | A    |
| I <sub>Q</sub>             | Quiescent current                                                               | Total current from I <sub>N_DCDC1</sub> pin; Device not switching, no load                                                                                                                                                                                      |                 |       | 25   | 50    | μA   |
| R <sub>DS(ON)</sub>        | High-side FET on resistance                                                     | V <sub>IN_DCDC1</sub> = 3.6 V                                                                                                                                                                                                                                   |                 |       | 230  | 355   | mΩ   |
|                            | Low-side FET on resistance                                                      | V <sub>IN_DCDC1</sub> = 3.6 V                                                                                                                                                                                                                                   |                 |       | 90   | 145   |      |



## 6.5 Electrical Characteristics (continued)

Over operating free-air temperature range (unless otherwise noted).

| PARAMETER                 |                             | TEST CONDITIONS                                                                                                        | MIN   | TYP  | MAX                | UNIT |
|---------------------------|-----------------------------|------------------------------------------------------------------------------------------------------------------------|-------|------|--------------------|------|
| I <sub>LIMIT</sub>        | High-side current limit     | V <sub>IN_DCDC1</sub> = 3.6 V                                                                                          |       | 2.8  |                    | A    |
|                           | Low-side current limit      | V <sub>IN_DCDC1</sub> = 3.6 V                                                                                          |       | 3.1  |                    |      |
| V <sub>PG</sub>           | Power-good threshold        | V <sub>OUT</sub> falling                                                                                               | 88.5% | 90%  | 91.5%              |      |
|                           | Hysteresis                  | V <sub>OUT</sub> rising                                                                                                | 3.8%  | 4.1% | 4.4%               |      |
|                           | Deglitch                    | V <sub>OUT</sub> falling                                                                                               |       | 1    |                    | ms   |
|                           |                             | V <sub>OUT</sub> rising                                                                                                |       | 10   |                    | μs   |
|                           | Time-out                    |                                                                                                                        |       | 5    |                    | ms   |
| I <sub>INRUSH</sub>       | Inrush current              | V <sub>IN_DCDC1</sub> = 3.6 V; C <sub>OUT</sub> = 10 μF to 100 μF                                                      |       |      | 500                | mA   |
| R <sub>DIS</sub>          | Discharge resistor          |                                                                                                                        | 150   | 250  | 350                | Ω    |
| L                         | Nominal inductor value      | See <a href="#">Table 8-2</a> .                                                                                        | 1     | 1.5  | 2.2                | μH   |
|                           | Tolerance                   |                                                                                                                        | –30%  |      | 30%                |      |
| C <sub>OUT</sub>          | Output capacitance value    | Ceramic, X5R or X7R, see <a href="#">Table 8-3</a> .                                                                   | 10    | 22   | 100 <sup>(8)</sup> | μF   |
| <b>DCDC2 (1.1-V BUCK)</b> |                             |                                                                                                                        |       |      |                    |      |
| V <sub>IN_DCDC2</sub>     | Input voltage range         | V <sub>IN_BIAS</sub> > V <sub>UVLO</sub>                                                                               | 2.7   |      | 5.5                | V    |
| V <sub>DCDC2</sub>        | Output voltage range        | Adjustable through I <sup>2</sup> C                                                                                    | 0.85  |      | 1.675              | V    |
|                           | DC accuracy                 | 2.7 V ≤ V <sub>IN</sub> ≤ 5.5 V; 0 A ≤ I <sub>OUT</sub> ≤ 1.8 A                                                        | –2%   |      | 2%                 |      |
| I <sub>OUT</sub>          | Continuous output current   | V <sub>IN_DCDC2</sub> > 2.7 V                                                                                          |       |      | 1.8                | A    |
| I <sub>Q</sub>            | Quiescent current           | Total current from I <sub>N_DCDC2</sub> pin; device not switching, no load                                             |       | 25   | 50                 | μA   |
| R <sub>DS(ON)</sub>       | High-side FET on resistance | V <sub>IN_DCDC2</sub> = 3.6 V                                                                                          |       | 230  | 355                | mΩ   |
|                           | Low-side FET on resistance  | V <sub>IN_DCDC2</sub> = 3.6 V                                                                                          |       | 90   | 145                |      |
| I <sub>LIMIT</sub>        | High-side current limit     | V <sub>IN_DCDC2</sub> = 3.6 V                                                                                          |       | 2.8  |                    | A    |
|                           | Low-side current limit      | V <sub>IN_DCDC2</sub> = 3.6 V                                                                                          |       | 3.1  |                    |      |
| V <sub>PG</sub>           | Power-good threshold        | V <sub>OUT</sub> falling                                                                                               | 88.5% | 90%  | 91.5%              |      |
|                           | Hysteresis                  | V <sub>OUT</sub> rising                                                                                                | 3.8%  | 4.1% | 4.4%               |      |
|                           | Deglitch                    | V <sub>OUT</sub> falling                                                                                               |       | 1    |                    | ms   |
|                           |                             | V <sub>OUT</sub> rising                                                                                                |       | 10   |                    | μs   |
|                           | Time-out                    |                                                                                                                        |       | 5    |                    | ms   |
| I <sub>INRUSH</sub>       | Inrush current              | V <sub>IN_DCDC2</sub> = 3.6 V; C <sub>OUT</sub> = 10 μF to 100 μF                                                      |       |      | 500                | mA   |
| R <sub>DIS</sub>          | Discharge resistor          |                                                                                                                        | 150   | 250  | 350                | Ω    |
| L                         | Nominal inductor value      | See <a href="#">Table 8-2</a> .                                                                                        | 1     | 1.5  | 2.2                | μH   |
|                           | Tolerance                   |                                                                                                                        | –30%  |      | 30%                |      |
| C <sub>OUT</sub>          | Output capacitance value    | Ceramic, X5R or X7R, see <a href="#">Table 8-3</a> .                                                                   | 10    | 22   | 100 <sup>(8)</sup> | μF   |
| <b>DCDC3 (1.2-V BUCK)</b> |                             |                                                                                                                        |       |      |                    |      |
| V <sub>IN_DCDC3</sub>     | Input voltage range         | V <sub>IN_BIAS</sub> > V <sub>UVLO</sub>                                                                               |       |      | 5.5                | V    |
| V <sub>DCDC3</sub>        | Output voltage range        | Adjustable through I <sup>2</sup> C                                                                                    | 0.9   |      | 3.4                | V    |
|                           | DC accuracy                 | 2.7 V ≤ V <sub>IN</sub> ≤ 5.5 V; 0 A ≤ I <sub>OUT</sub> ≤ 1.8 A, V <sub>IN_DCDC3</sub> ≥ (V <sub>DCDC3</sub> + 700 mV) | –2%   |      | 2%                 |      |
| I <sub>OUT</sub>          | Continuous output current   | V <sub>IN_DCDC3</sub> > 2.7 3.6 V                                                                                      |       |      | 1.8                | A    |
| I <sub>Q</sub>            | Quiescent current           | Total current from I <sub>N_DCDC3</sub> pin; Device not switching, no load                                             |       | 25   | 50                 | μA   |
| R <sub>DS(ON)</sub>       | High-side FET on resistance | V <sub>IN_DCDC3</sub> = 3.6 V                                                                                          |       | 230  | 345                | mΩ   |
|                           | Low-side FET on resistance  | V <sub>IN_DCDC3</sub> = 3.6 V                                                                                          |       | 100  | 150                |      |
| I <sub>LIMIT</sub>        | High-side current limit     | V <sub>IN_DCDC3</sub> = 3.6 V                                                                                          |       | 2.8  |                    | A    |
|                           | Low-side current limit      | V <sub>IN_DCDC3</sub> = 3.6 V                                                                                          |       | 3    |                    |      |

## 6.5 Electrical Characteristics (continued)

Over operating free-air temperature range (unless otherwise noted).

| PARAMETER                                 |                                | TEST CONDITIONS                                                                                                                                     |                 | MIN   | TYP  | MAX   | UNIT |                  |
|-------------------------------------------|--------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------|-----------------|-------|------|-------|------|------------------|
| V <sub>PG</sub>                           | Power-good threshold           | V <sub>OUT</sub> falling                                                                                                                            |                 | 88.5% | 90%  | 91.5% |      |                  |
|                                           | Hysteresis                     | V <sub>OUT</sub> rising                                                                                                                             |                 | 3.8%  | 4.1% | 4.4%  |      |                  |
|                                           | Deglitch                       | V <sub>OUT</sub> falling                                                                                                                            |                 | 1     |      |       | ms   |                  |
|                                           |                                | V <sub>OUT</sub> rising                                                                                                                             |                 | 10    |      |       | μs   |                  |
|                                           | Time-out                       |                                                                                                                                                     |                 | 5     |      |       | ms   |                  |
| I <sub>INRUSH</sub>                       | Inrush current                 | V <sub>IN_DCDC3</sub> = 3.6 V; C <sub>OUT</sub> = 10 μF to 100 μF                                                                                   |                 | 500   |      |       | mA   |                  |
| R <sub>DIS</sub>                          | Discharge resistor             |                                                                                                                                                     |                 | 150   | 250  | 350   | Ω    |                  |
| L                                         | Nominal inductor value         | See <a href="#">Table 8-2</a> .                                                                                                                     |                 | 1.0   | 1.5  | 2.2   | μH   |                  |
|                                           | Tolerance                      |                                                                                                                                                     |                 | –30%  |      |       | 30%  |                  |
| C <sub>OUT</sub>                          | Output capacitance value       | Ceramic, X5R or X7R, see <a href="#">Table 8-3</a> .                                                                                                |                 | 10    | 22   | 100   | μF   |                  |
| DCDC4 (3.3-V BUCK-BOOST) / ANALOG AND I/O |                                |                                                                                                                                                     |                 |       |      |       |      |                  |
| V <sub>IN_DCDC4</sub>                     | Input voltage soft-start range | V <sub>IN_BIAS</sub> > V <sub>UVLO</sub> , –40°C to +55°C                                                                                           |                 | 3.4   |      |       | V    |                  |
|                                           |                                | V <sub>IN_BIAS</sub> > V <sub>UVLO</sub> , 56°C to 105°C                                                                                            |                 | 3.8   |      |       |      |                  |
|                                           | Input voltage operating range  | V <sub>IN_BIAS</sub> > V <sub>UVLO</sub> , –40°C to +105°C                                                                                          |                 | 2.7   |      |       | 5.5  | V                |
| V <sub>DCDC4</sub>                        | Output voltage range           | Adjustable through I <sup>2</sup> C                                                                                                                 |                 | 1.175 |      |       | 3.4  | V                |
|                                           | DC accuracy                    | 2.7 V ≤ V <sub>IN</sub> ≤ 5.5 V;<br>0 A ≤ I <sub>OUT</sub> ≤ 1 A                                                                                    |                 | –2%   |      |       | 2%   |                  |
| Output voltage ripple                     |                                | PFM mode enabled;<br>4.2 V ≤ V <sub>IN</sub> ≤ 5.5 V;<br>0 A ≤ I <sub>OUT</sub> ≤ 1 A 1.6 A<br>C <sub>OUT</sub> = 80 μF<br>V <sub>OUT</sub> = 3.3 V |                 |       |      |       | 200  | mV <sub>pp</sub> |
| Minimum duty cycle in step-down mode      |                                |                                                                                                                                                     |                 |       |      |       | 18%  |                  |
| I <sub>OUT</sub>                          | Continuous output current      | V <sub>IN_DCDC4</sub> = 2.8 V, V <sub>OUT</sub> = 3.3 V                                                                                             |                 |       |      |       | 1    | A                |
|                                           |                                | V <sub>IN_DCDC4</sub> = 3.6 V, V <sub>OUT</sub> = 3.3 V                                                                                             |                 |       |      |       | 1.3  |                  |
|                                           |                                | V <sub>IN_DCDC4</sub> = 5 V, V <sub>OUT</sub> = 3.3 V                                                                                               |                 |       |      |       | 1.6  |                  |
| I <sub>Q</sub>                            | Quiescent current              | Total current from IN_DCDC4 pin; Device not switching, no load.                                                                                     |                 | 25    |      |       | 50   | μA               |
| f <sub>SW</sub>                           | Switching frequency            |                                                                                                                                                     |                 | 2400  |      |       |      | kHz              |
| R <sub>DS(ON)</sub>                       | High-side FET on resistance    | V <sub>IN_DCDC3</sub> = 3.6 V                                                                                                                       | IN_DCDC4 to L4A | 166   |      |       | mΩ   |                  |
|                                           |                                |                                                                                                                                                     | L4B to DCDC4    | 149   |      |       |      |                  |
|                                           | Low-side FET on resistance     | V <sub>IN_DCDC3</sub> = 3.6 V                                                                                                                       | L4A to GND      | 142   |      |       |      | 190              |
|                                           |                                |                                                                                                                                                     | L4B to GND      | 144   |      |       |      | 190              |
| I <sub>LIMIT</sub>                        | Average switch current limit   | V <sub>IN_DCDC4</sub> = 3.6 V                                                                                                                       |                 | 3000  |      |       |      | mA               |
| V <sub>PG</sub>                           | Power-good threshold           | V <sub>OUT</sub> falling                                                                                                                            |                 | 88.5% | 90%  | 91.5% |      |                  |
|                                           | Hysteresis                     | V <sub>OUT</sub> rising                                                                                                                             |                 | 3.8%  | 4.1% | 4.4%  |      |                  |
|                                           | Deglitch                       | V <sub>OUT</sub> falling                                                                                                                            |                 | 1     |      |       | ms   |                  |
|                                           |                                | V <sub>OUT</sub> rising                                                                                                                             |                 | 10    |      |       | μs   |                  |
|                                           | Time-out                       |                                                                                                                                                     |                 | 5     |      |       | ms   |                  |
| I <sub>INRUSH</sub>                       | Inrush current                 | V <sub>IN_DCDC4</sub> = 3.6 V; C <sub>OUT</sub> = 10 μF to 100 μF                                                                                   |                 | 500   |      |       | mA   |                  |
| R <sub>DIS</sub>                          | Discharge resistor             |                                                                                                                                                     |                 | 150   | 250  | 350   | Ω    |                  |
| L                                         | Nominal inductor value         | See <a href="#">Table 8-2</a> .                                                                                                                     |                 | 1.2   | 1.5  | 2.2   | μH   |                  |
|                                           | Tolerance                      |                                                                                                                                                     |                 | –30%  |      |       | 30%  |                  |
| C <sub>OUT</sub>                          | Output capacitance value       | Ceramic, X5R or X7R, see <a href="#">Table 8-3</a> .                                                                                                |                 | 40    | 80   | 100   | μF   |                  |
| DCDC5 and DCDC6 (POWER PATH)              |                                |                                                                                                                                                     |                 |       |      |       |      |                  |

## 6.5 Electrical Characteristics (continued)

Over operating free-air temperature range (unless otherwise noted).

| PARAMETER                                  |                                                    | TEST CONDITIONS                                                                                                                                                     | MIN   | TYP  | MAX  | UNIT |
|--------------------------------------------|----------------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------|------|------|------|
| V <sub>CC</sub>                            | DCDC5 and DCDC6 input voltage range.               | V <sub>IN_BU</sub> = 0 V                                                                                                                                            | 2.2   |      | 3.3  | V    |
| V <sub>IN_BU</sub>                         | DCDC5 and DCDC6 input voltage range <sup>(1)</sup> |                                                                                                                                                                     | 2.2   |      | 5.5  | V    |
| t <sub>RISE</sub>                          | V <sub>CC</sub> , V <sub>IN_BU</sub> rise time     | V <sub>CC</sub> = 0 V to 3.3 V, V <sub>IN_BU</sub> = 0 V to 5.5 V                                                                                                   | 30    |      |      | μs   |
| R <sub>DS(ON)</sub>                        | Power path switch impedance                        | CC to SYS_BU<br>V <sub>CC</sub> = 2.4 V, V <sub>IN_BU</sub> = 0 V                                                                                                   |       | 14.5 |      | Ω    |
|                                            | Power path switch impedance                        | IN_BU to SYS_BU<br>V <sub>IN_BU</sub> = 3.6 V                                                                                                                       |       | 10.5 |      |      |
| I <sub>LEAK</sub>                          | Forward leakage current                            | Into CC pin;<br>V <sub>CC</sub> = 3.3 V, V <sub>IN_BU</sub> = 0 V;<br>OFF state; FSEAL = 0b;<br>over full temperature range                                         |       | 50   | 300  | nA   |
|                                            | Reverse leakage current                            | Out of CC pin;<br>V <sub>CC</sub> = 1.5 V; V <sub>IN_BU</sub> = 5.5 V;<br>over full temperature range                                                               |       |      | 500  |      |
| R <sub>CC</sub>                            | Acceptable CC source impedance                     | I <sub>OUT, DCDC5</sub> < 10 μA;<br>I <sub>OUT, DCDC6</sub> < 10 μA                                                                                                 |       |      | 1000 | Ω    |
| I <sub>Q</sub>                             | Quiescent current                                  | Average current into CC pin; RECOVERY or POWER_OFF state; V <sub>IN_BU</sub> = 0 V; V <sub>CC</sub> = 2.4 V; DCDC5 and DCDC6 enabled, no load T <sub>J</sub> = 25°C |       | 350  |      | nA   |
| <b>DCDC5 (1-V BATTERY BACKUP SUPPLY)</b>   |                                                    |                                                                                                                                                                     |       |      |      |      |
| V <sub>DCDC5</sub>                         | Output voltage                                     |                                                                                                                                                                     |       | 1    |      | V    |
|                                            | DC accuracy                                        | 2.7 V ≤ V <sub>IN_BU</sub> ≤ 5.5 V; 1.5 μA ≤ I <sub>OUT</sub> ≤ 25 mA –40°C ≤ T <sub>A</sub> < 0°C                                                                  | –2.5% |      | 2.5% |      |
|                                            |                                                    | 2.7 V ≤ V <sub>IN_BU</sub> ≤ 5.5 V 1.5 μA ≤ I <sub>OUT</sub> ≤ 25 mA 0°C ≤ T <sub>A</sub> < 105°C                                                                   | –2%   |      | 2%   |      |
|                                            |                                                    | 2.2 V ≤ V <sub>CC</sub> ≤ 3.3 V; V <sub>IN_BU</sub> = 0; 1.5 μA ≤ I <sub>OUT</sub> ≤ 100 μA                                                                         | –2.5% |      | 2.5% |      |
| I <sub>OUT</sub>                           | Continuous output current                          | 2.2 V ≤ V <sub>CC</sub> ≤ 3.3 V<br>V <sub>IN_BU</sub> = 0 V                                                                                                         |       | 10   | 100  | μA   |
|                                            |                                                    | 2.7 V ≤ V <sub>IN_BU</sub> ≤ 5.5 V                                                                                                                                  |       |      | 25   | mA   |
| I <sub>LIMIT</sub>                         | High-side current limit                            | V <sub>IN_BU</sub> = 2.8 V                                                                                                                                          |       | 50   |      | mA   |
| V <sub>PG</sub>                            | Power-good threshold                               | V <sub>OUT</sub> falling                                                                                                                                            | 79%   | 85%  | 91%  |      |
|                                            | Hysteresis                                         | V <sub>OUT</sub> rising                                                                                                                                             |       | 6%   |      |      |
| L                                          | Nominal inductor value                             | Chip inductor, see <a href="#">Table 8-3</a> .                                                                                                                      | 4.7   | 10   | 22   | μH   |
|                                            | Tolerance                                          |                                                                                                                                                                     | –30%  |      | 30%  |      |
| C <sub>OUT</sub>                           | Output capacitance value                           | Ceramic, X5R or X7R, see <a href="#">Table 8-3</a> .                                                                                                                | 20    |      | 47   | μF   |
|                                            | Tolerance                                          |                                                                                                                                                                     | –20%  |      | 20%  |      |
| <b>DCDC6 (1.8-V BATTERY BACKUP SUPPLY)</b> |                                                    |                                                                                                                                                                     |       |      |      |      |
| V <sub>DCDC6</sub>                         | Output voltage                                     |                                                                                                                                                                     |       | 1.8  |      | V    |
|                                            | DC accuracy                                        | 2.7 V ≤ V <sub>IN_BU</sub> ≤ 5.5 V;<br>1 μA ≤ I <sub>OUT</sub> ≤ 25 mA                                                                                              | –2%   |      | 2%   |      |
|                                            |                                                    | 2.2 V ≤ V <sub>CC</sub> ≤ 3.3 V, V <sub>IN_BU</sub> = 0;<br>1 μA ≤ I <sub>OUT</sub> ≤ 100 μA                                                                        | –2%   |      | 2%   |      |
| I <sub>OUT</sub>                           | Continuous output current                          | 2.2 V ≤ V <sub>CC</sub> ≤ 3.3 V<br>V <sub>IN_BU</sub> = 0 V                                                                                                         |       | 10   | 100  | μA   |
|                                            |                                                    | 2.7 V ≤ V <sub>IN_BU</sub> ≤ 5.5 V                                                                                                                                  |       |      | 25   | mA   |

## 6.5 Electrical Characteristics (continued)

Over operating free-air temperature range (unless otherwise noted).

| PARAMETER            |                                         | TEST CONDITIONS                                                                                                  |  | MIN   | TYP  | MAX   | UNIT |
|----------------------|-----------------------------------------|------------------------------------------------------------------------------------------------------------------|--|-------|------|-------|------|
| R <sub>DS(ON)</sub>  | High-side FET on resistance             | V <sub>IN_BU</sub> = 3 V                                                                                         |  | 2.5   |      | 3.5   | Ω    |
|                      | Low-side FET on resistance              | V <sub>IN_BU</sub> = 3 V                                                                                         |  | 2     |      | 3     |      |
| I <sub>LIMIT</sub>   | High-side current limit                 | V <sub>IN_BU</sub> = 3 V                                                                                         |  | 50    |      |       | mA   |
| V <sub>PG</sub>      | Hysteresis                              | V <sub>OUT</sub> rising                                                                                          |  | 3%    |      |       |      |
| L                    | Nominal inductor value                  | Chip inductor, see <a href="#">Table 8-3</a>                                                                     |  | 4.7   | 10   | 22    | μH   |
|                      | Tolerance                               |                                                                                                                  |  | –30%  |      | 30%   |      |
| C <sub>OUT</sub>     | Output capacitance value                | Ceramic, X5R or X7R, see <a href="#">Table 8-3</a>                                                               |  | 20    |      | 47    | μF   |
|                      | Tolerance                               |                                                                                                                  |  | –20%  |      | 20%   |      |
| LDO1 (1.8-V LDO)     |                                         |                                                                                                                  |  |       |      |       |      |
| V <sub>IN_LDO1</sub> | Input voltage range                     | V <sub>IN_BIAS</sub> > V <sub>UVLO</sub>                                                                         |  | 1.8   |      | 5.5   | V    |
| I <sub>Q</sub>       | Quiescent current                       | No load                                                                                                          |  | 35    |      |       | μA   |
| V <sub>OUT</sub>     | Output voltage range                    | Adjustable through I <sup>2</sup> C                                                                              |  | 0.9   |      | 3.4   | V    |
|                      | DC accuracy                             | V <sub>OUT</sub> + 0.2 V ≤ V <sub>IN</sub> ≤ 5.5 V; 0 A ≤ I <sub>OUT</sub> ≤ 200 mA                              |  | –2%   |      | 2%    |      |
| I <sub>OUT</sub>     | Output current range                    | V <sub>IN_LDO1</sub> – V <sub>DO</sub> = V <sub>OUT</sub>                                                        |  | 0     |      | 200   | mA   |
|                      |                                         | V <sub>IN_LDO1</sub> > 2.7 V, V <sub>OUT</sub> = 1.8 V                                                           |  | 0     |      | 400   |      |
| I <sub>LIMIT</sub>   | Short circuit current limit             | Output shorted to GND                                                                                            |  | 445   | 550  |       | mA   |
| V <sub>DO</sub>      | Dropout voltage                         | I <sub>OUT</sub> = 100 mA, V <sub>IN</sub> = 3.6 V                                                               |  |       |      | 200   | mV   |
| V <sub>PG</sub>      | Power-good threshold                    | V <sub>OUT</sub> falling                                                                                         |  | 88.5% | 90%  | 91.5% |      |
|                      | Hysteresis                              | V <sub>OUT</sub> rising                                                                                          |  | 3.8%  | 4.1% | 4.4%  |      |
|                      | Deglitch                                | V <sub>OUT</sub> falling                                                                                         |  | 1     |      |       | ms   |
|                      |                                         | V <sub>OUT</sub> rising                                                                                          |  | 10    |      |       | μs   |
|                      | Time-out                                |                                                                                                                  |  | 5     |      |       | ms   |
| I <sub>INRUSH</sub>  | Inrush current                          | V <sub>IN_DCDC2</sub> = 3.6 V; C <sub>OUT</sub> = 10 μF to 100 μF                                                |  |       |      | 500   | mA   |
| R <sub>DIS</sub>     | Discharge resistor                      |                                                                                                                  |  | 150   | 250  | 350   | Ω    |
| C <sub>OUT</sub>     | Nominal output Output capacitance value | Ceramic, X5R or X7R                                                                                              |  | 10    |      | 100   | μF   |
| LOAD SWITCH 1 (LS1)  |                                         |                                                                                                                  |  |       |      |       |      |
| V <sub>IN_LS1</sub>  | Input voltage range                     | V <sub>IN_BIAS</sub> > V <sub>UVLO</sub>                                                                         |  | 1.2   |      | 3.6   | V    |
| R <sub>DS(ON)</sub>  | Static on resistance                    | V <sub>IN_LS1</sub> = 3.3 V, I <sub>OUT</sub> = 300 mA, over full temperature range                              |  |       |      | 110   | mΩ   |
|                      |                                         | V <sub>IN_LS1</sub> = 1.8 V, I <sub>OUT</sub> = 300 mA, DDR2, LPDDR, MDDR at 266 MHz over full temperature range |  |       |      | 110   |      |
|                      |                                         | V <sub>IN_LS1</sub> = 1.5 V, I <sub>OUT</sub> = 300 mA, DDR3 at 333 MHz over full temperature range              |  |       |      | 110   |      |
|                      |                                         | V <sub>IN_LS1</sub> = 1.35 V, I <sub>OUT</sub> = 300 mA, DDR3L at 333 MHz over full temperature range            |  |       |      | 110   |      |
|                      |                                         | V <sub>IN_LS1</sub> = 1.2 V, I <sub>OUT</sub> = 200 mA, LPDDR2 at 333 MHz over full temperature range            |  |       |      | 150   |      |
| I <sub>LIMIT</sub>   | Short circuit current limit             | Output shorted to GND                                                                                            |  | 350   |      |       | mA   |
| T <sub>OTS</sub>     | Overtemperature shutdown <sup>(3)</sup> |                                                                                                                  |  | 125   | 132  | 139   | °C   |
|                      | Hysteresis                              |                                                                                                                  |  | 10    |      |       |      |
| C <sub>OUT</sub>     | Nominal output capacitance value        | Ceramic, X5R or X7R, see <a href="#">Table 8-3</a> .                                                             |  | 10    |      | 100   | μF   |
| LOAD SWITCH 2 (LS2)  |                                         |                                                                                                                  |  |       |      |       |      |
| V <sub>IN_LS2</sub>  | Input voltage range                     | V <sub>IN_BIAS</sub> > V <sub>UVLO</sub>                                                                         |  | 4     |      | 5.5   | V    |

## 6.5 Electrical Characteristics (continued)

Over operating free-air temperature range (unless otherwise noted).

| PARAMETER                     |                                                      | TEST CONDITIONS                                                                     | MIN                | TYP  | MAX  | UNIT |
|-------------------------------|------------------------------------------------------|-------------------------------------------------------------------------------------|--------------------|------|------|------|
| V <sub>UVLO</sub>             | Undervoltage lockout                                 | Measured at IN_LS2. Supply falling <sup>(4)</sup>                                   | 2.48               | 2.6  | 2.7  | V    |
|                               | Hysteresis                                           | Input voltage rising                                                                |                    | 170  |      | mV   |
| R <sub>DS(ON)</sub>           | Static on resistance                                 | V <sub>IN_LS2</sub> = 5 V, I <sub>OUT</sub> = 500 mA, over full temperature range   |                    |      | 500  | mΩ   |
| I <sub>LIMIT</sub>            | Short circuit current limit                          | Output shorted to GND; V <sub>IN_LS2</sub> ≥ 4 V                                    | LS2ILIM[1:0] = 00b |      | 126  | mA   |
|                               |                                                      |                                                                                     | LS2ILIM[1:0] = 01b | 188  | 251  |      |
|                               |                                                      |                                                                                     | LS2ILIM[1:0] = 10b | 465  | 631  |      |
|                               |                                                      |                                                                                     | LS2ILIM[1:0] = 11b | 922  | 1290 |      |
| I <sub>LEAK</sub>             | Reverse leakage current                              | V <sub>LS2</sub> > V <sub>IN_LS2</sub> + 1 V                                        |                    | 12   | 30   | μA   |
| t <sub>BLANK</sub>            | Interrupt blanking time                              | Output shorted to GND until interrupt is triggered                                  |                    | 15   |      | ms   |
| R <sub>DIS</sub>              | Internal discharge resistor at output <sup>(2)</sup> | LS2DCHRG = 1b                                                                       | 150                | 250  | 380  | Ω    |
| T <sub>OTS</sub>              | Overtemperature shutdown <sup>(4)</sup>              |                                                                                     | 125                | 132  | 139  | °C   |
|                               | Hysteresis                                           |                                                                                     |                    | 10   |      |      |
| C <sub>OUT</sub>              | Nominal output capacitance value                     | Ceramic, X5R or X7R, see Table 8-3.                                                 | 1                  |      | 100  | μF   |
| <b>LOAD SWITCH 3 (LS3)</b>    |                                                      |                                                                                     |                    |      |      |      |
| V <sub>IN_LS3</sub>           | Input voltage range                                  | V <sub>IN_BIAS</sub> > V <sub>UVLO</sub>                                            | 1.8                |      | 10   | V    |
| R <sub>DS(ON)</sub>           | Static on resistance                                 | V <sub>IN_LS3</sub> = 9 V, I <sub>OUT</sub> = 500 mA, over full temperature range   |                    |      | 440  | mΩ   |
|                               |                                                      | V <sub>IN_LS3</sub> = 5 V, I <sub>OUT</sub> = 500 mA, over full temperature range   |                    |      | 526  |      |
|                               |                                                      | V <sub>IN_LS3</sub> = 2.8 V, I <sub>OUT</sub> = 200 mA, over full temperature range |                    |      | 656  |      |
|                               |                                                      | V <sub>IN_LS3</sub> = 1.8 V, I <sub>OUT</sub> = 200 mA, over full temperature range |                    |      | 910  |      |
| I <sub>LIMIT</sub>            | Short circuit current limit                          | V <sub>IN_LS</sub> > 2.3 V,<br>Output shorted to GND                                | LSILIM[1:0] = 00b  | 98   | 126  | mA   |
|                               |                                                      |                                                                                     | LSILIM[1:0] = 01b  | 194  | 253  |      |
|                               |                                                      |                                                                                     | LSILIM[1:0] = 10b  | 475  | 738  |      |
|                               |                                                      |                                                                                     | LSILIM[1:0] = 11b  | 900  | 1234 |      |
|                               |                                                      | V <sub>IN_LS</sub> ≤ 2.3 V,<br>Output shorted to GND                                | LSILIM[1:0] = 00b  | 98   | 126  |      |
|                               |                                                      |                                                                                     | LSILIM[1:0] = 01b  | 194  | 253  |      |
|                               |                                                      |                                                                                     | LSILIM[1:0] = 10b  | 475  | 738  |      |
| t <sub>BLANK</sub>            | Interrupt blanking time                              | Output shorted to GND until interrupt is triggered.                                 |                    | 15   |      | ms   |
| R <sub>DIS</sub>              | Internal discharge resistor at output <sup>(2)</sup> | LS3DCHRG = 1                                                                        | 650                | 1000 | 1500 | Ω    |
| T <sub>OTS</sub>              | Overtemperature shutdown <sup>(4)</sup>              |                                                                                     | 125                | 132  | 139  | °C   |
|                               | Hysteresis                                           |                                                                                     |                    | 10   |      | °C   |
| C <sub>OUT</sub>              | Nominal output capacitance value                     | Ceramic, X5R or X7R, see Table 8-3.                                                 | 1                  | 100  | 220  | μF   |
| <b>BACKUP BATTERY MONITOR</b> |                                                      |                                                                                     |                    |      |      |      |
| V <sub>TH</sub>               | Comparator threshold                                 | Ideal level                                                                         |                    | 3    |      | V    |
|                               |                                                      | Good level                                                                          |                    | 2.6  |      | V    |
|                               |                                                      | Low level                                                                           |                    | 2.3  |      | V    |
|                               | Accuracy                                             |                                                                                     | –3%                |      | 3%   |      |
| R <sub>LOAD</sub>             | Load impedance                                       | Applied from CC to GND during comparison.                                           | 70                 | 100  | 130  | kΩ   |

## 6.5 Electrical Characteristics (continued)

Over operating free-air temperature range (unless otherwise noted).

| PARAMETER                                    |                                                       | TEST CONDITIONS                                                                      | MIN                        | TYP           | MAX  | UNIT    |
|----------------------------------------------|-------------------------------------------------------|--------------------------------------------------------------------------------------|----------------------------|---------------|------|---------|
| $t_{DLY}$                                    | Measurement delay                                     | $R_{LOAD}$ is connected during delay time. Measurement is taken at the end of delay. |                            | 600           |      | ms      |
| <b>I/O LEVELS AND TIMING CHARACTERISTICS</b> |                                                       |                                                                                      |                            |               |      |         |
| $PG_{DLY}$                                   | PGOOD delay time                                      | PGDLY[1:0] = 00b                                                                     |                            | 10            |      | ms      |
|                                              |                                                       | PGDLY[1:0] = 01b                                                                     |                            | 20            |      |         |
|                                              |                                                       | PGDLY[1:0] = 10b                                                                     |                            | 50            |      |         |
|                                              |                                                       | PGDLY[1:0] = 11b                                                                     |                            | 150           |      |         |
| $t_{DG}$                                     | PB input                                              | Rising edge                                                                          |                            | 100           |      | ms      |
|                                              |                                                       | Falling edge                                                                         |                            | 50            |      | ms      |
|                                              | AC_DET input                                          | Rising edge                                                                          |                            | 100           |      | $\mu$ s |
|                                              |                                                       | Falling edge                                                                         |                            | 10            |      | ms      |
|                                              | PWR_EN input                                          | Rising edge                                                                          |                            | 10            |      | ms      |
|                                              |                                                       | Falling edge                                                                         |                            | 100           |      | $\mu$ s |
|                                              | GPIO1                                                 | Rising edge                                                                          |                            | 1             |      | ms      |
|                                              |                                                       | Falling edge                                                                         |                            | 1             |      | ms      |
|                                              | GPIO3 GPIO2                                           | Rising edge                                                                          |                            | 5             |      | $\mu$ s |
|                                              |                                                       | Falling edge                                                                         |                            | 5             |      | $\mu$ s |
| $t_{RESET}$                                  | Reset time                                            | PB input held low                                                                    | TRST = 0b                  | 8             |      | s       |
|                                              |                                                       |                                                                                      | TRST = 1b                  | 15            |      |         |
|                                              |                                                       |                                                                                      |                            |               |      |         |
| $V_{IH}$                                     | High level input voltage                              | SCL, SDA, GPIO1, and GPIO3 GPIO2                                                     | 1.3                        |               |      | V       |
|                                              |                                                       | AC_DET, PB                                                                           | $0.66 \times V_{IN\_BIAS}$ |               |      |         |
|                                              |                                                       | PWR_EN                                                                               | 1.3                        |               |      |         |
| $V_{IL}$                                     | Low level input voltage                               | SCL, SDA, PWR_EN, AC_DET, PB, GPIO1, and GPIO3 GPIO2                                 | 0                          |               | 0.4  | V       |
| $V_{OH}$                                     | High level output voltage                             | GPO2; $I_{SOURCE} = 5$ mA; GPO2_BUF = 1                                              | $V_{IN\_LS1} - 0.3$        | $V_{IN\_LS1}$ |      | V       |
|                                              |                                                       | PGOOD_BU; $I_{SOURCE} = 100$ $\mu$ A                                                 | $V_{DCDC6} - 10$ mV        |               |      |         |
| $V_{OL}$                                     | Low level output voltage                              | nWAKEUP, nINT, SDA, PGOOD, GPIO1, GPO2, and GPIO3; $I_{SINK} = 2$ mA                 | 0                          |               | 0.3  | V       |
|                                              |                                                       | nPFO; $I_{SINK} = 2$ mA                                                              | 0                          |               | 0.35 |         |
|                                              |                                                       | PGOOD_BU; $I_{SINK} = 100$ $\mu$ A                                                   | 0                          |               | 0.3  |         |
| $V_{PFI}$                                    | Power-fail comparator threshold                       | Input falling                                                                        |                            | 800           |      | mV      |
|                                              | Hysteresis                                            | Input rising                                                                         |                            | 40            |      | mV      |
|                                              | Accuracy                                              |                                                                                      | -4%                        |               | 4%   |         |
|                                              | Deglitch                                              | Input falling                                                                        |                            | 25            |      | $\mu$ s |
|                                              |                                                       | Input rising                                                                         |                            | 10            |      | ms      |
| $I_{DC34\_SEL}$                              | DC34_SEL bias current                                 | Enabled only at power-up.                                                            |                            | 10            |      | $\mu$ A |
| $V_{DC34\_SEL}$                              | DCDC3 and DCDC4 power-up default selection thresholds | Threshold 1                                                                          |                            | 100           |      | mV      |
|                                              |                                                       | Threshold 2                                                                          |                            | 163           |      |         |
|                                              |                                                       | Threshold 3                                                                          |                            | 275           |      |         |
|                                              |                                                       | Threshold 4                                                                          |                            | 400           |      |         |
|                                              |                                                       | Threshold 5                                                                          |                            | 575           |      |         |
|                                              |                                                       | Threshold 6                                                                          |                            | 825           |      |         |
|                                              |                                                       | Threshold 7                                                                          |                            | 1200          |      |         |

## 6.5 Electrical Characteristics (continued)

Over operating free-air temperature range (unless otherwise noted).

| PARAMETER                |                                                            | TEST CONDITIONS                                                                                                                | MIN   | TYP  | MAX  | UNIT |
|--------------------------|------------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------|-------|------|------|------|
| R <sub>DC34_SEL</sub>    | DCDC3 and DCDC4 power-up default selection resistor values | Setting 0                                                                                                                      | 0     | 0    | 7.7  | kΩ   |
|                          |                                                            | Setting 1                                                                                                                      | 11.3  | 12.1 | 13   |      |
|                          |                                                            | Setting 2                                                                                                                      | 18.1  | 20   | 22   |      |
|                          |                                                            | Setting 3                                                                                                                      | 30.9  | 31.6 | 32.3 |      |
|                          |                                                            | Setting 4                                                                                                                      | 44.8  | 45.3 | 46.4 |      |
|                          |                                                            | Setting 5                                                                                                                      | 64.2  | 64.9 |      |      |
|                          |                                                            | Setting 6                                                                                                                      | 92.9  | 95.3 | 96.9 |      |
|                          |                                                            | Setting 7                                                                                                                      | 135.3 | 150  |      |      |
| I <sub>BIAS</sub>        | Input bias current                                         | SCL, SDA, GPIO1 <sup>(5)</sup> , GPIO3 <sup>(5)</sup> ; V <sub>IN</sub> = 3.3 V                                                |       | 0.01 | 1    | μA   |
|                          |                                                            | PB, AC_DET, PFI; V <sub>IN</sub> = 3.3 V                                                                                       |       |      | 500  | nA   |
| I <sub>LEAK</sub>        | Pin leakage current                                        | nINT, nWAKEUP, nPFO, PGOOD, PWR_EN, GPIO1 <sup>(6)</sup> , GPO2 <sup>(7)</sup> , GPIO3 <sup>(6)</sup> V <sub>OUT</sub> = 3.3 V |       |      | 500  | nA   |
| OSCILLATOR               |                                                            |                                                                                                                                |       |      |      |      |
| f <sub>OSC</sub>         | Oscillator frequency                                       |                                                                                                                                |       | 2400 |      | kHz  |
|                          | Frequency accuracy                                         | T <sub>J</sub> = −40°C to +105°C                                                                                               | −12%  |      | 12%  |      |
| OVERTEMPERATURE SHUTDOWN |                                                            |                                                                                                                                |       |      |      |      |
| T <sub>OTS</sub>         | Overtemperature shutdown                                   | Increasing junction temperature                                                                                                | 135   | 145  | 155  | °C   |
|                          | Hysteresis                                                 | Decreasing junction temperature                                                                                                |       | 20   |      |      |
| T <sub>WARN</sub>        | High-temperature warning                                   | Increasing junction temperature                                                                                                | 90    | 100  | 110  | °C   |
|                          | Hysteresis                                                 | Decreasing junction temperature                                                                                                |       | 15   |      |      |

- (1) IN\_BU has priority over CC input.
- (2) Discharge function disabled by default.
- (3) Switch is temporarily turned OFF if temperature exceeds OTS threshold.
- (4) Switch is temporarily turned OFF if input voltage drops below UVLO threshold.
- (5) Configured as input.
- (6) Configured as output.
- (7) Configured as open-drain output.
- (8) 500-μF of remote capacitance can be supported for DCDC1 and DCDC2.

## 6.6 Timing Requirements

|                     |                                                                                              |                              | MIN              | NOM | MAX              | UNIT |
|---------------------|----------------------------------------------------------------------------------------------|------------------------------|------------------|-----|------------------|------|
| f <sub>SCL</sub>    | Serial clock frequency                                                                       |                              |                  | 100 |                  | kHz  |
|                     |                                                                                              |                              |                  | 400 |                  |      |
| t <sub>HD;STA</sub> | Hold time (repeated) START condition. After this period, the first clock pulse is generated. | SCL = 100 kHz                | 4                |     |                  | μs   |
|                     |                                                                                              | SCL = 400 kHz                | 600              |     |                  | ns   |
| t <sub>LOW</sub>    | LOW period of the SCL clock                                                                  | SCL = 100 kHz                | 4.7              |     |                  | μs   |
|                     |                                                                                              | SCL = 400 kHz                | 1.3              |     |                  |      |
| t <sub>HIGH</sub>   | HIGH period of the SCL clock                                                                 | SCL = 100 kHz                | 4                |     |                  | μs   |
|                     |                                                                                              | SCL = 400 kHz <sup>(1)</sup> | 1                |     |                  |      |
| t <sub>SU;STA</sub> | Set-up time for a repeated START condition                                                   | SCL = 100 kHz                | 4.7              |     |                  | μs   |
|                     |                                                                                              | SCL = 400 kHz                | 600              |     |                  | ns   |
| t <sub>HD;DAT</sub> | Data hold time                                                                               | SCL = 100 kHz                | 0                |     | 3.45             | μs   |
|                     |                                                                                              | SCL = 400 kHz                | 0                |     | 900              | ns   |
| t <sub>SU;DAT</sub> | Data set-up time                                                                             | SCL = 100 kHz                | 250              |     |                  | ns   |
|                     |                                                                                              | SCL = 400 kHz                | 100              |     |                  |      |
| t <sub>r</sub>      | Rise time of both SDA and SCL signals                                                        | SCL = 100 kHz                |                  |     | 1000             | ns   |
|                     |                                                                                              | SCL = 400 kHz                |                  |     | 300              |      |
| t <sub>f</sub>      | Fall time of both SDA and SCL signals                                                        | SCL = 100 kHz                |                  |     | 300              | ns   |
|                     |                                                                                              | SCL = 400 kHz                |                  |     | 300              |      |
| t <sub>SU;STO</sub> | Set-up time for STOP condition                                                               | SCL = 100 kHz                | 4                |     |                  | μs   |
|                     |                                                                                              | SCL = 400 kHz                | 600              |     |                  | ns   |
| t <sub>BUF</sub>    | Bus free time between STOP and START condition                                               | SCL = 100 kHz                | 4.7              |     |                  | μs   |
|                     |                                                                                              | SCL = 400 kHz                | 1.3              |     |                  |      |
| t <sub>SP</sub>     | Pulse width of spikes which must be suppressed by the input filter                           | SCL = 100 kHz                | — <sup>(2)</sup> |     | — <sup>(2)</sup> | ns   |
|                     |                                                                                              | SCL = 400 kHz                | 0                |     | 50               |      |
| C <sub>b</sub>      | Capacitive load for each bus line                                                            | SCL = 100 kHz                |                  |     | 400              | pF   |
|                     |                                                                                              | SCL = 400 kHz                |                  |     | 400              |      |

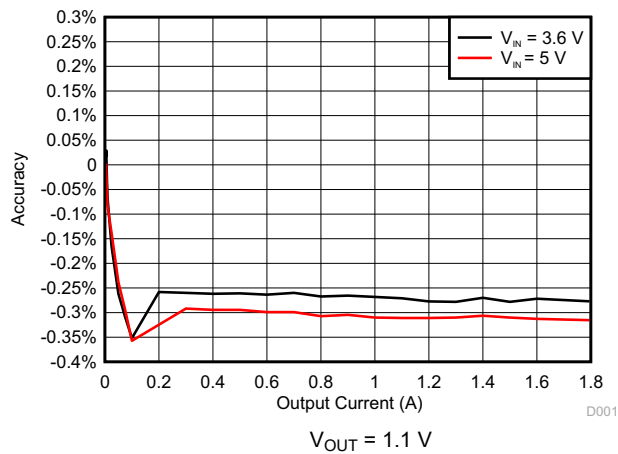
(1) The SCL duty cycle at 400 kHz must be > 40%.

(2) The inputs of I<sup>2</sup>C devices in Standard-mode do not require spike suppression.

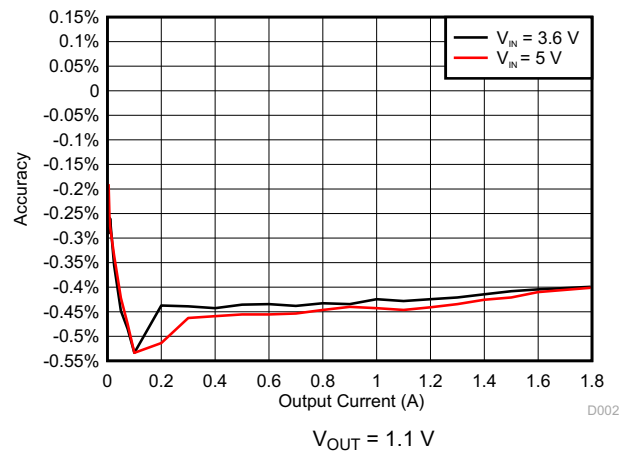


## 6.7 Typical Characteristics

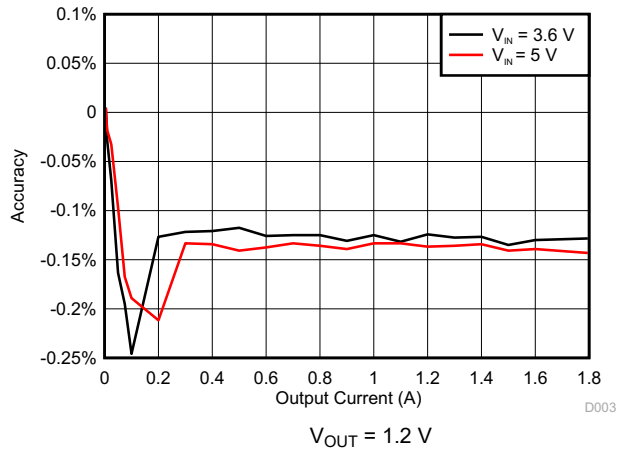
At  $T_J = 25^\circ\text{C}$  unless otherwise noted.



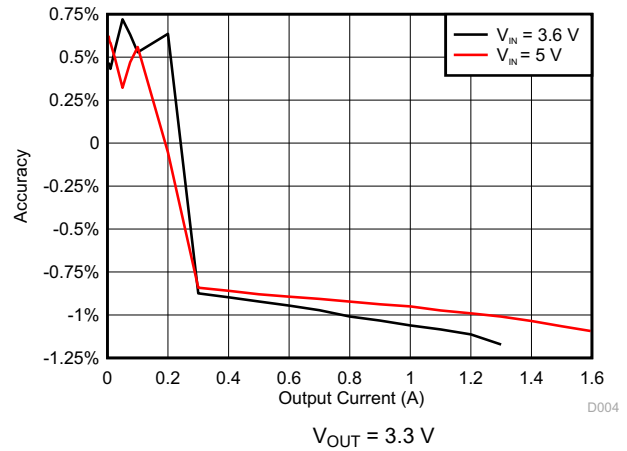
**Figure 6-1. DCDC1 Accuracy**



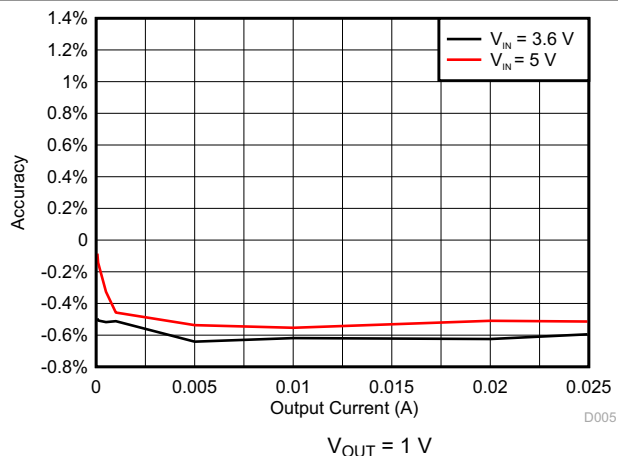
**Figure 6-2. DCDC2 Accuracy**



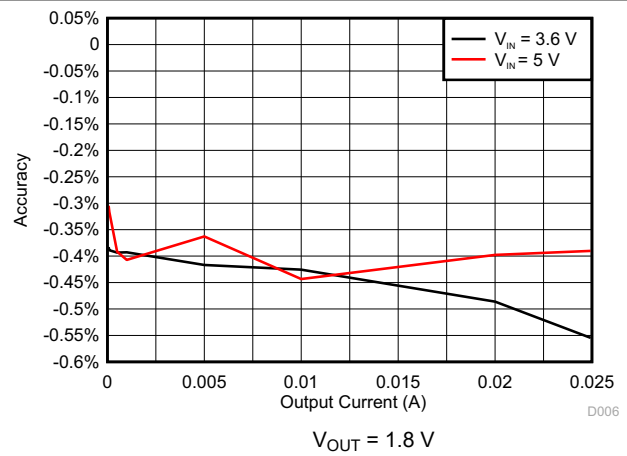
**Figure 6-3. DCDC3 Accuracy**



**Figure 6-4. DCDC4 Accuracy**



**Figure 6-5. DCDC5 Accuracy**



**Figure 6-6. DCDC6 Accuracy**

## 7 Detailed Description

### 7.1 Overview

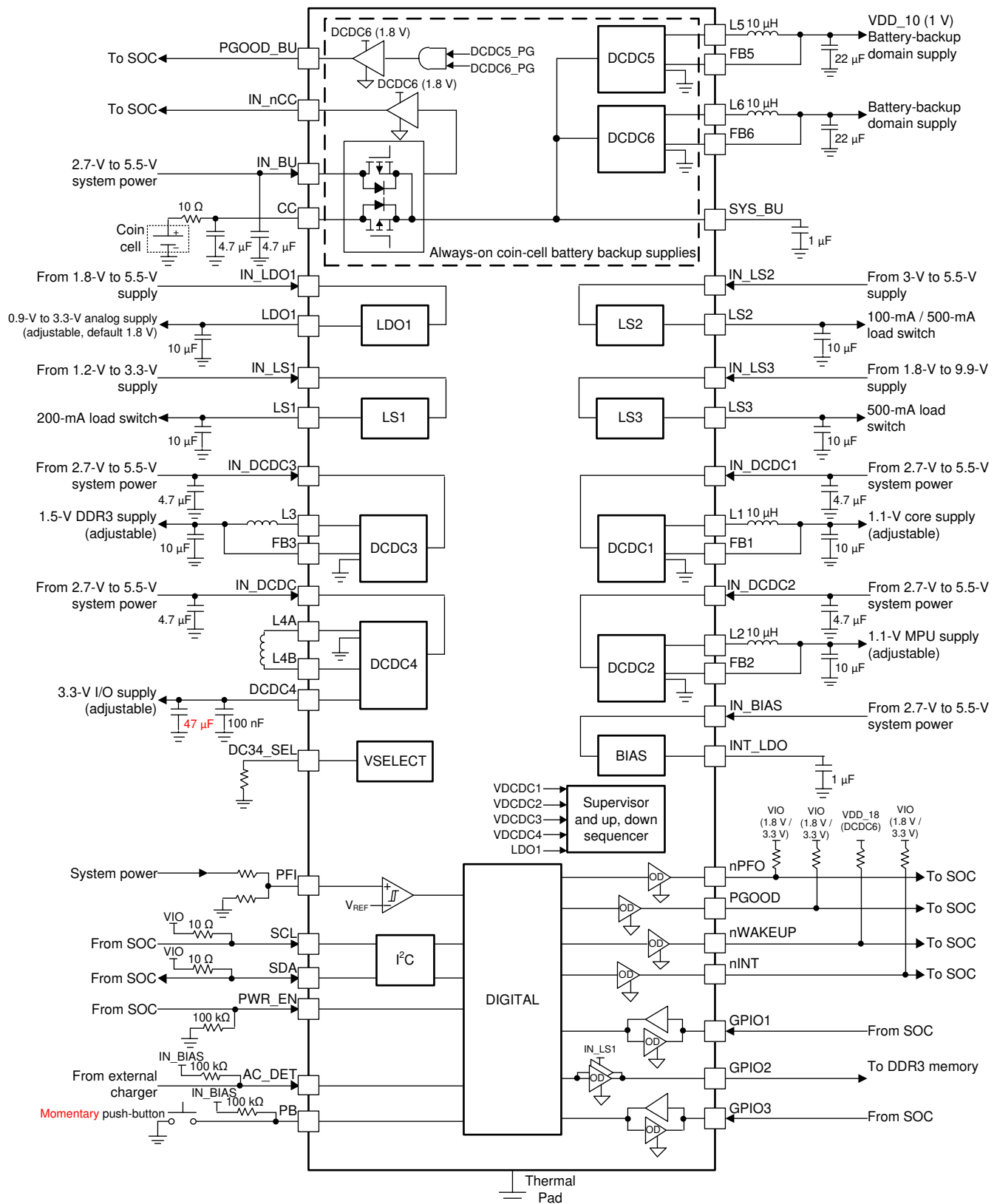
The TPS6521835 provides three step-down converters, three load switches, three general-purpose I/Os, two battery backup supplies, one buck-boost converter, and one LDO. The system can be supplied by a regulated 5-V supply. The device is characterized across a  $-40^{\circ}\text{C}$  to  $+105^{\circ}\text{C}$  temperature range, which makes it suitable for various industrial applications.

The I<sup>2</sup>C interface provides comprehensive features for using TPS6521835. All rails, load switches, and GPIOs can be enabled and disabled. Voltage thresholds for the UVLO and supervisor can be customized. Power-up and power-down sequences can also be programmed through I<sup>2</sup>C. Interrupts for overtemperature, overcurrent, and undervoltage can be monitored for the load-switch.

The integrated voltage supervisor monitors DCDC 1-4 and LDO1 for undervoltage. It has two settings; the standard settings only monitor for undervoltage, while the strict settings implement tight tolerances on both undervoltage and overvoltage. A power-good signal is provided to report the regulation state of the five rails.

The three hysteretic step-down converters can each supply up to 1.8 A of current. The default output voltages for each converter can be adjusted through the I<sup>2</sup>C interface. DCDC1 and DCDC2 features dynamic voltage scaling with an adjustable slew rate. The step-down converters operate in a low power mode at light load, and can be forced into power mode (PWM) operation for noise sensitive applications.

## 7.2 Functional Block Diagram



## 7.3 Feature Description

### 7.3.1 Wake-Up and Power-Up and Power-Down Sequencing

The TPS6521835 has a predefined power-up and power-down sequence, which does not change in a typical application. The user can define custom sequences with I<sup>2</sup>C. The power-up sequence is defined by a series of ten strobes and nine delay times. Each output rail is assigned to a strobe to determine the order of enabling rails. A single rail is assigned to only one strobe, but multiple rails can be assigned to the same strobe. The delay times between strobes are between 2 ms and 5 ms.

#### 7.3.1.1 Power-Up Sequencing

When the power-up sequence initiates, STROBE 1 occurs, and any rail assigned to this strobe is enabled. After a delay time of DLY1, STROBE 2 occurs and the rail assigned to this strobe is powered up. The sequence continues until all strobes occur and all DLYx times execute. Strobe assignments and delay times are defined in the SEQx registers, and are changed under I<sup>2</sup>C control. The power-up sequence executes if one of the following events occurs:

- From the OFF state:
  - The push-button (PB) is pressed (falling edge on PB) *or*
  - The AC\_DET pin is pulled low (falling edge) *or*
  - The PWR\_EN is asserted (driven to high-level) *or*
  - The main power is connected (IN\_BIAS) and AC\_DET is grounded *and*
  - The device is not in undervoltage lockout (UVLO) or overtemperature shutdown (OTS).
- From the PRE\_OFF state:
  - The PB is pressed (falling edge on PB) *or*
  - The AC\_DET pin is pulled low (falling edge) *or*
  - The PWR\_EN is asserted (driven to high-level) *and*
  - The device is not in UVLO or OTS.
- From the SUSPEND state:
  - The PB is pressed (falling edge on PB) *or*
  - The AC\_DET pin is pulled low (falling edge) *or*
  - The PWR\_EN pin is pulled high (level sensitive) *and*
  - The device is not in UVLO or OTS.

When a power-up event is detected, the device enters a WAIT\_PWR\_EN state and triggers the power-up sequence. The device remains in WAIT\_PWR\_EN as long as the PWR\_EN and either the PB or AC\_DET pin are held low. If both, the PB and AC\_DET return to logic-high state and the PWR\_EN pin has not been asserted within 20 s of entering WAIT\_PWR\_EN state, the power-down sequence is triggered and the device returns to OFF state. Once PWR\_EN is asserted, the device advances to ACTIVE state, which is functionally equivalent to WAIT\_PWR\_EN. However, the AC\_DET pin is ignored and power-down is controlled by the PWR\_EN pin only.

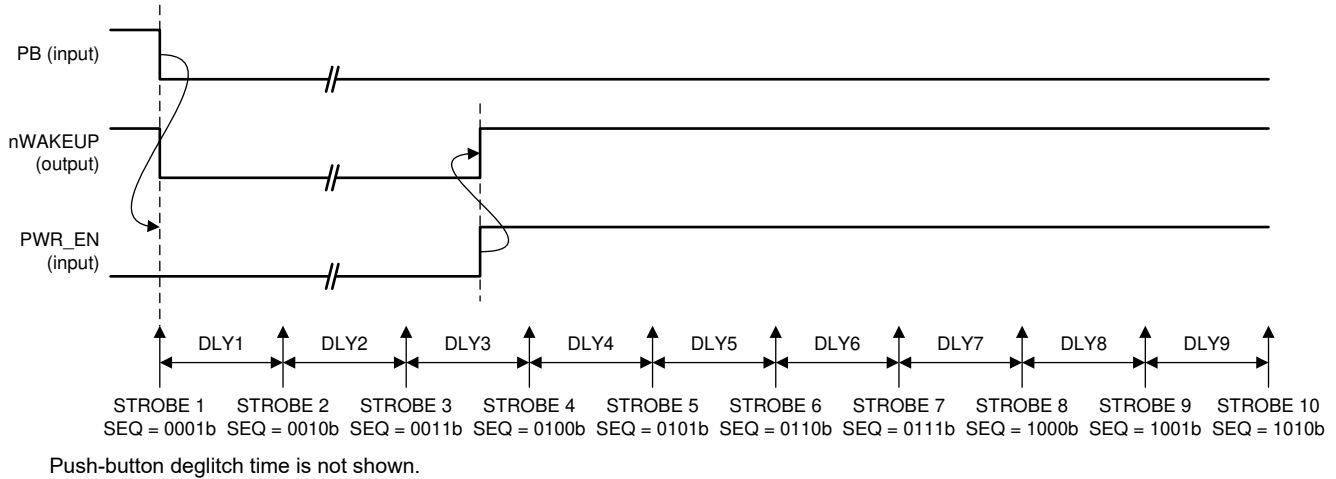
Rails not assigned to a strobe (SEQ = 0000b) are not affected by power-up and power-down sequencing and remain in their current ON or OFF state regardless of the sequencer. A rail can be enabled and disabled at any time by setting the corresponding enable bit in the ENABLEx register, with the exception that the ENABLEx register cannot be accessed while the sequencer is active. Enable bits always reflect the current enable state of the rail. For example, the sequencer sets and resets the enable bits for the rails under its control.

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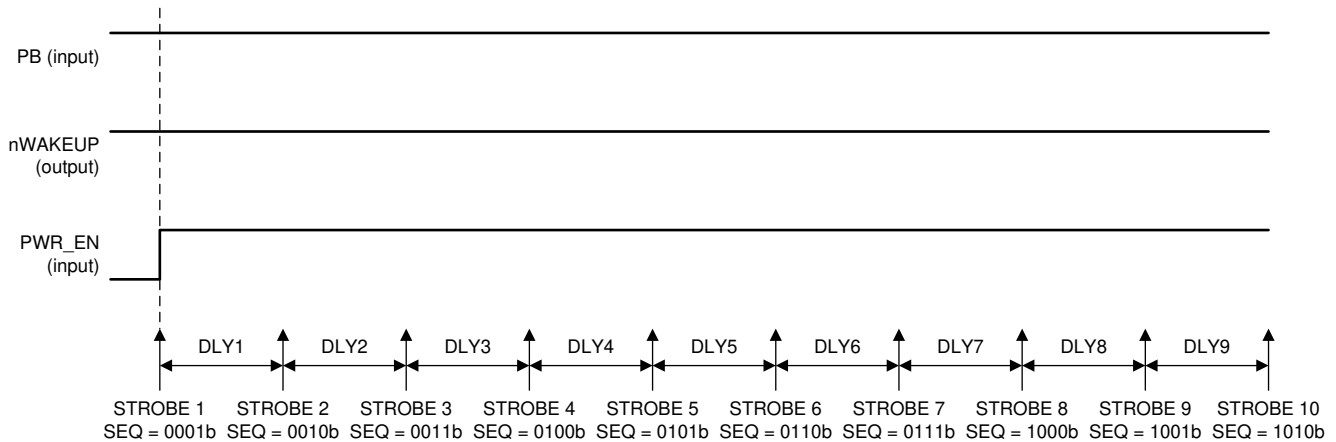
#### Note

The power-up sequence is defined by strobes and delay times, and can be triggered by the PB, AC\_DET (not shown, same as PB), or PWR\_EN pin.

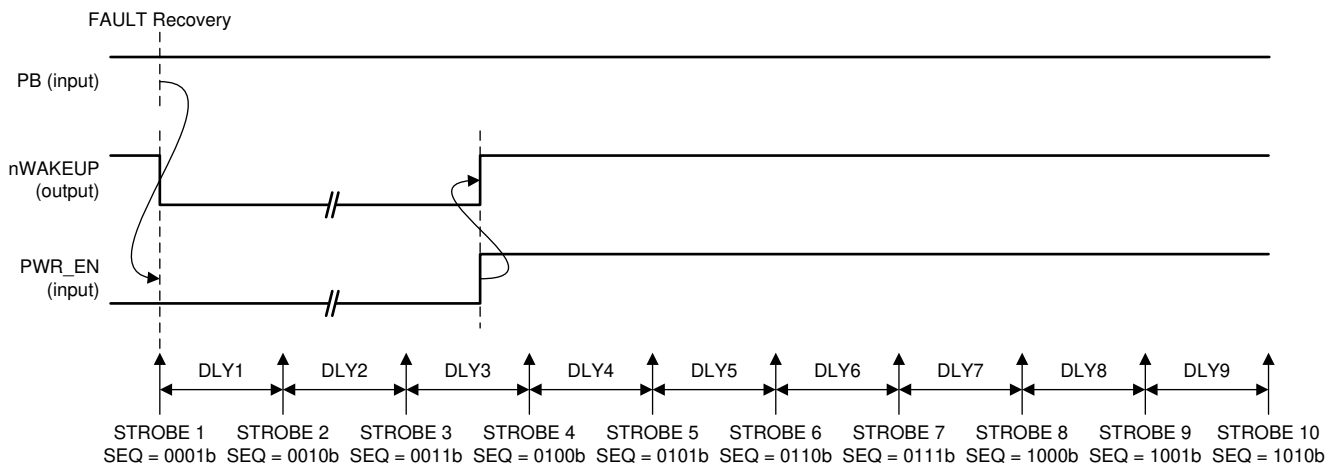
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**Figure 7-1. Power-Up Sequences from OFF or SUSPEND State; PB is Power-Up Event**



**Figure 7-2. Power-Up Sequences from SUSPEND State; PWR\_EN is Power-Up Event**



**Figure 7-3. Power-Up Sequences from RECOVERY State**

### 7.3.1.2 Power-Down Sequencing

By default, the power-down sequence follows the reverse of the power-up sequence. When the power-down sequence is triggered, STROBE 10 occurs and any rail assigned to STROBE 10 is shut down and its discharge circuit is enabled. After a delay time of DLY9, STROBE 9 occurs and any rail assigned to it is shut down and its discharge circuit is enabled. The sequence continues until all strobes occur and all DLYx times execute. The DLYx times are extended by a factor of 10x to provide ample time for discharge, and preventing output voltages from crossing during shut-down. The DLYFCTR bit is applied globally to all power-down delay times. Regardless of the DLYx and DLYFCTR settings, the PMIC enters OFF, SUSPEND, or RECOVERY state 500 ms after the power-down sequence initiates, to ensure that the discharge circuits remain enabled for a minimum of 150 ms before the next power-up sequence starts.

A power-down sequence executes if one of the following events occurs:

- The device is in the WAIT\_PWR\_EN state, the PB and AC\_DET pins are high, PWR\_EN is low, and the 20-s timer has expired.
- The device is in the ACTIVE state and the PWR\_EN pin is pulled low.
- The device is in the WAIT\_PWR\_EN, ACTIVE, or SUSPEND state and the push-button is held low for > 8 s (15 s if TRST = 1b).
- A fault occurs in the device (OTS, UVLO, PGOOD failure).

When transitioning from ACTIVE to SUSPEND state, the rails not controlled by the power-down sequencer maintains the same ON/OFF state in SUSPEND state that it had in ACTIVE state. This allows for the selected power rails to remain powered up when in the SUSPEND state.

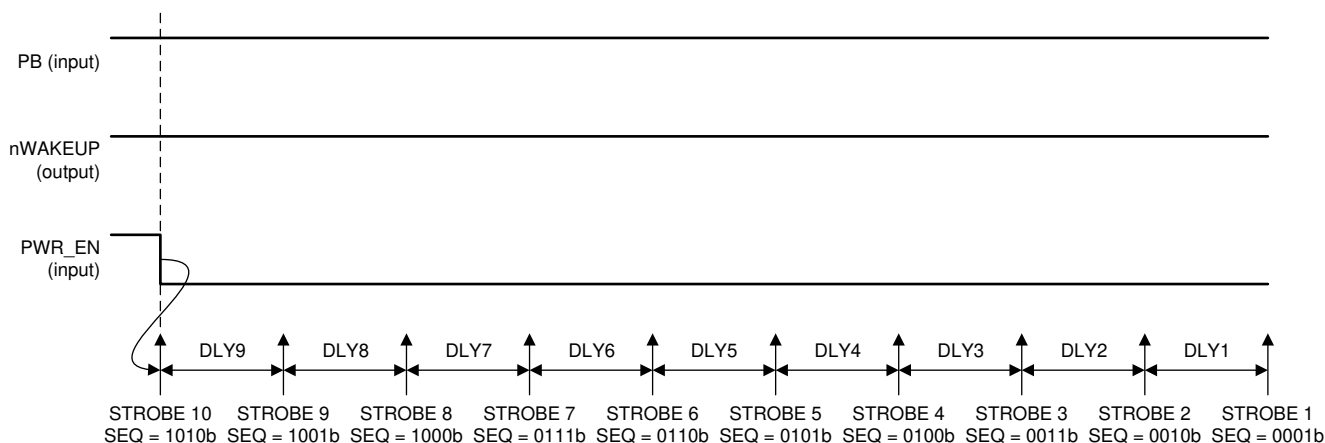
When transitioning to the OFF or RECOVERY state, rails not under sequencer control are shut-down as follows:

- DCDC1, DCDC2, DCDC3, DCDC4, LDO1, and LS1 shut down at the beginning of the power-down sequence, if not under sequencer control (SEQ = 0b).
- LS2 and LS3 shut down as the state machine enters an OFF or RECOVERY state; 500 ms after the power-down sequence is triggered.

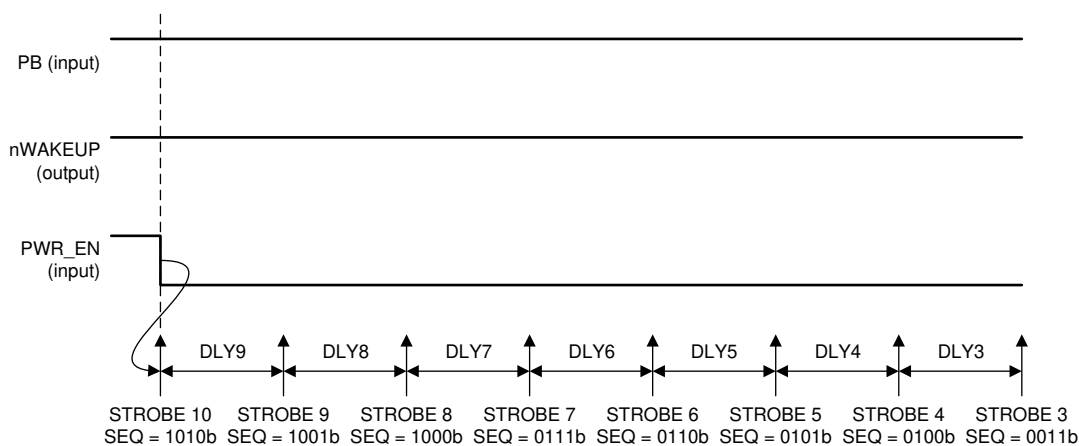
If the supply voltage on IN\_BIAS drops below 2.5 V, the digital core is reset and all power rails are shut down instantaneously and are pulled low to ground by their internal discharge circuitry (DCDC1-4, and LDO1). The amount of time the discharge circuitry remains active is a function of the INT\_LDO hold up time (see [Section 7.3.1.6](#) for more details).

### 7.3.1.3 Strobe 1 and Strobe 2

STROBE 1 and STROBE 2 are dedicated to DCDC5 and DCDC6 which are *always-on*; powered up as soon as the device exits the OFF state, and ON in any other state. STROBE 1 and STROBE 2 options are available only for DCDC5 and DCDC6, not for any other rails.

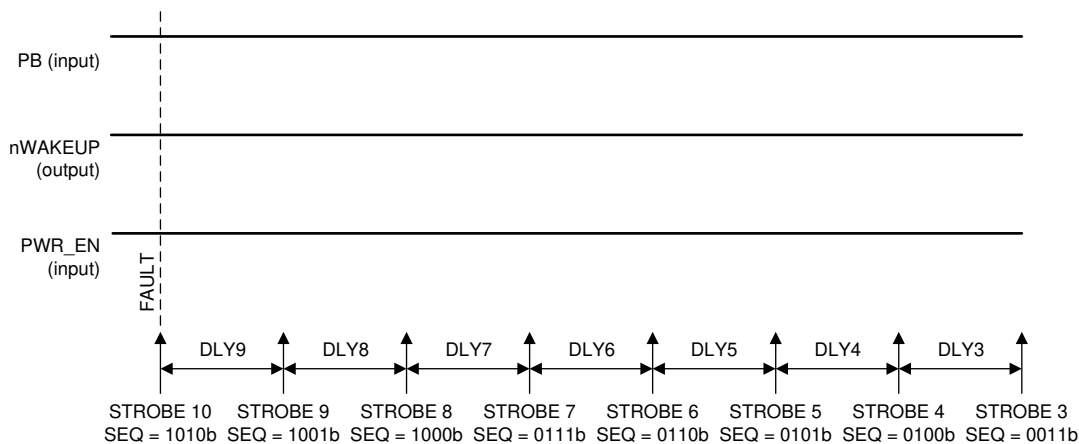


**Figure 7-4. Power-Down Sequences to OFF State; PWR\_EN is Power-Down Event; FSEAL = 0b**



STROBE2 and STROBE1 are not shown.

**Figure 7-5. Power-Down Sequences to SUSPEND State; PWR\_EN is Power-Down Event; FSEAL = 1b**



STROBE2 and STROBE1 are not shown.

**Figure 7-6. Power-Down Sequences to RECOVERY State; TSD or UV is Power-Down Event**

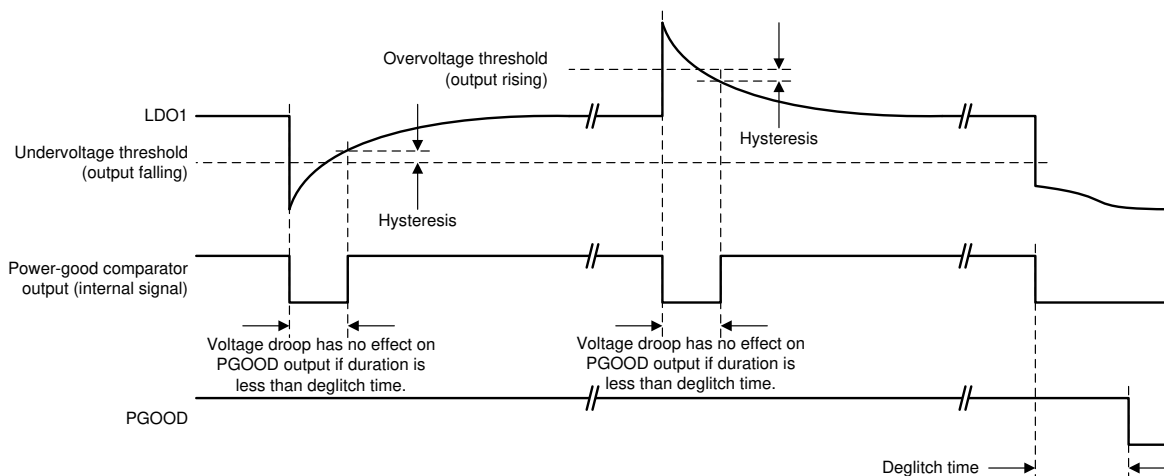
### 7.3.1.4 Supply Voltage Supervisor and Power-Good (PGOOD)

Power-good (PGOOD) is an open-drain output of the built-in voltage supervisor that monitors DCDC1, DCDC2, DCDC3, DCDC4, and LDO1. The output is Hi-Z when all enabled rails are in regulation and driven low when one or more rails encounter a fault which brings the output voltage outside the specified tolerance range. In a typical application PGOOD drives the reset signal of the SOC.

The supervisor monitors all enabled rails of the five regulators for undervoltage. The threshold and deglitch times for the supervisor are summarized in [Table 7-1](#) summarizes these details.

**Table 7-1. Supervisor Characteristics**

| PARAMETER               |                            | (TYPICAL)  |
|-------------------------|----------------------------|------------|
| Undervoltage monitoring | Threshold (output falling) | 90%        |
|                         | Deglitch (output falling)  | 1 ms       |
|                         | Deglitch (output rising)   | 10 $\mu$ s |
| Overvoltage monitoring  | Threshold (output falling) | N/A        |
|                         | Deglitch (output falling)  | N/A        |
|                         | Deglitch (output rising)   | N/A        |



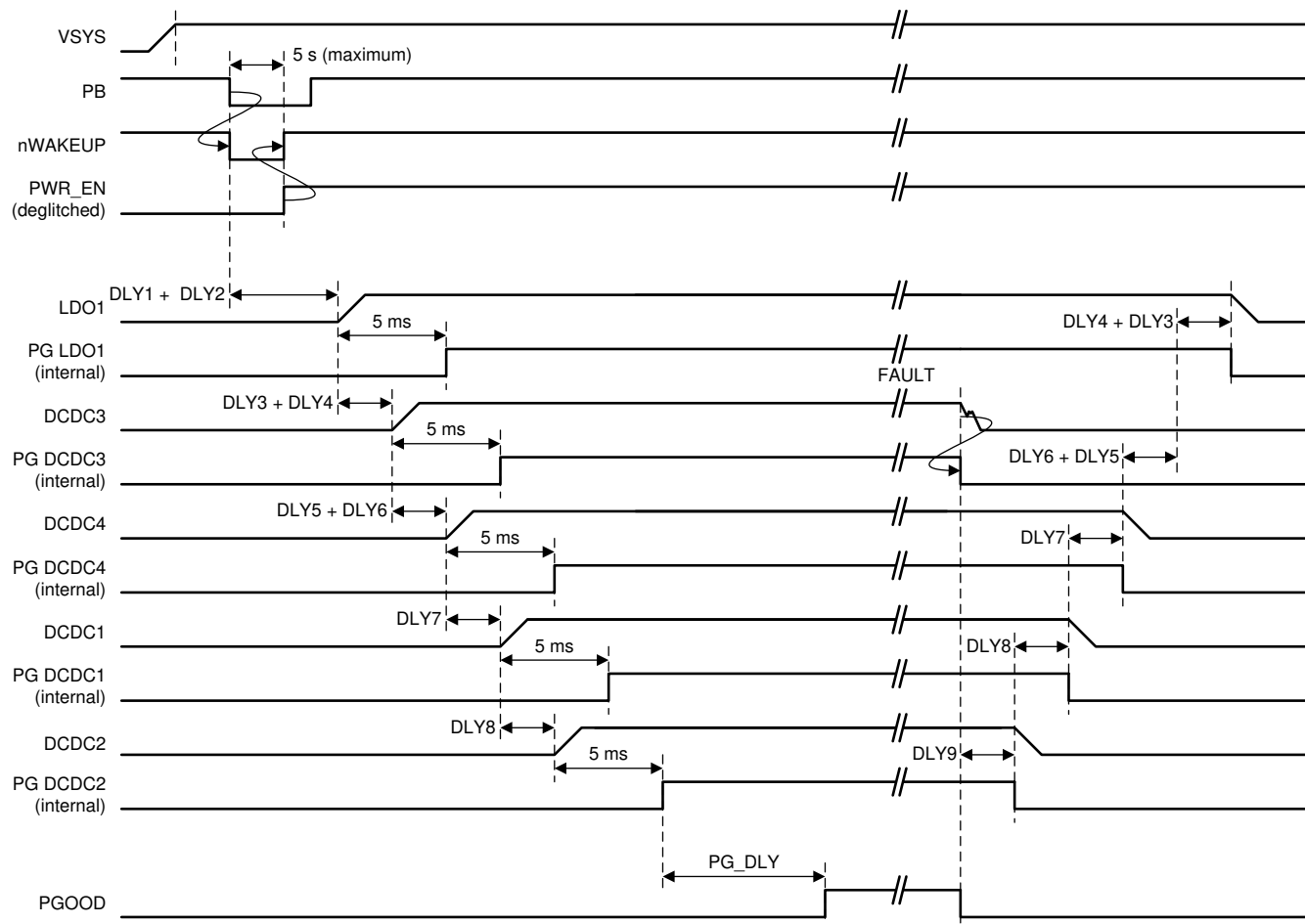
**Figure 7-7. Definition of Undervoltage, Overvoltage Thresholds, Hysteresis, and Deglitch Times**

The following rules apply to the PGOOD output:

- The power-up default state for THE PGOOD is low. When all rails are disabled, the PGOOD output is driven low.
- Only enabled rails are monitored. Disabled rails are ignored.
- Power-good monitoring of a particular rail starts 5 ms after the rail is enabled and is continuously monitored thereafter. This allows the rail to power-up.
- The PGOOD is delayed by PGDLY time after the sequencer is finished and the last rail is enabled.
- If an enabled rail is continuously outside the monitoring threshold for longer than the deglitch time, then the PGOOD is pulled low, and all rails are shut-down following the power-down sequence. PGDLY does not apply.
- Disabling a rail manually by resetting the DCx\_EN or LDO1\_EN bit has no effect on the PGOOD pin. If all rails are disabled, the PGOOD is driven low as the last rail is disabled.
- If the power-down sequencer is triggered, PGOOD is driven low.
- The PGOOD is driven low in the SUSPEND state, regardless of the number of rails that are enabled.

[Figure 7-8](#) shows a typical power-up sequence and PGOOD timing.





A. (1) Sequence shown for TPS65218D0 variant. For other TPS65218xx variants, refer to registers SEQ1-7 in Section 5.6.4 for factory programmed sequence order and timing.

**Figure 7-8. Typical Power-Up Sequence of the Main Output Rails**

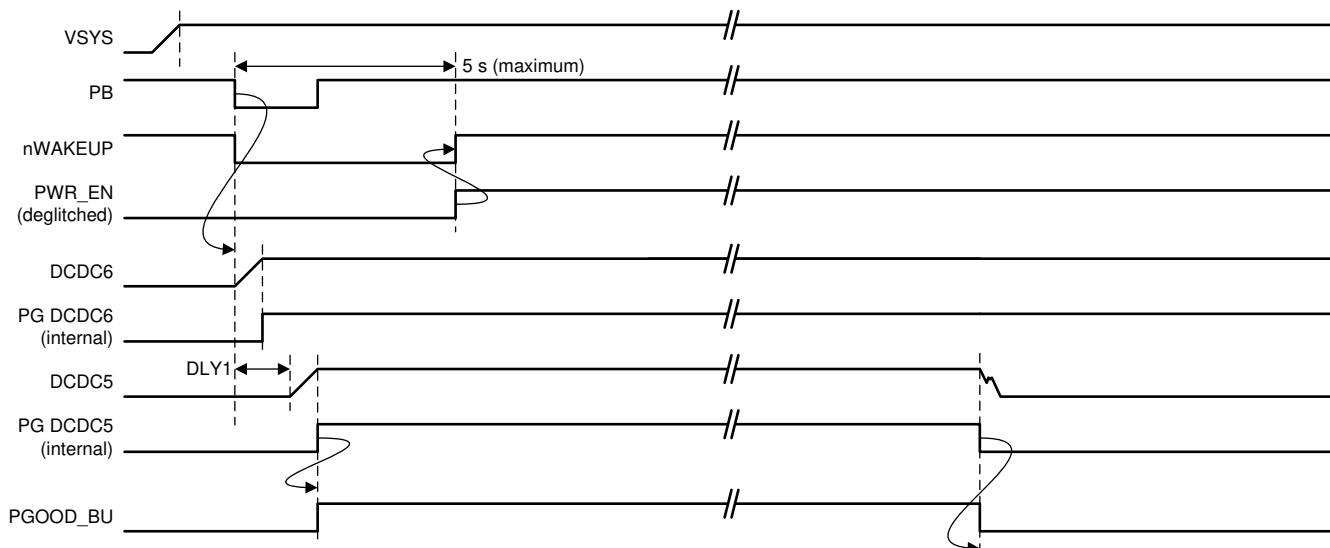
### 7.3.1.5 Backup Supply Power-Good (PGOOD\_BU)

PGOOD\_BU is a push-pull output indicating if DCDC5 and DCDC6 are in regulation. The output is driven to high when both rails are in regulation, and driven low if at least one of the rails is below the power-good threshold. The output-high level is equal to the output voltage of DCDC6.

PGOOD\_BU is the logical *and* between PGOOD (DCDC5) and PGOOD (DCDC6), and has no delay time built-in. Unlike the main power-good, a fault on DCDC5 or DCDC6 does not trigger the power-down sequencer, does not disable any of the rails in the system, and has no effect on the PGOOD pin. DCDC5 and DCDC6 recover automatically once the fault is removed.

#### Note

In this example, the power-down is triggered by a fault on DCDC3.



A. Sequence shown for TPS65218D0 and TPS6521825 variants. For TPS6521815 variant, order and timing of DCDC5 and DCDC6 can be modified using registers SEQ1-2 and SEQ5 in [Section 7.5.4](#).

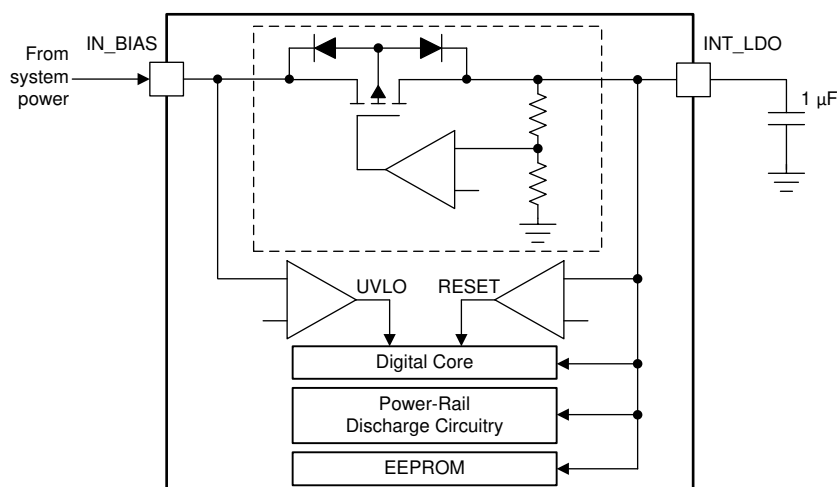
**Figure 7-9. Typical Power-Up Sequence of DCDC5 and DCDC6**

### 7.3.1.6 Internal LDO (INT\_LDO)

The internal LDO provides a regulated voltage to the internal digital core and analog circuitry. The internal LDO has a nominal output voltage of 2.5 V and can support up to 10 mA of external load.

When system power fails, the UVLO comparator triggers the power-down sequence. If system power drops below 2.5 V, the digital core is reset and all remaining power rails are shut down instantaneously and are pulled low to ground by their internal discharge circuitry (DCDC1-4 and LDO1).

The internal LDO reverse blocks to prevent the discharging of the output capacitor ( $C_{INT\_LDO}$ ) on the INT\_LDO pin. The remaining charge on the INT\_LDO output capacitor provides a supply for the power rail discharge circuitry to ensure the outputs are discharged to ground even if the system supply has failed. The amount of hold-up time specified in [Section 6.5](#) is a function of the output capacitor value ( $C_{INT\_LDO}$ ) and the amount of external load on the INT\_LDO pin, if any. The design allows for enough hold-up time to sufficiently discharge DCDC1-4, and LDO1 to ensure proper processor power-down sequencing. The amount of hold-up time is a function of the output capacitor value, which should not exceed 22  $\mu\text{F}$  and the amount of external load, if any.



**Figure 7-10. Internal LDO and UVLO Sensing**

### 7.3.1.7 Current Limited Load Switches

The TPS6521835 provides three current limited load switches with individual inputs, outputs, and enable control. Each switch provides the following control and diagnostic features:

- The ON or OFF state of the switch is controlled by the corresponding LSx\_EN bit in the ENABLE register.
- LS1 can be controlled by the sequencer or through I<sup>2</sup>C communication.
- LS2 and LS3 can *only* be controlled through I<sup>2</sup>C communication. The sequencer has no control over LS2 and LS3.
- Each switch has an active discharge function, disabled by default, and enabled through the LSxDCHRG bit. When enabled, the switch output is discharged to ground whenever the switch is disabled.
- When the PFI input drops below the power-fail threshold (the power-fail comparator trips), the load switches are automatically disabled to shed system load. This function must be individually enabled for each switch through the corresponding LSxnPFO bit. The switches do not turn back on automatically as the system voltage recovers, and must be manually re-enabled.
- An interrupt (LSx\_I) issues whenever a load switch actively limits the output current, such as when the output load exceeds the current limit value. The switch remains ON and provides current to the load according to the current-limit setting.
- All three load switches have local overtemperature sensors which disable the corresponding switch if the power dissipation and junction temperature exceeds the safe operating value. The switch automatically recovers once the temperature drops below the OTS threshold value minus hysteresis. The LSx\_F (fault) interrupt bit is set while the switch is held OFF by the OTS function.

#### 7.3.1.7.1 Load Switch 1 (LS1)

LS1 is a non-reverse blocking, low-voltage (< 3.6 V), low-impedance switch intended to support DDRx self-refresh mode by cutting off the DDRx supply to the SOC DDRx interface during SUSPEND mode. In a typical application, the input of LS1 is tied to the output of DCDC3 while the output of LS1 is connected to the memory-interface supply pin of the SOC. LS1 can be controlled by the internal sequencer, just as any power rail.

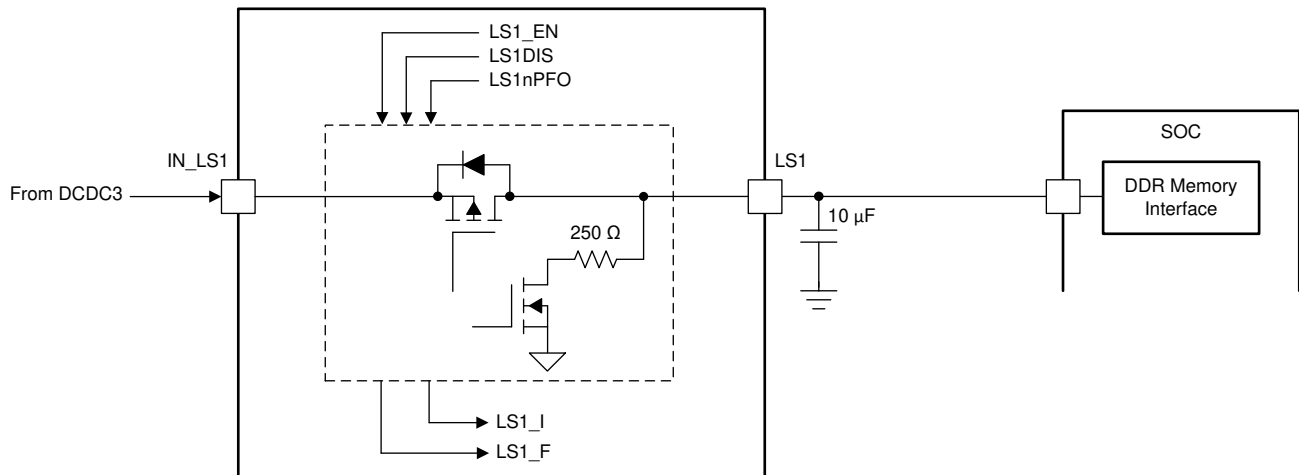


Figure 7-11. Typical Application of Load Switch 1

### 7.3.1.7.2 Load Switch 2 (LS2)

LS2 is a reverse-blocking, 5 V, low-impedance switch. Load switch 2 provides four different current limit values (100/200/500/1000 mA) that are selectable through LS2ILIM[1:0] bits. Overcurrent is reported through the LS2\_I interrupt.

LS2 has its own input-undervoltage protection which forces the switch OFF if the switch input voltage ( $V_{IN\_LS2}$ ) is  $< 2.7$  V. Similar to OTS, the LS2\_F interrupt is set when the switch is held OFF by the local UVLO function, and the switch recovers automatically when the input voltage rises above the UVLO threshold.

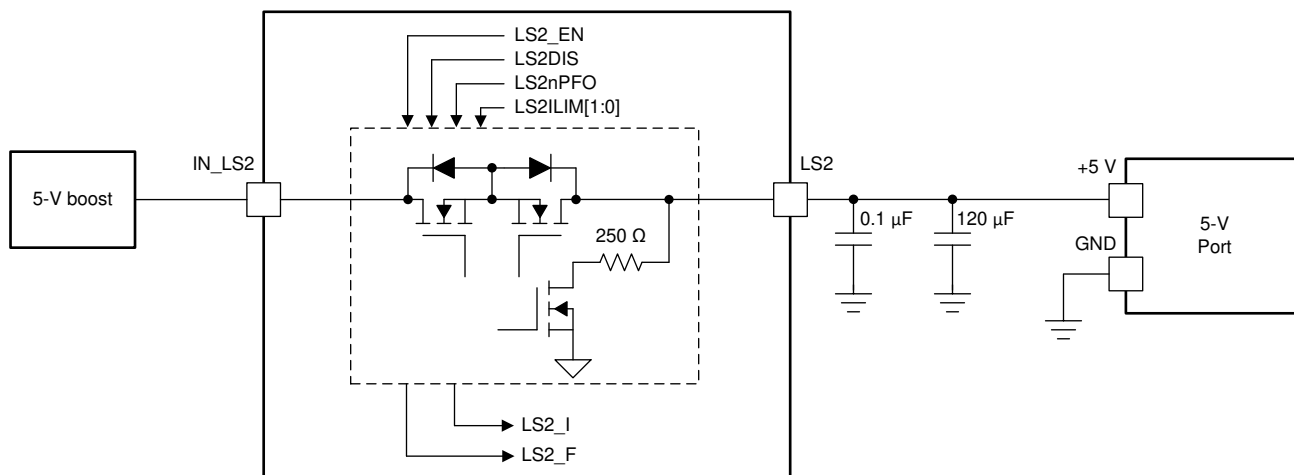


Figure 7-12. Typical Application of Load Switch 2

### 7.3.1.7.3 Load Switch 3 (LS3)

LS3 is a non-reverse blocking, medium-voltage ( $< 10$  V), low-impedance switch that can be used to provide 1.8-V to 10-V power to an auxiliary port. LS3 has four selectable current limit values that are selectable through LS3ILIM[1:0].

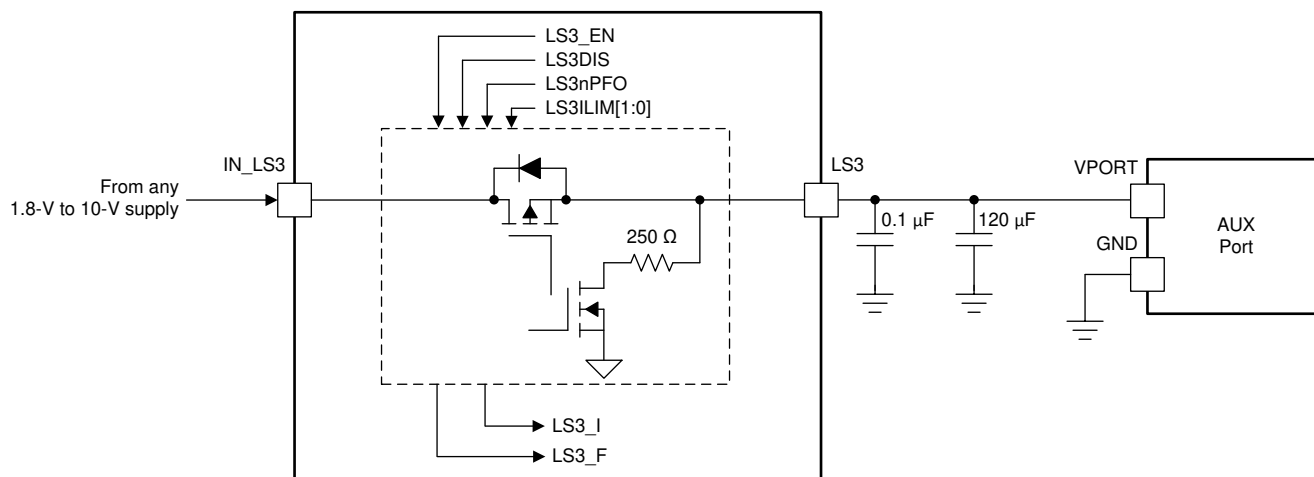
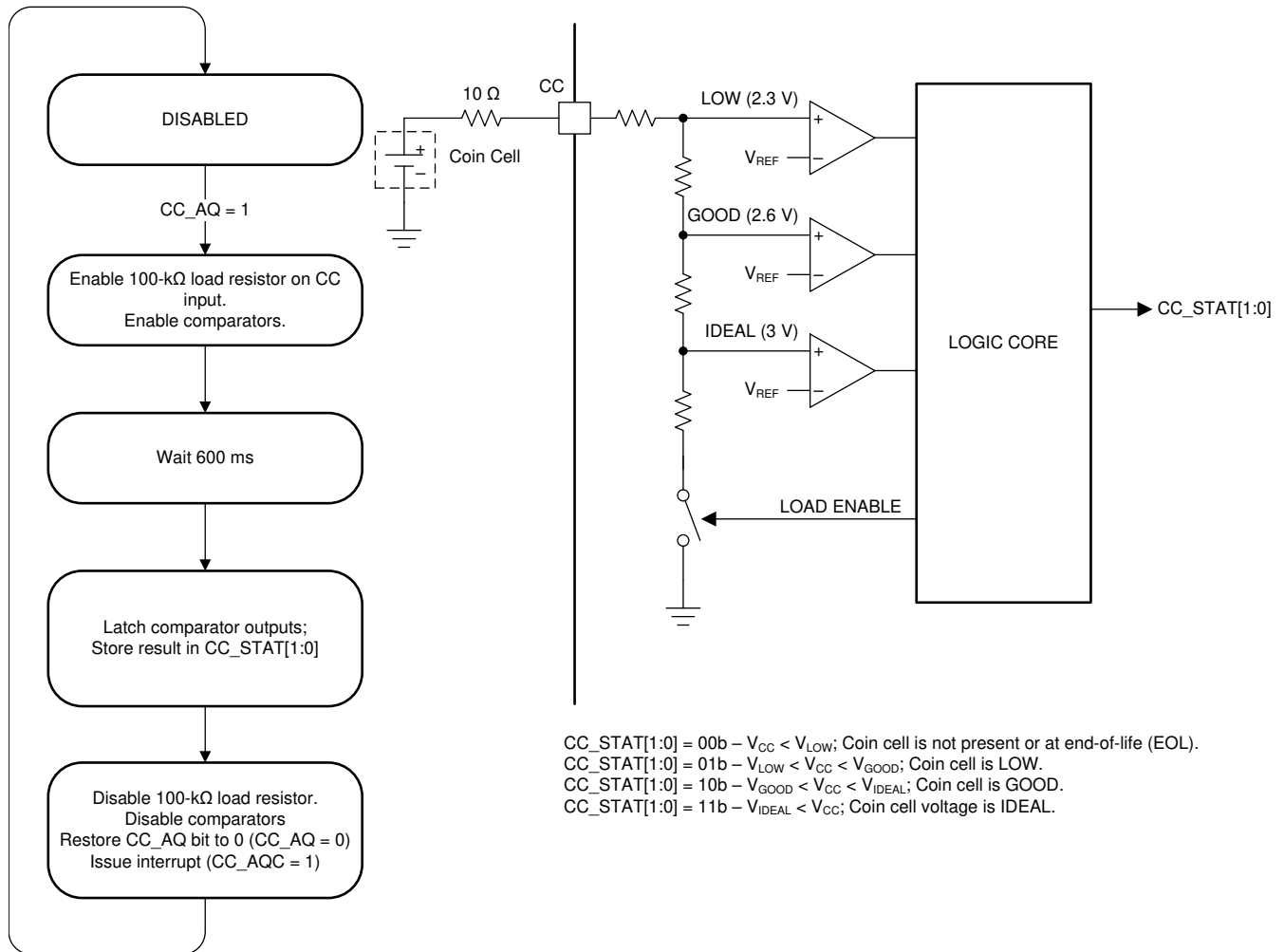


Figure 7-13. Typical Application of Load Switch 3

### 7.3.1.8 LDO1

LDO1 is a general-purpose LDO intended to provide power to analog circuitry on the SOC. LDO1 has an input voltage range from 1.8 V to 5.5 V, and can be connected either directly to the system power or the output of a DCDC converter. The output voltage is programmable in the range of 0.9 V to 3.4 V with a default of 1.8 V. LDO1 supports up to 200 mA at the minimum specified headroom voltage, and up to 400 mA at the typical operating condition of  $V_{OUT} = 1.8$  V,  $V_{IN\_LDO1} > 2.7$  V.

### 7.3.1.9 Coin Cell Battery Voltage Acquisition



**Figure 7-14. Left: Flow Chart for Acquiring Coin Cell Battery Voltage Right: Comparator Circuit**

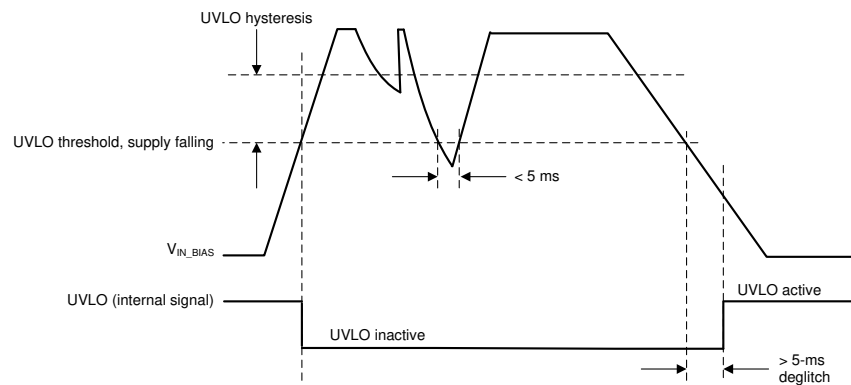
### 7.3.1.10 UVLO

Depending on the slew rate of the input voltage into the IN\_BIAS pin, the power rails of TPS6521835 will be enabled at either  $V_{ULVO}$  or  $V_{ULVO} + V_{HYS}$ .

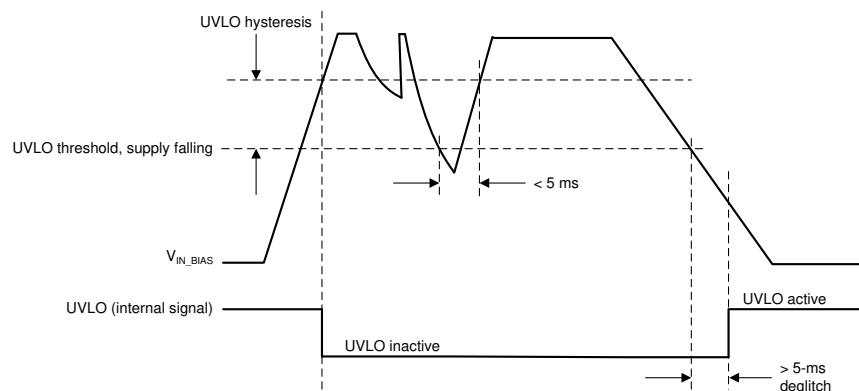
If the slew rate of the IN\_BIAS voltage is greater than 30 V/s, then TPS6521835 will power up at  $V_{ULVO}$ . Once the input voltage rises above this level, the input voltage may drop to the  $V_{UVLO}$  level before the PMIC shuts down. In this scenario, if the input voltage were to fall below  $V_{UVLO}$  but above 2.55 V, the input voltage would have to recover above  $V_{UVLO}$  in less than 5 ms for the device to remain active.

If the slew rate of the IN\_BIAS voltage is less than 30 V/s, then TPS6521835 will power up at  $V_{ULVO} + V_{HYS}$ . Once the input voltage rises above this level, the input voltage may drop to the  $V_{UVLO}$  level before the PMIC shuts down. In this scenario, if the input voltage were to fall below  $V_{UVLO}$  but above 2.5 V, the input voltage would have to recover above  $V_{UVLO} + V_{HYS}$  in less than 5 ms for the device to remain active.

In either slew rate scenario, if the input voltage were to fall below 2.5 V, the digital core is reset and all remaining power rails are shut down instantaneously and are pulled low to ground by their internal discharge circuitry (DCDC1-4 and LDO1).



**Figure 7-15. Definition of UVLO and Hysteresis, IN\_BIAS Slew Rate > 30 V/s**



**Figure 7-16. Definition of UVLO and Hysteresis, IN\_BIAS Slew Rate < 30 V/s**

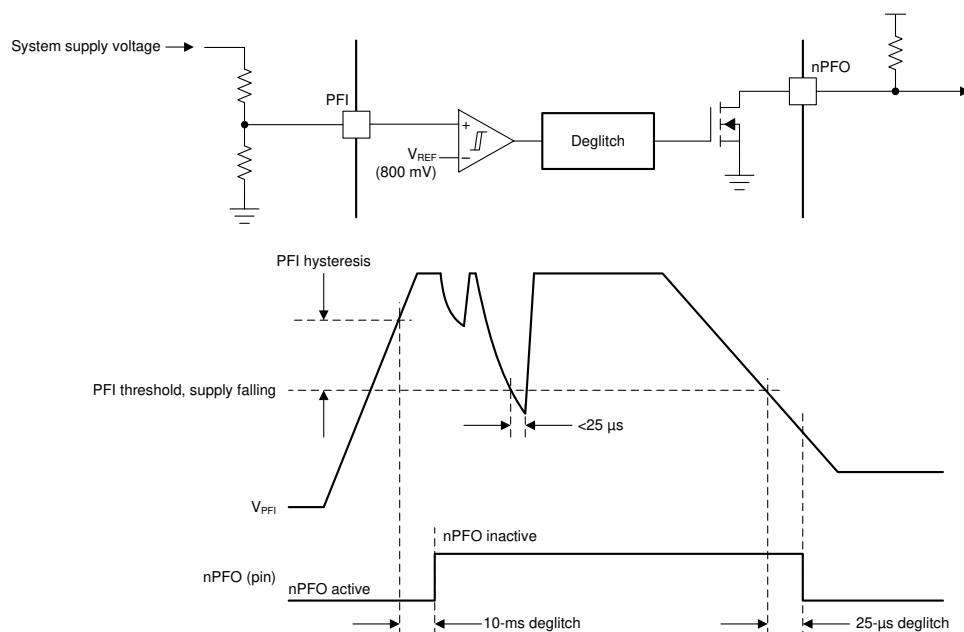
After the UVLO triggers, the internal LDO blocks current flow from its output capacitor back to the IN\_BIAS pin, allowing the digital core and the discharge circuits to remain powered for a limited amount of time to properly shut-down and discharge the output rails. The hold-up time is determined by the value of the capacitor connected to INT\_LDO. See [Section 7.3.1.6](#) for more details.

#### 7.3.1.11 Power-Fail Comparator

The power-fail comparator notifies the system host if the system supply voltage drops and the system is at risk of shutting down. The comparator has an internal 800-mV threshold and the trip-point is adjusted by an external resistor divider.

By default, the power-fail comparator has no impact on any of the power rails or load switches. Load switches are configured individually, to be disabled when the PFI comparator trips to shed system load and extend hold-up time as described in [Section 7.3.1.7](#). The power-fail comparator also triggers the power-down sequencer, such that all or selective rails power-down when the system voltage fails. To tie the power-fail comparator into the power-down sequence, the OFFnPFO bit in the CONTROL register must be set to 1.

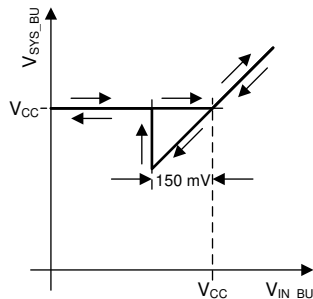
The power-fail comparator cannot be monitored by software, such that no interrupt or status bit is associated to this function.



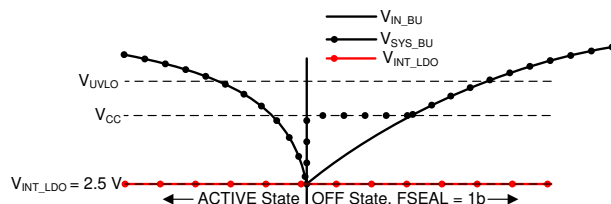
**Figure 7-17. Power-Fail Comparator Simplified Circuit and Timing Diagram**

### 7.3.1.12 Battery-Backup Supply Power-Path

DCDC5 and DCDC6 are supplied from either the CC (coin-cell battery) input or IN\_BU (main system supply). The power-path is designed to prioritize IN\_BU to maximize coin-cell battery life. Whenever the PMIC is powered-up (WAIT\_PWR\_EN, ACTIVE, SUSPEND, and RECOVERY state), the power-path is forced to select the IN\_BU input. In OFF mode the power-path selects the higher of the two inputs with a built-in hysteresis of 150 mV as shown in Figure 7-18.

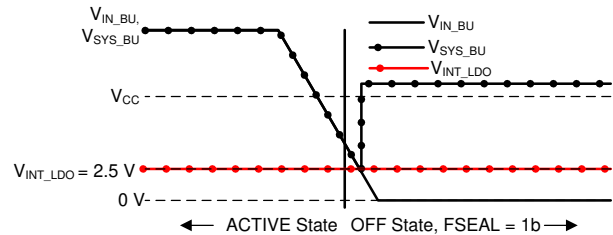


**Figure 7-18. Switching Behavior of the Battery-Backup-Supply Power-Path; Power-Path Hysteresis**



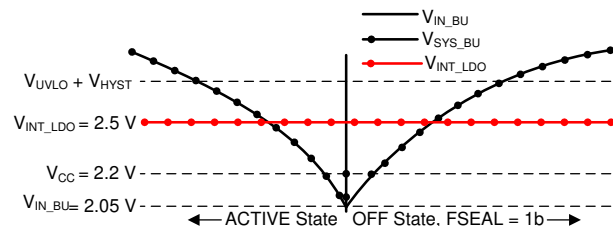
- A. System is supplied by Li-Ion battery with a fresh coin-cell backup battery.
- B. (VIN\_BIAS slow decay)

**Figure 7-20. Switching Behavior of the Battery-Backup-Supply Power-Path; Weakening Main Battery, Strong Coin-Cell**



- A. Main Supply is disconnected or decays rapidly.
- B. Rapid decay of VIN\_BIAS (preregulator)

**Figure 7-19. Switching Behavior of the Battery-Backup-Supply Power-Path; Main Power Supply Removal**



- A. System is supplied by Li-Ion battery with a weak coin-cell backup battery.
- B. VIN\_BIAS slow decay

**Figure 7-21. Switching Behavior of the Battery-Backup-Supply Power-Path; Weakening Main Battery, Weak Coin-Cell**

When  $V_{IN\_BIAS}$  drops below the UVLO threshold, the PMIC shuts down all rails and enters OFF mode. At this point the power-path selects the higher of the two input supplies. If the coin-cell battery is less than 150 mV above the UVLO threshold, SYS\_BU remains connected to IN\_BU (see Figure 7-20). If the coin-cell is >150 mV above the UVLO threshold, the power-path switches to the CC input as shown in Figure 7-21. With no load on the main supply, the input voltage may recover over time to a value greater than the coin-cell voltage and the power-path switches back to IN\_BU. This is a typical behavior in a Li-Ion battery powered system.

Depending on the system load,  $V_{IN\_BIAS}$  may drop below  $V_{INT\_LDO}$  before the power-down sequence is completed. In that case, INT\_LDO is turned OFF and the digital core is reset forcing the unit into OFF mode and the power-path switches to IN\_BU as shown in Figure 7-19.



### 7.3.1.13 DCDC3 and DCDC4 Power-Up Default Selection

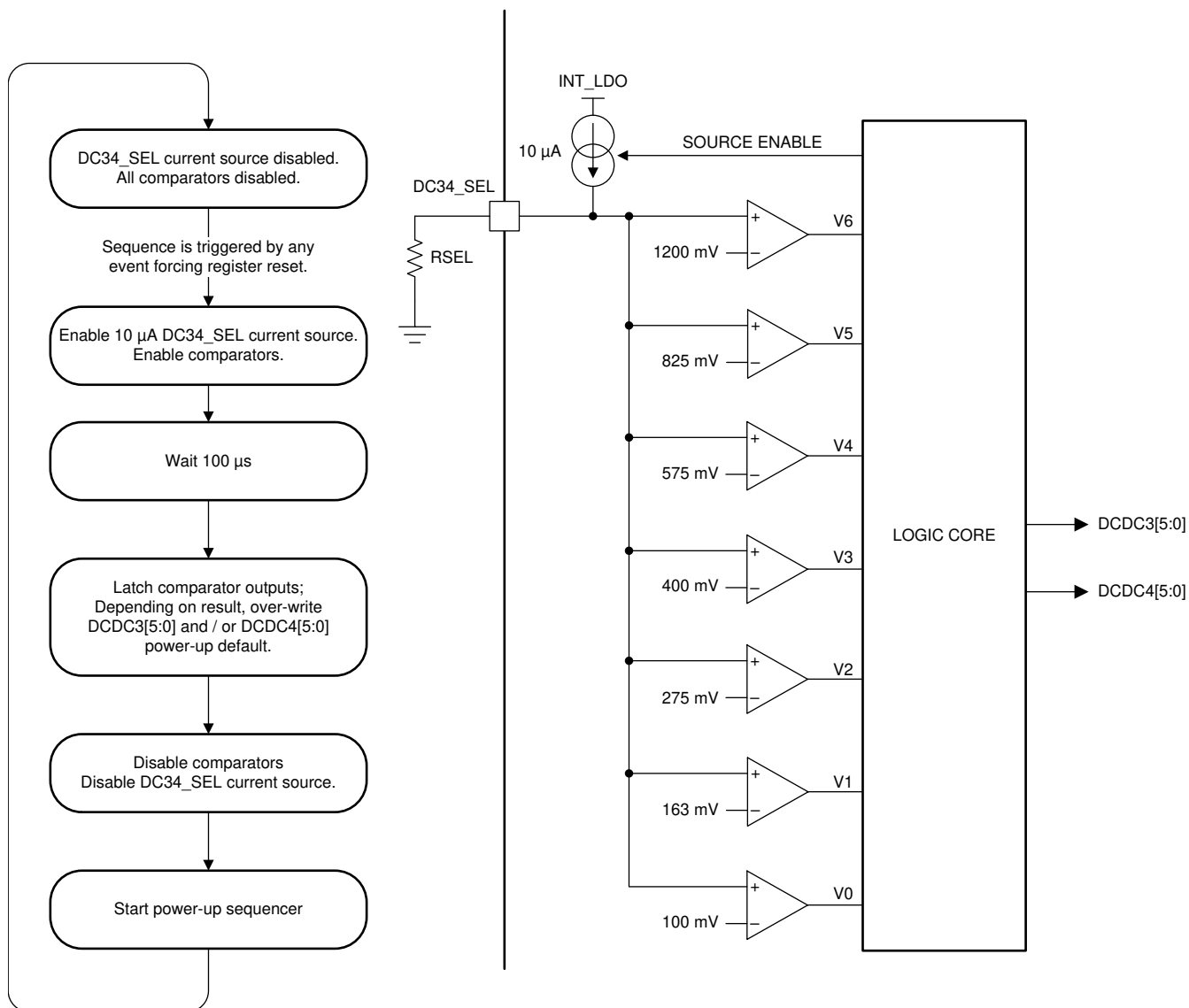


Figure 7-22. Left: Flow Chart for Selecting DCDC Power-Up Default Voltage Right: Comparator Circuit

Table 7-2. Power-Up Default Values of DCDC3 and DCDC4

| RSEL [KΩ] |      |                    | POWER-UP DEFAULT |               |
|-----------|------|--------------------|------------------|---------------|
| MIN       | TYP  | MAX                | DCDC3[5:0]       | DCDC4[5:0]    |
| 0         | 0    | 7.7                | 0xCh (1.2 V)     | 0x32h (3.3 V) |
| 11.3      | 12.1 | 13                 | 0x12 (1.35 V)    | 0x32h (3.3 V) |
| 18.1      | 20   | 22                 | 0x18 (1.5 V)     | 0x32h (3.3 V) |
| 30.9      | 31.6 | 32.3               | 0x1F (1.8 V)     | 0x32h (3.3 V) |
| 44.8      | 45.3 | 46.4               | 0x3D (3.3 V)     | 0x01 (1.2 V)  |
| 64.2      | 64.9 |                    | 0xCh (1.2 V))    | 0x07 (1.35 V) |
| 92.9      | 95.3 | 96.9               | 0xCh (1.2 V)     | 0x0D (1.5 V)  |
| 135.3     | 150  | Tied to<br>INT_LDO | 0xCh (1.2 V)     | 0x14 (1.8 V)  |

### 7.3.1.14 I/O Configuration

The device has two GPIOs and one GPO pin, which are configured as follows:

- GPIO1:
  - General-purpose, open-drain output is controlled by the GPO1 user bit or sequencer.
  - DDR3 reset input signal from SOC. The signal is either latched or passed-through to the GPO2 pin. See [Table 7-3](#) for details.
- GPO2:
  - General-purpose output is controlled by the GPO2 user bit.
  - DDR3 reset output signal. Signal is controlled by GPIO1 and PGOOD. See [Table 7-4](#) for details.
  - Output buffer is configured as open-drain or push-pull.
- GPIO3:
  - General-purpose, open-drain output id controlled by the GPO3 user bit or sequencer.
  - Reset input-signal for DCDC1 and DCDC2.

**Table 7-3. GPIO1 Configuration**

| IO1_SEL<br>(EEPROM) | GPO1<br>(USER BIT) | PGOOD<br>(PMIC SIGNAL) | GPIO1<br>(I/O PIN) | COMMENTS                                                                                                                                                                                          |
|---------------------|--------------------|------------------------|--------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 0                   | 0                  | X                      | 0                  | Open-drain output, driving low                                                                                                                                                                    |
| 0                   | 1                  | X                      | HiZ                | Open-drain output, HiZ                                                                                                                                                                            |
| 1                   | X                  | 0                      | X                  | Pin is configured as input and intended as DDR RESET signal. Coming out of POR, GPO2 is driven low. Otherwise, GPO2 status is latched at falling edge of PGOOD. See <a href="#">Figure 7-25</a> . |
| 1                   | X                  | 1                      | 0                  | Pin is configured as input and intended as DDR RESET signal. GPO2 is driven low.                                                                                                                  |
| 1                   | X                  | 1                      | 1                  | Pin is configured as input and intended as DDR RESET signal. GPO2 is driven high.                                                                                                                 |

**Table 7-4. GPO2 Configuration**

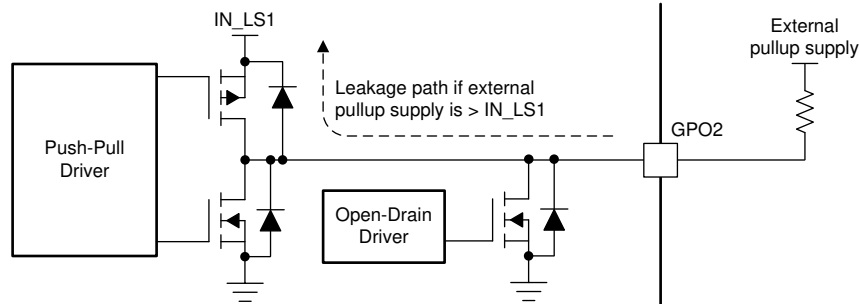
| IO1_SEL<br>(EEPROM) | GPO2_BUF<br>(EEPROM) | GPO2<br>(USER BIT) | COMMENTS                                                             |
|---------------------|----------------------|--------------------|----------------------------------------------------------------------|
| 0                   | 0                    | 0                  | GPO2 is open drain output controlled by GPO2 user bit (driving low). |
| 0                   | 0                    | 1                  | GPO2 is open drain output controlled by GPO2 user bit (HiZ).         |
| 0                   | 1                    | 0                  | GPO2 is push-pull output controlled by GPO2 user bit (driving low).  |
| 0                   | 1                    | 1                  | GPO2 is push-pull output controlled by GPO2 user bit (driving high). |
| 1                   | 0                    | X                  | GPO2 is open drain output controlled by GPIO1 and PGOOD.             |
| 1                   | 1                    | X                  | GPO2 is push-pull output controlled by GPIO1 and PGOOD.              |

**Table 7-5. GPIO3 Configuration**

| DC12_RST<br>(EEPROM) | GPO3<br>(USER BIT) | GPIO3<br>(I/O PIN) | COMMENTS                                                                                                              |
|----------------------|--------------------|--------------------|-----------------------------------------------------------------------------------------------------------------------|
| 0                    | 0                  | 0                  | Open-drain output, driving low                                                                                        |
| 0                    | 1                  | HiZ                | Open-drain output, HiZ                                                                                                |
| 1                    | X                  | Active low         | GPIO3 is DCDC1 and DCDC2 reset input signal to PMIC (active low). See <a href="#">Section 7.3.1.14.2</a> for details. |

#### 7.3.1.14.1 Configuring GPO2 as Open-Drain Output

GPO2 may be configured as open-drain or push-pull output. The supply for the push-pull driver is internally connected to the IN\_LS1 input pin, whereas an external pull-up resistor and supply are required in the open-drain configuration. Because of the internal connection to IN\_LS1, the external pull-up supply must not exceed the voltage on the IN\_LS1 pin, otherwise leakage current may be observed from GPO2 to IN\_LS1 as shown in [Figure 7-23](#).



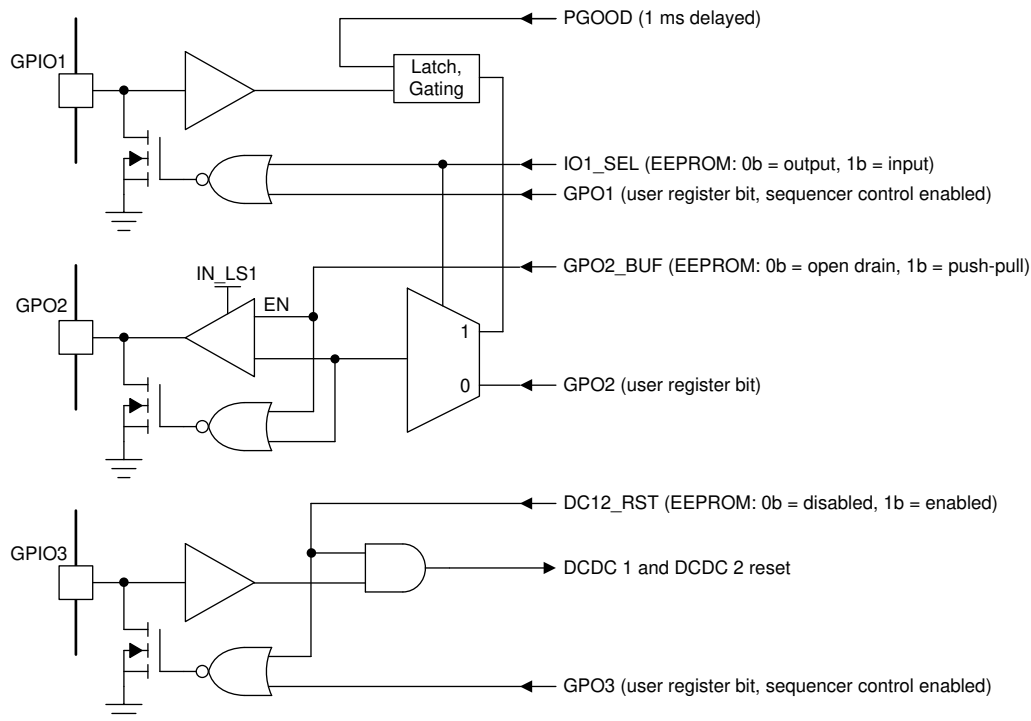
**Figure 7-23. GPO2 as Open-Drain Output**

**Note**

When configured as open-drain output, the external pull-up supply must not exceed the voltage level on IN\_LS1 pin.

**7.3.1.14.2 Using GPIO3 as Reset Signal to DCDC1 and DCDC2**

The GPIO3 is an edge-sensitive reset input to the PMIC, when the DC12\_RST bit set to 1. The reset signal affects DCDC1 and DCDC2 only, so that only those two registers are reset to the power-up default whenever GPIO3 input transitions from high to low, while all other registers maintain their current values. DCDC1 and DCDC2 transition back to the default value following the SLEW settings, and are not power cycled. This function recovers the processor from reset events while in low-power mode.



**Figure 7-24. I/O Pin Logic**

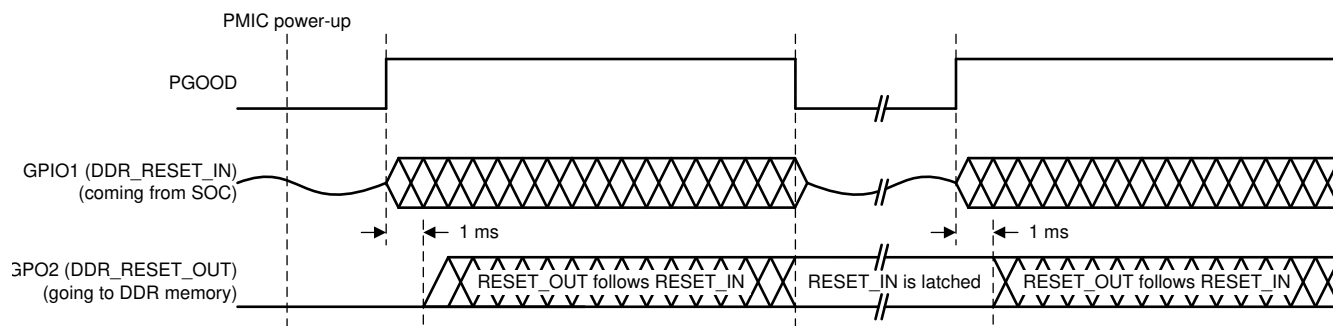


Figure 7-25. DDR3 Reset Timing Diagram

**Note**

GPIO must be configured as input (IO1\_SEL = 1b). GPIO2 is automatically configured as output.

**7.3.1.15 Push Button Input (PB)**

The PB pin is a CMOS-type input used to power-up the PMIC. Typically, the PB pin is connected to a momentary switch to ground and an external pullup resistor. The power-up sequence is triggered if the PB input is held low for 600 ms.

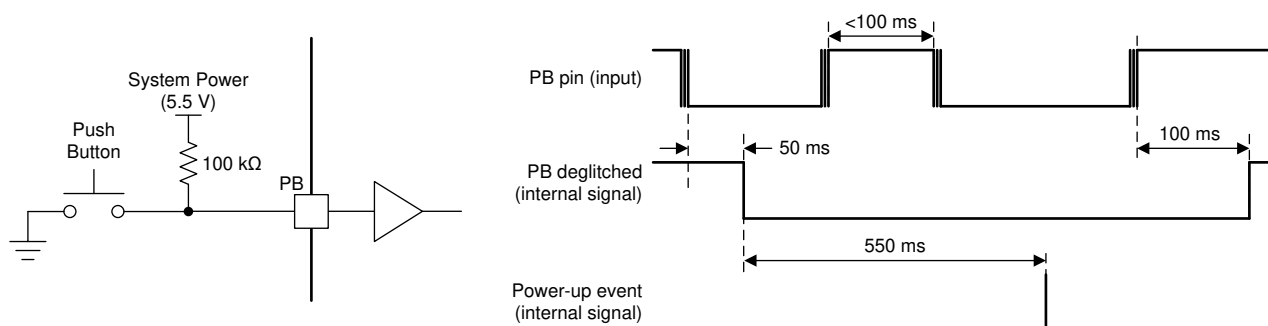
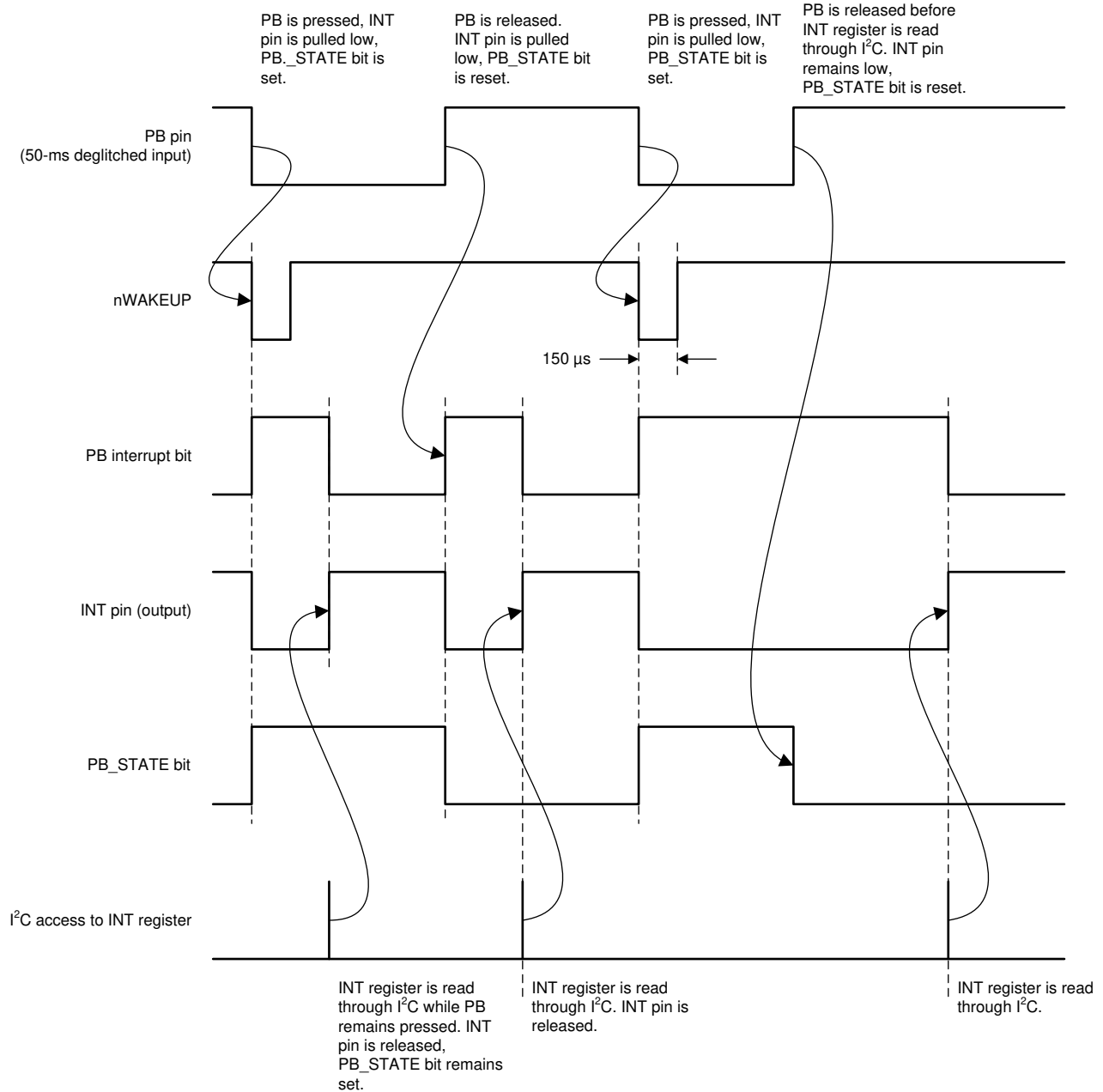


Figure 7-26. Left: Typical PB Input Circuit Right: Push-Button Input (PB) Deglitch and Power-Up Timing

In ACTIVE mode, the TPS6521835 monitors the PB input and issues an interrupt when the pin status changes, such as when it drops below or rises above the PB input-low or input-high thresholds. The interrupt is masked by the PBM bit in the INT\_MASK1 register.



**Figure 7-27. PB Input-Low or Input-High Thresholds**

**Note**

Interrupts are issued whenever the PB pin status changes. The PB\_STATE bit reflects the current status of the PB input. nWAKEUP is pulled low for 150  $\mu$ s on every falling edge of PB.

### 7.3.1.15.1 Signaling PB-Low Event on the nWAKEUP Pin

In ACTIVE state, the nWAKEUP pin is pulled low for five 32-kHz clock cycles (approximately 150  $\mu$ s) whenever a falling edge on the PB input is detected. This allows the host processor to wakeup from DEEP SLEEP mode of operation. It is recommended to pull-up the nWAKEUP pin to DCDC6 output through a 1-M $\Omega$  resistor.

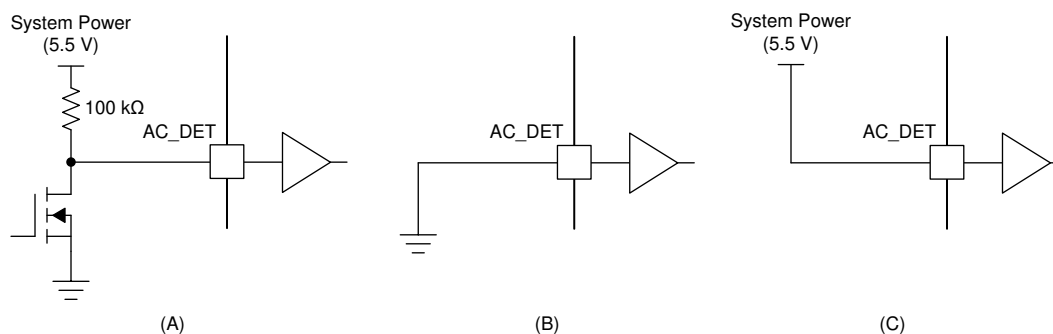
### 7.3.1.15.2 Push Button Reset

If the PB input is pulled low for 8 s (15 s if TRST = 1b) or longer, then all rails except for DCDC5 and DCDC6 are disabled, and the device enters the RECOVERY state. The device powers up automatically after the 500 ms power-down sequence is complete, regardless of the state of the PB input. Holding the PB pin low for 8 s (15 s if TRST = 1b), only turns off the device temporarily and forces a system restart, and is not a power-down function. If the PB is held low continuously, the device power-cycles in 8-s and 15-s intervals.

### 7.3.1.16 AC\_DET Input (AC\_DET)

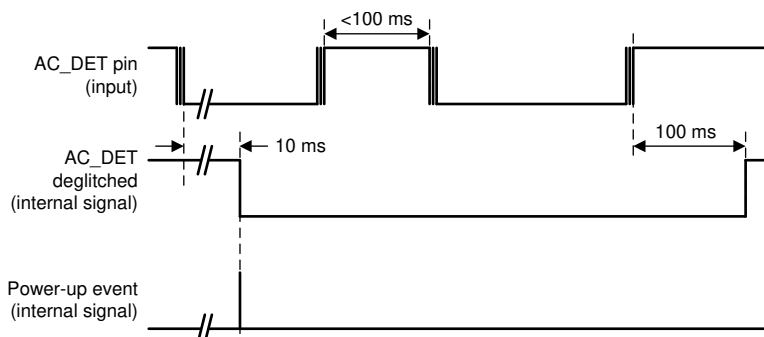
The AC\_DET pin is a CMOS-type input used in three different ways to control the power-up of the PMIC:

- In a battery operated system, AC\_DET is typically connected to an external battery charger with an open-drain power-good output pulled low when a valid charger supply is connected to the system. A falling edge on the AC\_DET pin causes the PMIC to power up.
- In a non-portable system, the AC\_DET pin may be shorted to ground and the device powers up whenever system power is applied to the chip.
- If none of the above behaviors are desired, AC\_DET may be tied to system power (IN\_BIAS). Power-up is then controlled through the push-button input or PWR\_EN input.



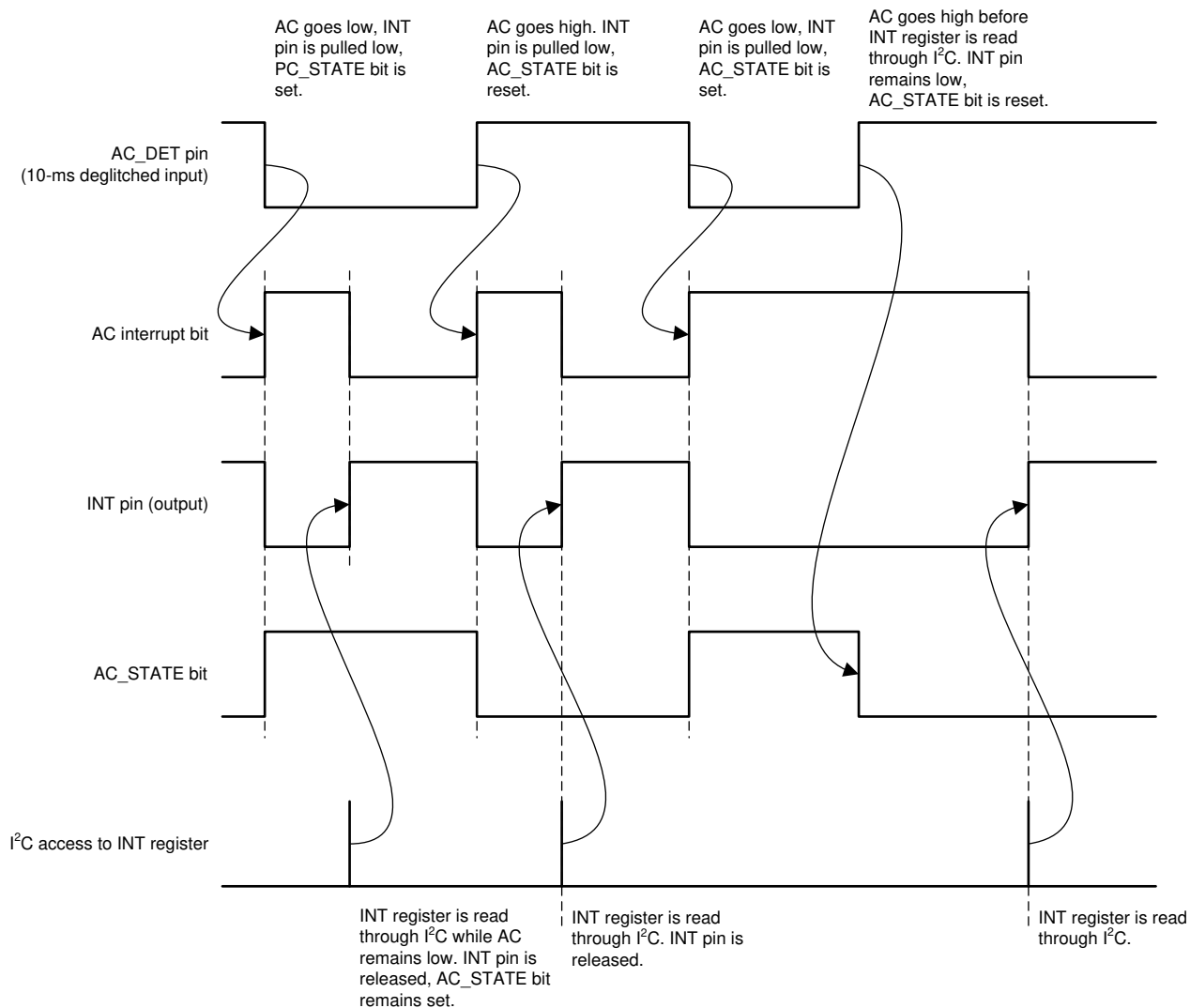
- A. Portable Systems  
B. Non-portable Systems  
C. Disabled

**Figure 7-28. AC\_DET Pin Configurations**



**Figure 7-29. AC\_DET Input Deglitch and Power-Up Timing (Portable Systems)**

In ACTIVE state, the TPS6521835 monitors the AC\_DET input and issues an interrupt when the pin status changes, such as when it drops below or rises above the AC\_DET input-low or input-high thresholds. The interrupt is masked by the ACM bit in the INT\_MASK1 register.



**Figure 7-30. AC\_STATE Pin**

#### Note

Interrupts are issued whenever the AC\_DET pin status changes. The AC\_STATE bit reflects the current status of the AC\_DET input.

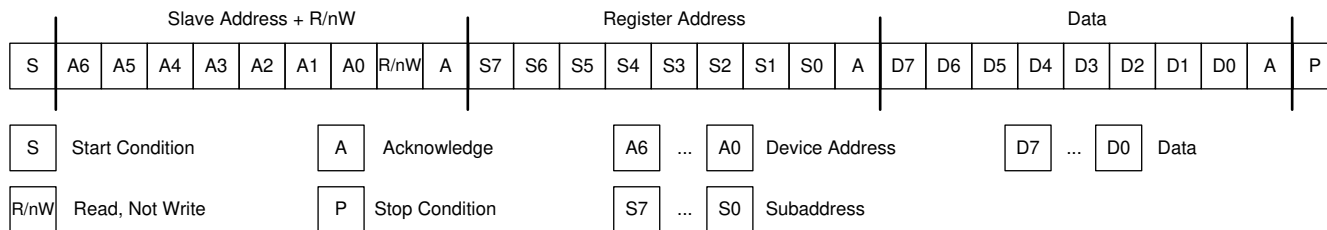
#### 7.3.1.17 Interrupt Pin (INT)

The interrupt pin signals any event or fault condition to the host processor. Whenever a fault or event occurs in the device, the corresponding interrupt bit is set in the INT register, and the open-drain output is pulled low. The INT pin is released (returns to Hi-Z state) and fault bits are cleared when the host reads the INT register. If a failure persists, the corresponding INT bit remains set and the INT pin is pulled low again after a maximum of 32  $\mu$ s.

The MASK register masks events from generating interrupts. The MASK settings affect the INT pin only, and have no impact on the protection and monitor circuits.

### 7.3.1.18 I<sup>2</sup>C Bus Operation

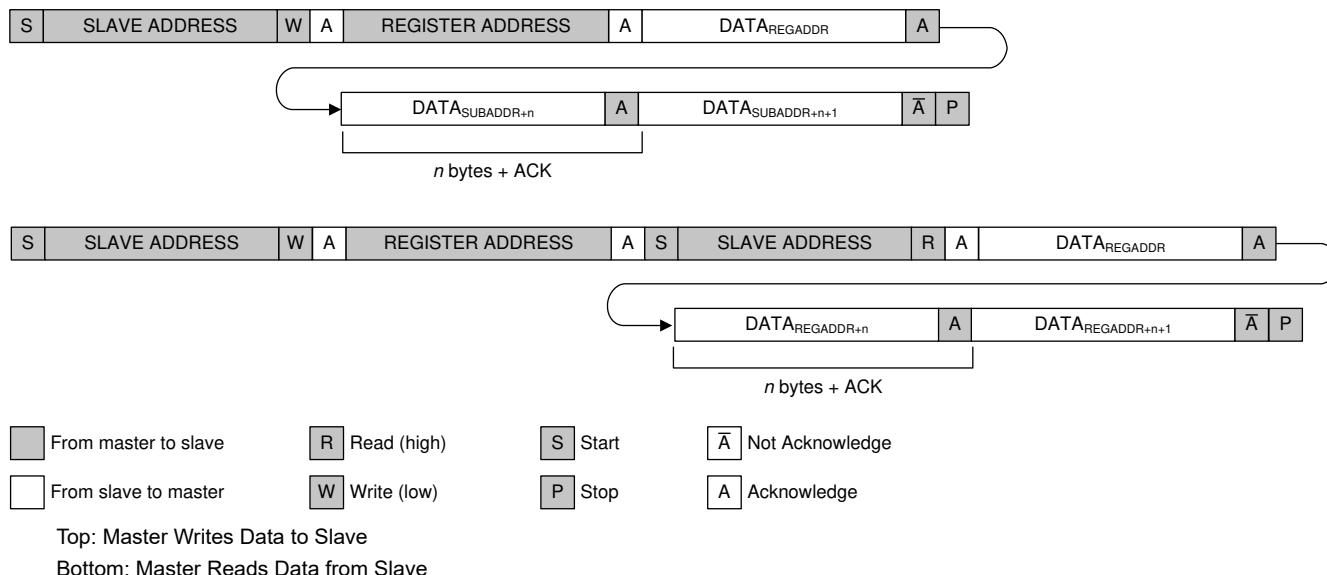
The TPS6521835 hosts a slave I<sup>2</sup>C interface (address 0x24) that supports data rates up to 400 kbps, auto-increment addressing.<sup>1</sup>



**Figure 7-31. Subaddress in I<sup>2</sup>C Transmission**

The I<sup>2</sup>C bus is a communications link between a controller and a series of slave terminals. The link is established using a two-wired bus consisting of a serial clock signal (SCL) and a serial data signal (SDA). The serial clock is sourced from the controller in all cases where the serial data line is bi-directional for data communication between the controller and the slave terminals. Each device has an open drain output to transmit data on the serial data line. An external pullup resistor must be placed on the serial data line to pull the drain output high during data transmission.

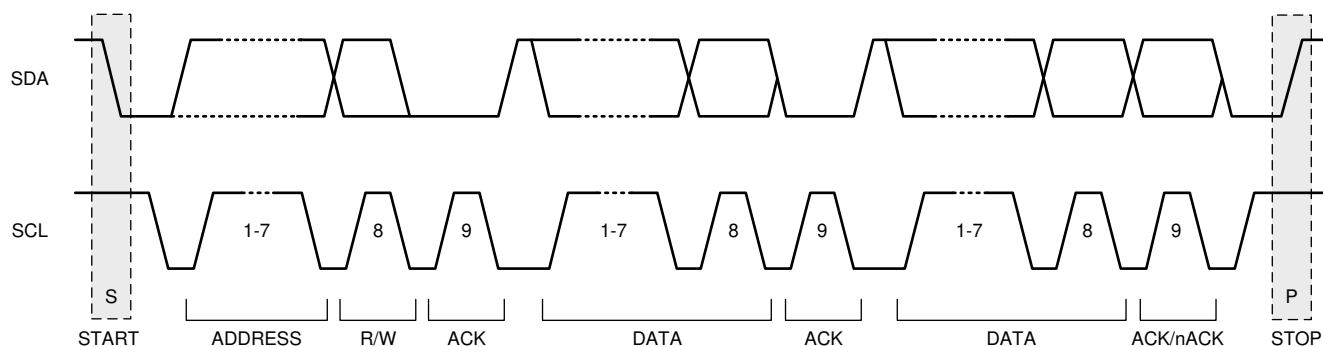
Data transmission initiates with a start bit from the controller as shown in Figure 7-33. The start condition is recognized when the SDA line transitions from high to low during the high portion of the SCL signal. Upon reception of a start bit, the device receives serial data on the SDA input and checks for valid address and control information. If the appropriate slave address is set for the device, the device issues an acknowledge pulse and prepares to receive register address and data. Data transmission is completed by either the reception of a stop condition or the reception of the data word sent to the device. A stop condition is recognized as a low to high transition of the SDA input during the high portion of the SCL signal. All other transitions of the SDA line must occur during the low portion of the SCL signal. An acknowledge issues after the reception of valid slave address, register-address, and data words. The I<sup>2</sup>C interfaces an auto-sequence through the register addresses, so that multiple data words can be sent for a given I<sup>2</sup>C transmission. Reference Figure 7-32 and Figure 7-33 for details.



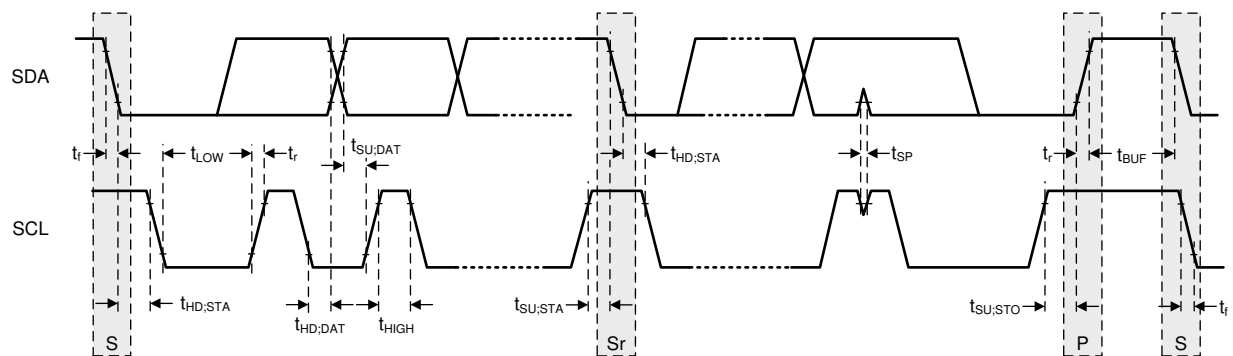
**Figure 7-32. I<sup>2</sup>C Data Protocol**

<sup>1</sup> Note: The SCL duty cycle at 400 kHz must be >40%.





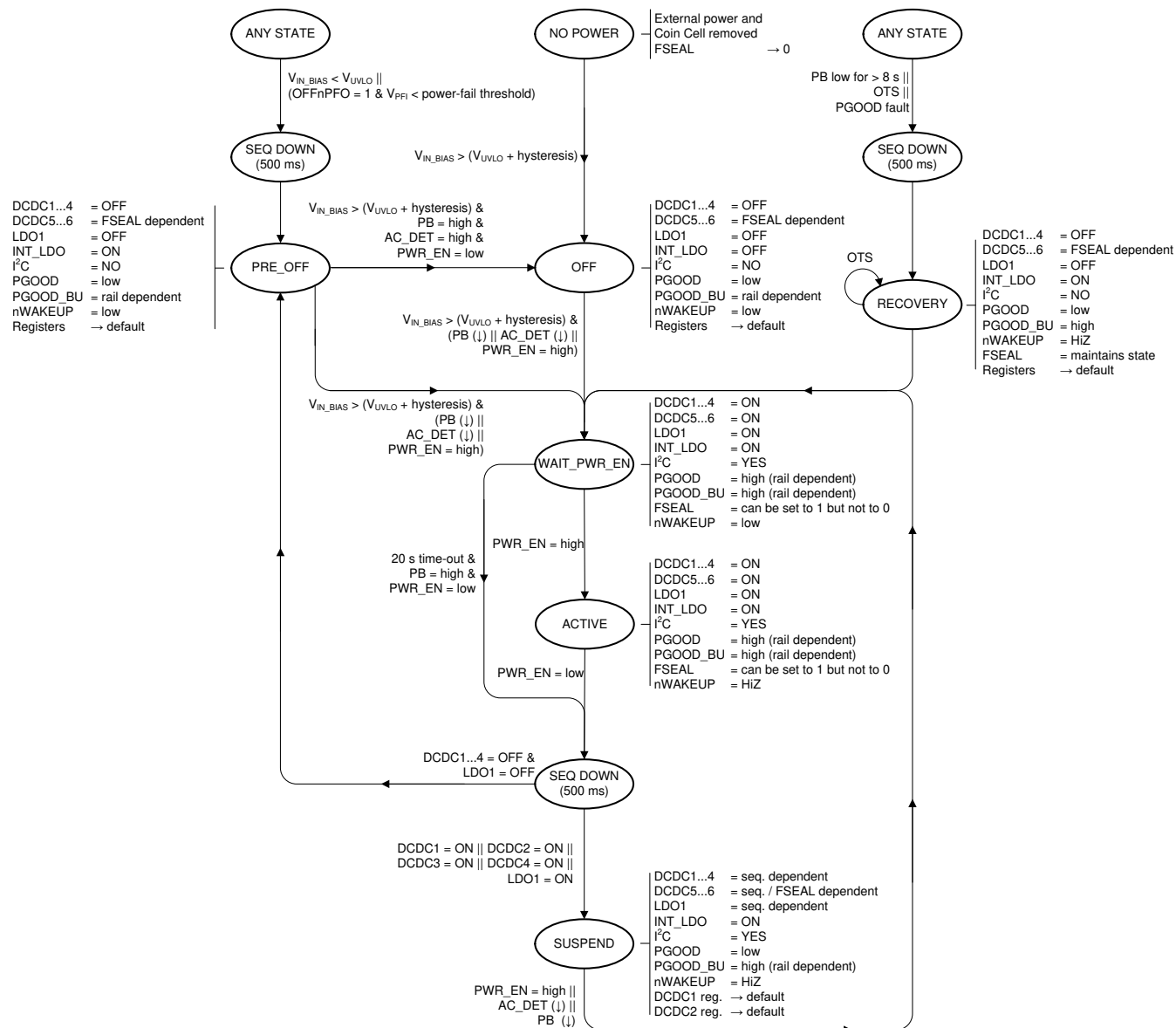
**Figure 7-33. I²C Protocol and Transmission Timing I²C Start Stop and Acknowledge Protocol**



**Figure 7-34. I²C Protocol and Transmission Timing I²C Data Transmission Timing**

## 7.4 Device Functional Modes

### 7.4.1 Modes of Operation



PB (↓) has 50 ms debounce.

AC\_DET (↓) has 10 ms debounce.

(↓) = denotes falling edge of signal.

**Figure 7-35. Modes of Operation Diagram**

### 7.4.2 OFF

In OFF mode, the PMIC is completely shut down with the exception of a few circuits to monitor the AC\_DET, PWR\_EN, and PB input. All power rails are turned off and the registers are reset to their default values. The I<sup>2</sup>C communication interface is turned off. This is the lowest-power mode of operation. To exit OFF mode V<sub>IN\_BIAS</sub> must exceed the UVLO threshold and one of the following wake-up events must occur:

- The PB input is pulled low.
- THE AC\_DET input is pulled low.
- The PWR\_EN input is pulled high.

To enter the OFF state, ensure that all power rails are assigned to the sequencer, then pull the PWR\_EN pin low. Additionally, if the OFFnPFO bit is set to 1b and the PFI input falls below the power fail threshold the device transitions to the OFF state. If the freshness seal is broken, DCDC5 and DCDC6 remains on in the OFF state. If a PGOOD or OTS fault occurs while in the ACTIVE state, TPS6521835 will transition to the RESET state.

### 7.4.3 ACTIVE

This is the typical mode of operation when the system is up and running. All DCDC converters, LDOs, and load switches are operational and can be controlled through the I<sup>2</sup>C interface. After a wake-up event, the PMIC enables all rails controlled by the sequencer and pulls the nWAKEUP pin low to signal the event to the host processor. The device only enters the ACTIVE state if the host asserts the PWR\_EN pin within 20 s after the wake-up event. Otherwise it will enter the OFF state. The nWAKEUP pin returns to HiZ mode after the PWR\_EN pin is asserted. The ACTIVE state can also be directly entered from the SUSPEND state by pulling the PWR\_EN pin high. See the SUSPEND state description for details. To exit the ACTIVE mode, the PWR\_EN pin must be pulled low.

### 7.4.4 SUSPEND

The SUSPEND state is a low-power mode of operation intended to support system standby. Typically all power rails are turned off with the exception of any rail with an SEQ register set to 0h. DCDC5 and DCDC6 also remain enabled if the freshness seal is broken. To enter the SUSPEND state, pull the PWR\_EN pin low. All power rails controlled by the power-down sequencer are shut down, and after 500 ms the device enters the SUSPEND state. All rails not controlled by the power-down sequencer will maintain its state. Note: all register values are reset as the device enters the SUSPEND state. The device enters the ACTIVE state after it detects a wake-up event as described in the previous sections.

### 7.4.5 RESET

The TPS6521835 can be reset by holding the PB pin low for more than 8 or 15 s, depending on the value of the TRST bit. All rails are shut down by the sequencer and all register values reset to their default values. Rails not controlled by the sequencer are shut down additionally. Note: the RESET function power-cycles the device and only temporarily shuts down the output rails. Resetting the device does not lead to an OFF state. If the PB\_IN pin is kept low for an extended amount of time, the device continues to cycle between the ACTIVE and RESET state, entering the RESET every 8 or 15 s.

The device is also reset if a PGOOD or OTS fault occurs. The TPS6521835 remains in the RECOVERY state until the fault is removed, at which time it transitions back to the ACTIVE state.

## 7.5 Register Maps

### 7.5.1 Password Protection

Registers 0x11 through 0x26 are protected against accidental write by a 8-bit password. The password must be written prior to writing to a protected register and automatically resets to 0x00 after the next I<sup>2</sup>C transaction, regardless of the register accessed or transaction type (read or write). The password is required for write access only and is not required for read access.

To write to a protected register:

1. Write the address of the destination register, XORed with the protection password (0x7D), to the PASSWORD register (0x10).
2. Write the data to the password protected register.
3. If the content of the PASSWORD register is XORed, with an address send that matches 0x7D, then the data transfers to the protected register. Otherwise, the transaction is ignored. In either case the PASSWORD register resets to 0x00 after the transaction.

The cycle must be repeated for any other register that is Level1 write protected.

### 7.5.2 Freshness Seal (FSEAL) Bit

The FSEAL (freshness seal) bit prevents accidental shut-down of the always-on supplies, DCDC5 and DCDC6. The FSEAL bit exists in a default state of 0b, and can be set to 1b and reset to 0b once for factory testing. The second time the bit is set to 1b, it remains 1b and cannot reset again under software control. Coin-cell battery and main supply must be disconnected from the device to reset the FSEAL bit again. With the FSEAL bit set to 1b, DCDC5 and DCDC6 are forced ON regardless of the state of the DC5\_EN and DC6\_EN bit, and the rails do not turn off when the device enters the OFF state.

A consecutive write of [0xB1, 0xFE, and 0xA3] to the password register sets the FSEAL bit to 1b. The three bytes must be written consecutively for the sequence to be valid. No other read or write transactions are allowed between the three bytes, or the sequence is invalid. After a valid sequence, the FSEAL bit in the STATUS register reflects the new setting.

After setting the FSEAL bit, the device can enter the OFF state or any other mode of operation without affecting the state of the FSEAL bit, provided the coin-cell supply remains connected to the chip.

A second write of [0xB1, 0xFE, and 0xA3] to the password register resets the FSEAL bit to 0b. The three bytes must be written consecutively for the sequence to be valid.

A third write of [0xB1, 0xFE, and 0xA3] to the password register sets the FSEAL bit to 1b and locks it into this state for as long as the coin-cell supply (CC) remains connected to the device.

### 7.5.3 FLAG Register

The FLAG register contains a bit for each power rail and GPO to keep track of the enable state of the rails while the system is suspended. The following rules apply to the FLAG register:

- The power-up default value for any flag bit is 0.
- Flag bits are read-only and cannot be written to.
- Upon entering a SUSPEND state, the flag bits are set to same value as their corresponding ENABLE bits. Rails and GPOs enabled in a SUSPEND state have flag bits set to 1, while all other flag bits are set to 0. Flag bits are not updated while in the SUSPEND state or when exiting the SUSPEND state.
- The FLAG register is static in WAIT\_PWR\_EN and ACTIVE state. The FLAG register reflects the enable state of DCDC1, DCDC2, DCDC3, DCDC4, and LDO1; and, reflects the enable state of GPO1, GPO2, and GPO3 during the last SUSPEND state.

The host processor reads the FLAG register to determine if the system powered up from the OFF or SUSPEND state. In the SUSPEND state, typically the DDR memory is kept in self refresh mode and therefore the DC3\_FLG or DC4\_FLG bits are set.

## 7.5.4 TPS6521835 Registers

Table 7-6 lists the memory-mapped registers for the TPS6521835. All register offset addresses not listed in Table 7-6 should be considered as reserved locations and the register contents should not be modified.

**Table 7-6. TPS6521835 Registers**

| SUBADDRESS | ACRONYM   | REGISTER NAME     | R/W | PASSWORD PROTECTED | SECTION                        |
|------------|-----------|-------------------|-----|--------------------|--------------------------------|
| 0x00       | CHIPID    | CHIP ID           | R   | No                 | <a href="#">Section 7.5.5</a>  |
| 0x01       | INT1      | INTERRUPT 1       | R   | No                 | <a href="#">Section 7.5.6</a>  |
| 0x02       | INT2      | INTERRUPT 2       | R   | No                 | <a href="#">Section 7.5.7</a>  |
| 0x03       | INT_MASK1 | INTERRUPT MASK 1  | R/W | No                 | <a href="#">Section 7.5.8</a>  |
| 0x04       | INT_MASK2 | INTERRUPT MASK 2  | R/W | No                 | <a href="#">Section 7.5.9</a>  |
| 0x05       | STATUS    | STATUS            | R   | No                 | <a href="#">Section 7.5.10</a> |
| 0x06       | CONTROL   | CONTROL           | R/W | No                 | <a href="#">Section 7.5.11</a> |
| 0x07       | FLAG      | FLAG              | R   | No                 | <a href="#">Section 7.5.12</a> |
| 0x10       | PASSWORD  | PASSWORD          | R/W | No                 | <a href="#">Section 7.5.13</a> |
| 0x11       | ENABLE1   | ENABLE 1          | R/W | Yes                | <a href="#">Section 7.5.14</a> |
| 0x12       | ENABLE2   | ENABLE 2          | R/W | Yes                | <a href="#">Section 7.5.15</a> |
| 0x13       | CONFIG1   | CONFIGURATION 1   | R/W | Yes                | <a href="#">Section 7.5.16</a> |
| 0x14       | CONFIG2   | CONFIGURATION 2   | R/W | Yes                | <a href="#">Section 7.5.17</a> |
| 0x15       | CONFIG3   | CONFIGURATION 3   | R/W | Yes                | <a href="#">Section 7.5.18</a> |
| 0x16       | DCDC1     | DCDC1 CONTROL     | R/W | Yes                | <a href="#">Section 7.5.19</a> |
| 0x17       | DCDC2     | DCDC2 CONTROL     | R/W | Yes                | <a href="#">Section 7.5.20</a> |
| 0x18       | DCDC3     | DCDC3 CONTROL     | R/W | Yes                | <a href="#">Section 7.5.21</a> |
| 0x19       | DCDC4     | DCDC4 CONTROL     | R/W | Yes                | <a href="#">Section 7.5.22</a> |
| 0x1A       | SLEW      | SLEW RATE CONTROL | R/W | Yes                | <a href="#">Section 7.5.23</a> |
| 0x1B       | LDO1      | LDO1 CONTROL      | R/W | Yes                | <a href="#">Section 7.5.24</a> |
| 0x20       | SEQ1      | SEQUENCER 1       | R/W | Yes                | <a href="#">Section 7.5.25</a> |
| 0x21       | SEQ2      | SEQUENCER 2       | R/W | Yes                | <a href="#">Section 7.5.26</a> |
| 0x22       | SEQ3      | SEQUENCER 3       | R/W | Yes                | <a href="#">Section 7.5.27</a> |
| 0x23       | SEQ4      | SEQUENCER 4       | R/W | Yes                | <a href="#">Section 7.5.28</a> |
| 0x24       | SEQ5      | SEQUENCER 5       | R/W | Yes                | <a href="#">Section 7.5.29</a> |
| 0x25       | SEQ6      | SEQUENCER 6       | R/W | Yes                | <a href="#">Section 7.5.30</a> |
| 0x26       | SEQ7      | SEQUENCER 7       | R/W | Yes                | <a href="#">Section 7.5.31</a> |

Table 7-7 explains the common abbreviations used in this section.

**Table 7-7. Common Abbreviations**

| Abbreviation | Description                                    |
|--------------|------------------------------------------------|
| R            | Read                                           |
| W            | Write                                          |
| R/W          | Read and write capable                         |
| h            | Hexadecimal notation of a group of bits        |
| b            | Hexadecimal notation of a bit or group of bits |
| X            | Do not care reset value                        |

### 7.5.5 CHIPID Register (subaddress = 0x00) [reset = 0x35]

CHIPID is shown in [Figure 7-31](#) and described in [Table 7-8](#).

Return to [Table 7-6](#).

**Figure 7-31. CHIPID Register**

| 7    | 6 | 5 | 4 | 3 | 2    | 1 | 0 |
|------|---|---|---|---|------|---|---|
| CHIP |   |   |   |   | REV  |   |   |
| R-6h |   |   |   |   | R-5h |   |   |

**Table 7-8. CHIPID Register Field Descriptions**

| Bit | Field | Type | Reset | Description                                                                                                                                                                                                                                        |
|-----|-------|------|-------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7-3 | CHIP  | R    | 6h    | Chip ID:<br>0h = TPS65218<br>1h = Future use<br>2h = TPS6521815<br>3h = Future use<br>4h = TPS6521825<br>5h = Future use<br>6h = TPS6521835<br>7h = Future use<br>8h = TPS6521845<br>9h = Future use<br>Ah = TPS6521855<br>...<br>1Fh = Future use |
| 2-0 | REV   | R    | 5h    | Revision code:<br>0h = Revision 1.0<br>1h = Revision 1.1<br>2h = Revision 2.0<br>3h = Revision 2.1<br>4h = Revision 3.0<br>5h = Revision 4.0 (D0)<br>6h = Future use<br>7h = Future use                                                            |

### 7.5.6 INT1 Register (subaddress = 0x01) [reset = 0x00]

INT1 is shown in [Figure 7-32](#) and described in [Table 7-9](#).

Return to [Table 7-6](#).

**Figure 7-32. INT1 Register**

| 7        | 6 | 5    | 4    | 3    | 2    | 1      | 0    |
|----------|---|------|------|------|------|--------|------|
| RESERVED |   | VPRG | AC   | PB   | HOT  | CC_AQC | PRGC |
| R-00b    |   | R-0b | R-0b | R-0b | R-0b | R-0b   | R-0b |

**Table 7-9. INT1 Register Field Descriptions**

| Bit | Field    | Type | Reset | Description                                                                                                                       |
|-----|----------|------|-------|-----------------------------------------------------------------------------------------------------------------------------------|
| 7-6 | RESERVED | R    | 00b   |                                                                                                                                   |
| 5   | VPRG     | R    | 0b    | Programming voltage interrupt:<br>0b = No significance.<br>1b = Input voltage is too low for programming power-up default values. |

**Table 7-9. INT1 Register Field Descriptions (continued)**

| Bit | Field  | Type | Reset | Description                                                                                                                                                                                              |
|-----|--------|------|-------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 4   | AC     | R    | 0b    | AC_DET pin status change interrupt. Note: Status information is available in STATUS register.<br>0b = No change in status.<br>1b = AC_DET status change (AC_DET pin changed high to low or low to high). |
| 3   | PB     | R    | 0b    | Push-button status change interrupt. Note: Status information is available in STATUS register<br>0b = No change in status.<br>1b = Push-button status change (PB changed high to low or low to high).    |
| 2   | HOT    | R    | 0b    | Thermal shutdown early warning:<br>0b = Chip temperature is below HOT threshold.<br>1b = Chip temperature exceeds HOT threshold.                                                                         |
| 1   | CC_AQC | R    | 0b    | Coin cell battery voltage acquisition complete interrupt:<br>0b = No significance.<br>1b = Backup battery status comparators have settled and results are available in STATUS register.                  |
| 0   | PRGC   | R    | 0b    | EEPROM programming complete interrupt:<br>0b = No significance.<br>1b = Programming of power-up default settings has completed successfully.                                                             |

### 7.5.7 INT2 Register (subaddress = 0x02) [reset = 0x00]

INT2 is shown in [Figure 7-33](#) and described in [Table 7-10](#).

Return to [Table 7-6](#).

**Figure 7-33. INT2 Register**

| 7        | 6 | 5     | 4     | 3     | 2     | 1     | 0     |
|----------|---|-------|-------|-------|-------|-------|-------|
| RESERVED |   | LS3_F | LS2_F | LS1_F | LS3_I | LS2_I | LS1_I |
| R-00b    |   | R-0b  | R-0b  | R-0b  | R-0b  | R-0b  | R-0b  |

**Table 7-10. INT2 Register Field Descriptions**

| Bit | Field    | Type | Reset | Description                                                                                                                                                                                                         |
|-----|----------|------|-------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7-6 | RESERVED | R    | 00b   |                                                                                                                                                                                                                     |
| 5   | LS3_F    | R    | 0b    | Load switch 3 fault interrupt:<br>0b = No fault. Switch is working normally.<br>1b = Load switch exceeded operating temperature limit and is temporarily disabled.                                                  |
| 4   | LS2_F    | R    | 0b    | Load switch 2 fault interrupt:<br>0b = No fault. Switch is working normally.<br>1b = Load switch exceeded operating temperature limit or input voltage dropped below minimum value. Switch is temporarily disabled. |
| 3   | LS1_F    | R    | 0b    | Load switch 1 fault interrupt:<br>0b = No fault. Switch is working normally.<br>1b = Load switch exceeded operating temperature limit and is temporarily disabled.                                                  |

**Table 7-10. INT2 Register Field Descriptions (continued)**

| Bit | Field | Type | Reset | Description                                                                                                                                                                                                 |
|-----|-------|------|-------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 2   | LS3_I | R    | 0b    | Load switch 3 current-limit interrupt:<br>0b = Load switch is disabled or not in current limit.<br>1b = Load switch is actively limiting the output current (output load is exceeding current limit value). |
| 1   | LS2_I | R    | 0b    | Load switch 2 current-limit interrupt:<br>0b = Load switch is disabled or not in current limit.<br>1b = Load switch is actively limiting the output current (output load is exceeding current limit value). |
| 0   | LS1_I | R    | 0b    | Load switch 1 current-limit interrupt:<br>0b = Load switch is disabled or not in current limit.<br>1b = Load switch is actively limiting the output current (output load is exceeding current limit value). |

**7.5.8 INT\_MASK1 Register (subaddress = 0x03) [reset = 0x00]**

INT\_MASK1 is shown in [Figure 7-34](#) and described in [Table 7-11](#).

Return to [Table 7-6](#).

**Figure 7-34. INT\_MASK1 Register**

| 7        | 6      | 5      | 4      | 3      | 2       | 1      | 0      |
|----------|--------|--------|--------|--------|---------|--------|--------|
| RESERVED | VPRGM  | ACM    | PBM    | HOTM   | CC_AQCM | PRGCM  |        |
| R-00b    | R/W-0b | R/W-0b | R/W-0b | R/W-0b | R/W-0b  | R/W-0b | R/W-0b |

**Table 7-11. INT\_MASK1 Register Field Descriptions**

| Bit | Field    | Type | Reset | Description                                                                                                                                                                                                                         |
|-----|----------|------|-------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7-6 | RESERVED | R    | 00b   |                                                                                                                                                                                                                                     |
| 5   | VPRGM    | R/W  | 0b    | Programming voltage interrupt mask bit. Note: mask bit has no effect on monitoring function:<br>0b = Interrupt is unmasked (interrupt event pulls nINT pin low).<br>1b = Interrupt is masked (interrupt has no effect on nINT pin). |
| 4   | ACM      | R/W  | 0b    | AC_DET interrupt masking bit:<br>0b = Interrupt is unmasked (interrupt event pulls nINT pin low).<br>1b = Interrupt is masked (interrupt has no effect on nINT pin).<br>Note: mask bit has no effect on monitoring function.        |
| 3   | PBM      | R/W  | 0b    | PB interrupt masking bit. Note: mask bit has no effect on monitoring function.<br>0b = Interrupt is unmasked (interrupt event pulls nINT pin low).<br>1b = Interrupt is masked (interrupt has no effect on nINT pin).               |
| 2   | HOTM     | R/W  | 0b    | HOT interrupt masking bit. Note: mask bit has no effect on monitoring function.<br>0b = Interrupt is unmasked (interrupt event pulls nINT pin low).<br>1b = Interrupt is masked (interrupt has no effect on nINT pin).              |
| 1   | CC_AQCM  | R/W  | 0b    | C_AQC interrupt masking bit. Note: mask bit has no effect on monitoring function.<br>0b = Interrupt is unmasked (interrupt event pulls nINT pin low).<br>1b = Interrupt is masked (interrupt has no effect on nINT pin).            |



**Table 7-11. INT\_MASK1 Register Field Descriptions (continued)**

| Bit | Field | Type | Reset | Description                                                                                                                                                                                                             |
|-----|-------|------|-------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 0   | PRGCM | R/W  | 0b    | PRGC interrupt masking bit. Note: mask bit has no effect on monitoring function.<br>0b = Interrupt is unmasked (interrupt event pulls nINT pin low).<br>1b = Interrupt is masked (interrupt has no effect on nINT pin). |

### 7.5.9 INT\_MASK2 Register (subaddress = 0x04) [reset = 0x00]

INT\_MASK2 is shown in [Figure 7-35](#) and described in [Table 7-12](#).

Return to [Table 7-6](#).

**Figure 7-35. INT\_MASK2 Register**

| 7        | 6      | 5      | 4      | 3      | 2      | 1      | 0      |
|----------|--------|--------|--------|--------|--------|--------|--------|
| RESERVED | LS3_FM | LS2_FM | LS1_FM | LS3_IM | LS2_IM | LS1_IM |        |
| R-00b    | R/W-0b | R/W-0b | R/W-0b | R/W-0b | R/W-0b | R/W-0b | R/W-0b |

**Table 7-12. INT\_MASK2 Register Field Descriptions**

| Bit | Field    | Type | Reset | Description                                                                                                                                                                                                                       |
|-----|----------|------|-------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7-6 | RESERVED | R    | 00b   |                                                                                                                                                                                                                                   |
| 5   | LS3_FM   | R/W  | 0b    | LS3 fault interrupt mask bit. Note: mask bit has no effect on monitoring function.<br>0b = Interrupt is unmasked (interrupt event pulls nINT pin low).<br>1b = Interrupt is masked (interrupt has no effect on nINT pin).         |
| 4   | LS2_FM   | R/W  | 0b    | LS2 fault interrupt mask bit. Note: mask bit has no effect on monitoring function.<br>0b = Interrupt is unmasked (interrupt event pulls nINT pin low).<br>1b = Interrupt is masked (interrupt has no effect on nINT pin).         |
| 3   | LS1_FM   | R/W  | 0b    | LS1 fault interrupt mask bit. Note: mask bit has no effect on monitoring function.<br>0b = Interrupt is unmasked (interrupt event pulls nINT pin low).<br>1b = Interrupt is masked (interrupt has no effect on nINT pin).         |
| 2   | LS3_IM   | R/W  | 0b    | LS3 current-limit interrupt mask bit. Note: mask bit has no effect on monitoring function.<br>0b = Interrupt is unmasked (interrupt event pulls nINT pin low).<br>1b = Interrupt is masked (interrupt has no effect on nINT pin). |
| 1   | LS2_IM   | R/W  | 0b    | LS2 current-limit interrupt mask bit. Note: mask bit has no effect on monitoring function.<br>0b = Interrupt is unmasked (interrupt event pulls nINT pin low).<br>1b = Interrupt is masked (interrupt has no effect on nINT pin). |
| 0   | LS1_IM   | R/W  | 0b    | LS1 current-limit interrupt mask bit. Note: mask bit has no effect on monitoring function.<br>0b = Interrupt is unmasked (interrupt event pulls nINT pin low).<br>1b = Interrupt is masked (interrupt has no effect on nINT pin). |

### 7.5.10 STATUS Register (subaddress = 0x05) [reset = 00XXXXXXb]

Register mask: C0h

STATUS is shown in [Figure 7-36](#) and is described in [Table 7-13](#).

Return to [Table 7-6](#).

**Figure 7-36. STATUS Register**

| 7     | 6    | 5        | 4        | 3     | 2 | 1       | 0 |
|-------|------|----------|----------|-------|---|---------|---|
| FSEAL | EE   | AC_STATE | PB_STATE | STATE |   | CC_STAT |   |
| R-0b  | R-0b | R-X      | R-X      | R-X   |   | R-X     |   |

**Table 7-13. STATUS Register Field Descriptions**

| Bit | Field    | Type | Reset | Description                                                                                                                                                                                                                                                                                                                                                                                                                                                                                         |
|-----|----------|------|-------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7   | FSEAL    | R    | 0b    | Freshness seal (FSEAL) status. Note: See <a href="#">Section 7.5.2</a> for details.<br>0b = FSEAL is in native state (fresh).<br>1b = FSEAL is broken.                                                                                                                                                                                                                                                                                                                                              |
| 6   | EE       | R    | 0b    | EEPROM status:<br>0b = EEPROM values have not been changed from factory default setting.<br>1b = EEPROM values have been changed from factory default settings.                                                                                                                                                                                                                                                                                                                                     |
| 5   | AC_STATE | R    | X     | AC_DET input status bit:<br>0b = AC_DET input is inactive (AC_DET input pin is high).<br>1b = AC_DET input is active (AC_DET input is low).                                                                                                                                                                                                                                                                                                                                                         |
| 4   | PB_STATE | R    | X     | PB input status bit:<br>0b = Push Button input is inactive (PB input pin is high).<br>1b = Push Button input is active (PB input pin is low).                                                                                                                                                                                                                                                                                                                                                       |
| 3-2 | STATE    | R    | X     | State machine STATE indication:<br>0h = PMIC is in transitional state.<br>1h = PMIC is in WAIT_PWR_EN state.<br>2h = PMIC is in ACTIVE state.<br>3h = PMIC is in SUSPEND state.                                                                                                                                                                                                                                                                                                                     |
| 1-0 | CC_STAT  | R    | X     | Coin cell state of charge. Note: Coin-cell voltage acquisition must be triggered first before status bits are valid. See CC_AQ bit in <a href="#">Section 7.5.11</a> .<br>0h = $V_{CC} < V_{LOW\_LEVEL}$ ; Coin cell is not present or approaching end-of-life (EOL).<br>1h = $V_{LOW\_LEVEL} < V_{CC} < V_{GOOD\_LEVEL}$ ; Coin cell voltage is LOW.<br>2h = $V_{GOOD\_LEVEL} < V_{CC} < V_{IDEAL\_LEVEL}$ ; Coin cell voltage is GOOD.<br>3h = $V_{IDEAL} < V_{CC}$ ; Coin cell voltage is IDEAL. |

**7.5.11 CONTROL Register (subaddress = 0x06) [reset = 0x00]**

CONTROL is shown in [Figure 7-37](#) and described in [Table 7-14](#).

Return to [Table 7-6](#).

**Figure 7-37. CONTROL Register**

| 7          | 6 | 5 | 4 | 3 | 2 | 1       | 0      |
|------------|---|---|---|---|---|---------|--------|
| RESERVED   |   |   |   |   |   | OFFnPFO | CC_AQ  |
| R-0000 00b |   |   |   |   |   | R/W-0b  | R/W-0b |

**Table 7-14. CONTROL Register Field Descriptions**

| Bit | Field    | Type | Reset    | Description |
|-----|----------|------|----------|-------------|
| 7-2 | RESERVED | R    | 0000 00b |             |

**Table 7-14. CONTROL Register Field Descriptions (continued)**

| Bit | Field   | Type | Reset | Description                                                                                                                                                           |
|-----|---------|------|-------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 1   | OFFnPFO | R/W  | 0b    | Power-fail shutdown bit:<br>0b = nPFO has no effect on PMIC state.<br>1b = All rails are shut down and PMIC enters OFF state when PFI comparator trips (nPFO is low). |
| 0   | CC_AQ   | R/W  | 0b    | Coin Cell battery voltage acquisition start bit:<br>0b = No significance<br>1b = Triggers voltage acquisition. Bit is automatically reset to 0.                       |

### 7.5.12 FLAG Register (subaddress = 0x07) [reset = 0x00]

FLAG is shown in [Figure 7-38](#) and described in [Table 7-15](#).

Return to [Table 7-6](#).

**Figure 7-38. FLAG Register**

| 7        | 6        | 5        | 4        | 3       | 2       | 1       | 0       |
|----------|----------|----------|----------|---------|---------|---------|---------|
| GPO3_FLG | GPO2_FLG | GPO1_FLG | LDO1_FLG | DC4_FLG | DC3_FLG | DC2_FLG | DC1_FLG |
| R-0b     | R-0b     | R-0b     | R-0b     | R-0b    | R-0b    | R-0b    | R-0b    |

**Table 7-15. FLAG Register Field Descriptions**

| Bit | Field    | Type | Reset | Description                                                                                                                                                                                       |
|-----|----------|------|-------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7   | GPO3_FLG | R    | 0b    | GPO3 Flag bit:<br>0b = Device powered up from OFF or SUSPEND state and GPO3 was disabled while in SUSPEND.<br>1b = Device powered up from SUSPEND state and GPO3 was enabled while in SUSPEND.    |
| 6   | GPO2_FLG | R    | 0b    | GPO2 Flag bit<br>0b = Device powered up from OFF or SUSPEND state and GPO2 was disabled while in SUSPEND.<br>1b = Device powered up from SUSPEND state and GPO2 was enabled while in SUSPEND.     |
| 5   | GPO1_FLG | R    | 0b    | GPO1 Flag bit:<br>0b = Device powered up from OFF or SUSPEND state and GPO1 was disabled while in SUSPEND.<br>1b = Device powered up from SUSPEND state and GPO1 was enabled while in SUSPEND.    |
| 4   | LDO1_FLG | R    | 0b    | LDO1 Flag bit:<br>0b = Device powered up from OFF or SUSPEND state and LDO1 was disabled while in SUSPEND.<br>1b = Device powered up from SUSPEND state and LDO1 was enabled while in SUSPEND.    |
| 3   | DC4_FLG  | R    | 0b    | DCDC4 Flag bit:<br>0b = Device powered up from OFF or SUSPEND state and DCDC4 was disabled while in SUSPEND.<br>1b = Device powered up from SUSPEND state and DCDC4 was enabled while in SUSPEND. |

**Table 7-15. FLAG Register Field Descriptions (continued)**

| Bit | Field   | Type | Reset | Description                                                                                                                                                                                          |
|-----|---------|------|-------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 2   | DC3_FLG | R    | 0b    | DCDC3 Flag bit:<br>0b = Device powered up from OFF or SUSPEND state and DCDC3 was disabled while in SUSPEND.<br>1b = Device powered up from SUSPEND state and DCDC3 was enabled while in SUSPEND.    |
| 1   | DC2_FLG | R    | 0b    | DCDC2 Flag bit:<br>0b = Device powered up from OFF or SUSPEND state and DCDC2 was disabled while in SUSPEND.<br>1b = Device powered up from SUSPEND state and DCDC2 was enabled while in SUSPEND.    |
| 0   | DC1_FLG | R    | 0b    | DCDC1 Flag bit:<br>0b = Device powered up from OFF or SUSPEND state and DCDC1 was disabled while in SUSPEND.<br>1b = Device powered up from SUSPEND state and DCDC1PO3 was enabled while in SUSPEND. |

**7.5.13 PASSWORD Register (subaddress = 0x10) [reset = 0x00]**

PASSWORD is shown in [Figure 7-39](#) and described in [Table 7-16](#).

Return to [Table 7-6](#).

**Figure 7-39. PASSWORD Register**

|         |   |   |   |   |   |   |   |
|---------|---|---|---|---|---|---|---|
| 7       | 6 | 5 | 4 | 3 | 2 | 1 | 0 |
| PWRD    |   |   |   |   |   |   |   |
| R/W-00h |   |   |   |   |   |   |   |

**Table 7-16. PASSWORD Register Field Descriptions**

| Bit | Field | Type | Reset | Description                                                                                                                                                                                                                                                   |
|-----|-------|------|-------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7-0 | PWRD  | R/W  | 00h   | Register is used for accessing password protected registers (see <a href="#">Section 7.5.1</a> for details). Breaking the freshness seal (see <a href="#">Section 7.5.2</a> for details). Programming power-up default values . Read-back always yields 0x00. |

#### 7.5.14 ENABLE1 Register (subaddress = 0x11) [reset = 0x00]

ENABLE1 is shown in [Figure 7-40](#) and described in [Table 7-17](#).

Return to [Table 7-6](#).

Password protected.

**Figure 7-40. ENABLE1 Register**

| 7        | 6      | 5      | 4      | 3      | 2      | 1      | 0      |
|----------|--------|--------|--------|--------|--------|--------|--------|
| RESERVED | DC6_EN | DC5_EN | DC4_EN | DC3_EN | DC2_EN | DC1_EN |        |
| R-00b    | R/W-0b | R/W-0b | R/W-0b | R/W-0b | R/W-0b | R/W-0b | R/W-0b |

**Table 7-17. ENABLE1 Register Field Descriptions**

| Bit | Field    | Type | Reset | Description                                                                                                                                                                                                                              |
|-----|----------|------|-------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7-6 | RESERVED | R    | 00b   |                                                                                                                                                                                                                                          |
| 5   | DC6_EN   | R/W  | 0b    | DCDC6 enable bit. DCDC6 can only be disabled if FSEAL = 0. See <a href="#">Section 7.5.2</a> for details.<br>0b = Disabled<br>1b = Enabled                                                                                               |
| 4   | DC5_EN   | R/W  | 0b    | DCDC5 enable bit. Note: At power-up and down this bit is automatically updated by the internal power sequencer. DCDC5 can only be disabled if FSEAL = 0. See <a href="#">Section 7.5.2</a> for details.<br>0b = Disabled<br>1b = Enabled |
| 3   | DC4_EN   | R/W  | 0b    | DCDC4 enable bit. Note: At power-up and down this bit is automatically updated by the internal power sequencer.<br>0b = Disabled<br>1b = Enabled                                                                                         |
| 2   | DC3_EN   | R/W  | 0b    | DCDC3 enable bit. Note: At power-up and down this bit is automatically updated by the internal power sequencer.<br>0b = Disabled<br>1b = Enabled                                                                                         |
| 1   | DC2_EN   | R/W  | 0b    | DCDC2 enable bit. Note: At power-up and down this bit is automatically updated by the internal power sequencer.<br>0b = Disabled<br>1b = Enabled                                                                                         |
| 0   | DC1_EN   | R/W  | 0b    | DCDC1 enable bit. Note: At power-up and down this bit is automatically updated by the internal power sequencer.<br>0b = Disabled<br>1b = Enabled                                                                                         |

#### 7.5.15 ENABLE2 Register (subaddress = 0x12) [reset = 0x00]

ENABLE2 is shown in [Figure 7-41](#) and described in [Table 7-18](#).

Return to [Table 7-6](#).

Password protected.

**Figure 7-41. ENABLE2 Register**

| 7        | 6      | 5      | 4      | 3      | 2      | 1      | 0       |
|----------|--------|--------|--------|--------|--------|--------|---------|
| RESERVED | GPIO3  | GPIO2  | GPIO1  | LS3_EN | LS2_EN | LS1_EN | LDO1_EN |
| R-0b     | R/W-0b | R/W-0b | R/W-0b | R/W-0b | R/W-0b | R/W-0b | R/W-0b  |

**Table 7-18. ENABLE2 Register Field Descriptions**

| Bit | Field    | Type | Reset | Description                                                                                                                                                                             |
|-----|----------|------|-------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7   | RESERVED | R    | 0b    |                                                                                                                                                                                         |
| 6   | GPIO3    | R/W  | 0b    | General purpose output 3 / reset polarity. Note: If DC12_RST bit (register 0x14) is set to 1 this bit has no function.<br>0b = GPIO3 output is driven low.<br>1b = GPIO3 output is HiZ. |
| 5   | GPIO2    | R/W  | 0b    | General purpose output 2. Note: If IO_SEL bit (register 0x13) is set to 1 this bit has no function.<br>0b = GPIO2 output is driven low.<br>1b = GPIO2 output is HiZ.                    |
| 4   | GPIO1    | R/W  | 0b    | General purpose output 1. Note: If IO_SEL bit (register 0x13) is set to 1 this bit has no function.<br>0b = GPIO1 output is driven low.<br>1b = GPIO1 output is HiZ.                    |
| 3   | LS3_EN   | R/W  | 0b    | Load switch 3 (LS3) enable bit.<br>0b = Disabled<br>1b = Enabled                                                                                                                        |
| 2   | LS2_EN   | R/W  | 0b    | Load switch 2 (LS2) enable bit.<br>0b = Disabled<br>1b = Enabled                                                                                                                        |
| 1   | LS1_EN   | R/W  | 0b    | Load switch 1 (LS1) enable bit.<br>0b = Disabled<br>1b = Enabled<br>Note: At power-up and down this bit is automatically updated by the internal power sequencer.                       |
| 0   | LDO1_EN  | R/W  | 0b    | LDO1 enable bit.<br>0b = Disabled<br>1b = Enabled<br>Note: At power-up and down this bit is automatically updated by the internal power sequencer.                                      |

**7.5.16 CONFIG1 Register (subaddress = 0x13) [reset = 0x08]**

CONFIG1 is shown in [Figure 7-42](#) and described in [Table 7-19](#).

Return to [Table 7-6](#).

Password protected.

**Figure 7-42. CONFIG1 Register**

| 7      | 6        | 5       | 4       | 3        | 2       | 1 | 0 |
|--------|----------|---------|---------|----------|---------|---|---|
| TRST   | GPO2_BUF | IO1_SEL | PGDLY   | Reserved | UVLO    |   |   |
| R/W-0b | R/W-0b   | R/W-0b  | R/W-01b | R/W-0b   | R/W-00b |   |   |

**Table 7-19. CONFIG1 Register Field Descriptions**

| Bit | Field | Type | Reset | Description                                               |
|-----|-------|------|-------|-----------------------------------------------------------|
| 7   | TRST  | R/W  | 0b    | Push-button reset time constant:<br>0b = 8 s<br>1b = 15 s |

**Table 7-19. CONFIG1 Register Field Descriptions (continued)**

| Bit | Field    | Type | Reset | Description                                                                                                                                                                                                                                                                         |
|-----|----------|------|-------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 6   | GPO2_BUF | R/W  | 0b    | GPO2 output buffer configuration:<br>0b = GPO2 buffer is configured as open-drain.<br>1b = GPO2 buffer is configured as push-pull (high-level is driven to IN_LS1).                                                                                                                 |
| 5   | IO1_SEL  | R/W  | 0b    | GPIO1 / GPO2 configuration bit. See <a href="#">Section 7.3.1.14</a> for details.<br>0b = GPIO1 is configured as general-purpose, open-drain output.<br>GPO2 is independent output.<br>1b = GPIO1 is configured as input, controlling GPO2. Intended for DDR3 reset signal control. |
| 4-3 | PGDLY    | R/W  | 01b   | Power-Good delay. Note: Power-good delay applies to rising-edge only (power-up), not falling edge (power-down or fault).<br>00b = 10 ms<br>01b = 20 ms<br>10b = 50 ms<br>11b = 150 ms                                                                                               |
| 2   | Reserved | R    | 0b    | Supply Voltage Supervisor Sensitivity selection. See <a href="#">Section 6.5</a> for details.<br>0b = Power-good threshold (VOUT falling) has wider limits. Over-voltage is not monitored.<br>1b = Power-good threshold (VOUT falling) has tight limits. Over-voltage is monitored. |
| 1-0 | UVLO     | R/W  | 00b   | UVLO setting<br>00b = 2.75 V<br>01b = 2.95 V<br>10b = 3.25 V<br>11b = 3.35 V                                                                                                                                                                                                        |

### 7.5.17 CONFIG2 Register (subaddress = 0x14) [reset = 0xC0]

CONFIG2 is shown in [Figure 7-43](#) and described in [Table 7-20](#).

Return to [Table 7-6](#).

Password protected.

**Figure 7-43. CONFIG2 Register**

|          |         |          |   |         |   |         |   |
|----------|---------|----------|---|---------|---|---------|---|
| 7        | 6       | 5        | 4 | 3       | 2 | 1       | 0 |
| DC12_RST | UVLOHYS | RESERVED |   | LS3ILIM |   | LS2ILIM |   |
| R/W-1b   | R/W-1b  | R-00b    |   | R/W-00b |   | R/W-00b |   |

**Table 7-20. CONFIG2 Register Field Descriptions**

| Bit | Field    | Type | Reset | Description                                                                                                                                                  |
|-----|----------|------|-------|--------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7   | DC12_RST | R/W  | 1b    | DCDC1 and DCDC2 reset-pin enable:<br>0b = GPIO3 is configured as general-purpose output.<br>1b = GPIO3 is configured as warm-reset input to DCDC1 and DCDC2. |
| 6   | UVLOHYS  | R/W  | 1b    | UVLO hysteresis:<br>0b = 200 mV<br>1b = 400 mV                                                                                                               |
| 5-4 | RESERVED | R    | 00b   |                                                                                                                                                              |

**Table 7-20. CONFIG2 Register Field Descriptions (continued)**

| Bit | Field   | Type | Reset | Description                                                                                                                                                                                                                                                              |
|-----|---------|------|-------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 3-2 | LS3ILIM | R/W  | 00b   | Load switch 3 (LS3) current limit selection:<br>00b = 100 mA, (MIN = 98 mA)<br>01b = 200 mA, (MIN = 194 mA)<br>10b = 500 mA, (MIN = 475 mA)<br>11b = 1000 mA, (MIN = 900 mA)<br>See the LS3 current limit specification in <a href="#">Section 6.5</a> for more details. |
| 1-0 | LS2ILIM | R/W  | 00b   | Load switch 2 (LS2) current limit selection:<br>00b = 100 mA, (MIN = 94 mA)<br>01b = 200 mA, (MIN = 188 mA)<br>10b = 500 mA, (MIN = 465 mA)<br>11b = 1000 mA, (MIN = 922 mA)<br>See the LS2 current limit specification in <a href="#">Section 6.5</a> for more details. |



### 7.5.18 CONFIG3 Register (subaddress = 0x15) [reset = 0x0]

CONFIG3 is shown in [Figure 7-44](#) and described in [Table 7-21](#).

Return to [Table 7-6](#).

Password protected.

**Figure 7-44. CONFIG3 Register**

| 7        | 6 | 5       | 4       | 3       | 2        | 1        | 0        |
|----------|---|---------|---------|---------|----------|----------|----------|
| RESERVED |   | LS3nPFO | LS2nPFO | LS1nPFO | LS3DCHRG | LS2DCHRG | LS1DCHRG |
| R-00b    |   | R/W-0b  | R/W-0b  | R/W-0b  | R/W-0b   | R/W-0b   | R/W-0b   |

**Table 7-21. CONFIG3 Register Field Descriptions**

| Bit | Field    | Type | Reset | Description                                                                                                                                                                              |
|-----|----------|------|-------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7-6 | RESERVED | R    | 00b   |                                                                                                                                                                                          |
| 5   | LS3nPFO  | R/W  | 0b    | Load switch 3 power-fail disable bit:<br>0b = Load switch status is not affected by power-fail comparator.<br>1b = Load switch is disabled if power-fail comparator trips (nPFO is low). |
| 4   | LS2nPFO  | R/W  | 0b    | Load switch 2 power-fail disable bit:<br>0b = Load switch status is not affected by power-fail comparator.<br>1b = Load switch is disabled if power-fail comparator trips (nPFO is low). |
| 3   | LS1nPFO  | R/W  | 0b    | Load switch 1 power-fail disable bit:<br>0b = Load switch status is not affected by power-fail comparator.<br>1b = Load switch is disabled if power-fail comparator trips (nPFO is low). |
| 2   | LS3DCHRG | R/W  | 0b    | Load switch 3 discharge enable bit:<br>0b = Active discharge is disabled.<br>1b = Active discharge is enabled (load switch output is actively discharged when switch is OFF).            |
| 1   | LS2DCHRG | R/W  | 0b    | Load switch 2 discharge enable bit:<br>0b = Active discharge is disabled.<br>1b = Active discharge is enabled (load switch output is actively discharged when switch is OFF).            |
| 0   | LS1DCHRG | R/W  | 0b    | Load switch 1 discharge enable bit:<br>0b = Active discharge is disabled.<br>1b = Active discharge is enabled (load switch output is actively discharged when switch is OFF).            |

### 7.5.19 DCDC1 Register (offset = 0x16) [reset = 0xAB]

DCDC1 is shown in [Figure 7-45](#) and described in [Table 7-22](#).

Return to [Table 7-6](#).

Note 1: This register is password protected. For more information, see [Section 7.5.1](#).

Note 2: A 5-ms blanking time of the over-voltage and under-voltage monitoring occurs when a write is performed on the DCDC1 register.

Note 3: To change the output voltage of DCDC1, the GO bit or the GODSBL bit must be set to 1b in register 0x1A.

**Figure 7-45. DCDC1 Register**

| 7      | 6        | 5       | 4 | 3 | 2 | 1 | 0 |
|--------|----------|---------|---|---|---|---|---|
| PFM    | RESERVED | DCDC1   |   |   |   |   |   |
| R/W-1b | R-0b     | R/W-2Bh |   |   |   |   |   |

**Table 7-22. DCDC1 Register Field Descriptions**

| Bit | Field    | Type | Reset | Description                                                                                                                                                                                                         |
|-----|----------|------|-------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7   | PFM      | R/W  | 1b    | Pulse Frequency Modulation (PFM, also known as pulse-skip-mode) enable. PFM mode improves light-load efficiency. Actual PFM mode operation depends on load condition.<br>0b = Disabled (forced PWM)<br>1b = Enabled |
| 6   | RESERVED | R    | 0b    |                                                                                                                                                                                                                     |

**Table 7-22. DCDC1 Register Field Descriptions (continued)**

| Bit | Field | Type | Reset | Description                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                               |
|-----|-------|------|-------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 5-0 | DCDC1 | R/W  | 2Bh   | DCDC1 output voltage setting:<br>0h = 0.850<br>1h = 0.860<br>2h = 0.870<br>3h = 0.880<br>4h = 0.890<br>5h = 0.900<br>6h = 0.910<br>7h = 0.920<br>8h = 0.930<br>9h = 0.940<br>Ah = 0.950<br>Bh = 0.960<br>Ch = 0.970<br>Dh = 0.980<br>Eh = 0.990<br>Fh = 1.000<br>10h = 1.010<br>11h = 1.020<br>12h = 1.030<br>13h = 1.040<br>14h = 1.050<br>15h = 1.060<br>16h = 1.070<br>17h = 1.080<br>18h = 1.090<br>19h = 1.100<br>1Ah = 1.110<br>1Bh = 1.120<br>1Ch = 1.130<br>1Dh = 1.140<br>1Eh = 1.150<br>1Fh = 1.160<br>20h = 1.170<br>21h = 1.180<br>22h = 1.190<br>23h = 1.200 |

**Table 7-22. DCDC1 Register Field Descriptions (continued)**

| Bit | Field | Type | Reset | Description |
|-----|-------|------|-------|-------------|
|     |       |      |       | 24h = 1.210 |
|     |       |      |       | 25h = 1.220 |
|     |       |      |       | 26h = 1.230 |
|     |       |      |       | 27h = 1.240 |
|     |       |      |       | 28h = 1.250 |
|     |       |      |       | 29h = 1.260 |
|     |       |      |       | 2Ah = 1.270 |
|     |       |      |       | 2Bh = 1.280 |
|     |       |      |       | 2Ch = 1.290 |
|     |       |      |       | 2Dh = 1.300 |
|     |       |      |       | 2Eh = 1.310 |
|     |       |      |       | 2Fh = 1.320 |
|     |       |      |       | 30h = 1.330 |
|     |       |      |       | 31h = 1.340 |
|     |       |      |       | 32h = 1.350 |
|     |       |      |       | 33h = 1.375 |
|     |       |      |       | 34h = 1.400 |
|     |       |      |       | 35h = 1.425 |
|     |       |      |       | 36h = 1.450 |
|     |       |      |       | 37h = 1.475 |
|     |       |      |       | 38h = 1.500 |
|     |       |      |       | 39h = 1.525 |
|     |       |      |       | 3Ah = 1.550 |
|     |       |      |       | 3Bh = 1.575 |
|     |       |      |       | 3Ch = 1.600 |
|     |       |      |       | 3Dh = 1.625 |
|     |       |      |       | 3Eh = 1.650 |
|     |       |      |       | 3Fh = 1.675 |

**7.5.20 DCDC2 Register (subaddress = 0x17) [reset = 0xB2]**

DCDC2 is shown in [Figure 7-46](#) and described in [Table 7-23](#).

Return to [Table 7-6](#).

Note 1: This register is password protected. For more information, see [Section 7.5.1](#).

Note 2: A 5-ms blanking time of the over-voltage and under-voltage monitoring occurs when a write is performed on the DCDC2 register.

Note 3: To change the output voltage of DCDC2, the GO bit or the GODSBL bit must be set to 1b in register 0x1A.

**Figure 7-46. DCDC2 Register**

| 7      | 6        | 5 | 4 | 3 | 2 | 1 | 0       |
|--------|----------|---|---|---|---|---|---------|
| PFM    | RESERVED |   |   |   |   |   | DCDC2   |
| R/W-1b | R-0b     |   |   |   |   |   | R/W-32h |

**Table 7-23. DCDC2 Register Field Descriptions**

| Bit | Field | Type | Reset | Description                                                                                                                                                                                                         |
|-----|-------|------|-------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7   | PFM   | R/W  | 1b    | Pulse frequency modulation (PFM, also known as pulse-skip-mode) enable. PFM mode improves light-load efficiency. Actual PFM mode operation depends on load condition.<br>0b = Disabled (forced PWM)<br>1b = Enabled |

**Table 7-23. DCDC2 Register Field Descriptions (continued)**

| Bit | Field    | Type | Reset | Description                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                               |
|-----|----------|------|-------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 6   | RESERVED | R    | 0b    |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                           |
| 5-0 | DCDC2    | R/W  | 32h   | DCDC2 output voltage setting:<br>0h = 0.850<br>1h = 0.860<br>2h = 0.870<br>3h = 0.880<br>4h = 0.890<br>5h = 0.900<br>6h = 0.910<br>7h = 0.920<br>8h = 0.930<br>9h = 0.940<br>Ah = 0.950<br>Bh = 0.960<br>Ch = 0.970<br>Dh = 0.980<br>Eh = 0.990<br>Fh = 1.000<br>10h = 1.010<br>11h = 1.020<br>12h = 1.030<br>13h = 1.040<br>14h = 1.050<br>15h = 1.060<br>16h = 1.070<br>17h = 1.080<br>18h = 1.090<br>19h = 1.100<br>1Ah = 1.110<br>1Bh = 1.120<br>1Ch = 1.130<br>1Dh = 1.140<br>1Eh = 1.150<br>1Fh = 1.160<br>20h = 1.170<br>21h = 1.180<br>22h = 1.190<br>23h = 1.200 |

**Table 7-23. DCDC2 Register Field Descriptions (continued)**

| Bit | Field | Type | Reset | Description |
|-----|-------|------|-------|-------------|
|     |       |      |       | 24h = 1.210 |
|     |       |      |       | 25h = 1.220 |
|     |       |      |       | 26h = 1.230 |
|     |       |      |       | 27h = 1.240 |
|     |       |      |       | 28h = 1.250 |
|     |       |      |       | 29h = 1.260 |
|     |       |      |       | 2Ah = 1.270 |
|     |       |      |       | 2Bh = 1.280 |
|     |       |      |       | 2Ch = 1.290 |
|     |       |      |       | 2Dh = 1.300 |
|     |       |      |       | 2Eh = 1.310 |
|     |       |      |       | 2Fh = 1.320 |
|     |       |      |       | 30h = 1.330 |
|     |       |      |       | 31h = 1.340 |
|     |       |      |       | 32h = 1.350 |
|     |       |      |       | 33h = 1.375 |
|     |       |      |       | 34h = 1.400 |
|     |       |      |       | 35h = 1.425 |
|     |       |      |       | 36h = 1.450 |
|     |       |      |       | 37h = 1.475 |
|     |       |      |       | 38h = 1.500 |
|     |       |      |       | 39h = 1.525 |
|     |       |      |       | 3Ah = 1.550 |
|     |       |      |       | 3Bh = 1.575 |
|     |       |      |       | 3Ch = 1.600 |
|     |       |      |       | 3Dh = 1.625 |
|     |       |      |       | 3Eh = 1.650 |
|     |       |      |       | 3Fh = 1.675 |

**7.5.21 DCDC3 Register (subaddress = 0x18) [reset = 0xBD]**

DCDC3 is shown in [Figure 7-47](#) and described in [Table 7-24](#).

Return to [Table 7-6](#).

Note 1: This register is password protected. For more information, see [Section 7.5.1](#).

Note 2: A 5-ms blanking time of the over-voltage and under-voltage monitoring occurs when a write is performed on the DCDC3 register.

**Note**

Power-up default may differ depending on RSEL value. See [Section 7.3.1.13](#) for details.

**Figure 7-47. DCDC3 Register**

| 7      | 6        | 5 | 4 | 3 | 2 | 1 | 0       |
|--------|----------|---|---|---|---|---|---------|
| PFM    | RESERVED |   |   |   |   |   | DCDC3   |
| R/W-1b | R-0b     |   |   |   |   |   | R/W-3Dh |

**Table 7-24. DCDC3 Register Field Descriptions**

| Bit | Field    | Type | Reset | Description                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                               |
|-----|----------|------|-------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7   | PFM      | R/W  | 1b    | Pulse Frequency Modulation (PFM, also known as pulse-skip-mode) enable. PFM mode improves light-load efficiency. Actual PFM mode operation depends on load condition.<br>0b = Disabled (forced PWM)<br>1b = Enabled                                                                                                                                                                                                                                                                                                                                                       |
| 6   | RESERVED | R    | 0b    |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                           |
| 5-0 | DCDC3    | R/W  | 3Dh   | DCDC3 output voltage setting:<br>0h = 0.900<br>1h = 0.925<br>2h = 0.950<br>3h = 0.975<br>4h = 1.000<br>5h = 1.025<br>6h = 1.050<br>7h = 1.075<br>8h = 1.100<br>9h = 1.125<br>Ah = 1.150<br>Bh = 1.175<br>Ch = 1.200<br>Dh = 1.225<br>Eh = 1.250<br>Fh = 1.275<br>10h = 1.300<br>11h = 1.325<br>12h = 1.350<br>13h = 1.375<br>14h = 1.400<br>15h = 1.425<br>16h = 1.450<br>17h = 1.475<br>18h = 1.500<br>19h = 1.525<br>1Ah = 1.550<br>1Bh = 1.600<br>1Ch = 1.650<br>1Dh = 1.700<br>1Eh = 1.750<br>1Fh = 1.800<br>20h = 1.850<br>21h = 1.900<br>22h = 1.950<br>23h = 2.000 |

**Table 7-24. DCDC3 Register Field Descriptions (continued)**

| Bit | Field | Type | Reset | Description |
|-----|-------|------|-------|-------------|
|     |       |      |       | 24h = 2.050 |
|     |       |      |       | 25h = 2.100 |
|     |       |      |       | 26h = 2.150 |
|     |       |      |       | 27h = 2.200 |
|     |       |      |       | 28h = 2.250 |
|     |       |      |       | 29h = 2.300 |
|     |       |      |       | 2Ah = 2.350 |
|     |       |      |       | 2Bh = 2.400 |
|     |       |      |       | 2Ch = 2.450 |
|     |       |      |       | 2Dh = 2.500 |
|     |       |      |       | 2Eh = 2.550 |
|     |       |      |       | 2Fh = 2.600 |
|     |       |      |       | 30h = 2.650 |
|     |       |      |       | 31h = 2.700 |
|     |       |      |       | 32h = 2.750 |
|     |       |      |       | 33h = 2.800 |
|     |       |      |       | 34h = 2.850 |
|     |       |      |       | 35h = 2.900 |
|     |       |      |       | 36h = 2.950 |
|     |       |      |       | 37h = 3.000 |
|     |       |      |       | 38h = 3.050 |
|     |       |      |       | 39h = 3.100 |
|     |       |      |       | 3Ah = 3.150 |
|     |       |      |       | 3Bh = 3.200 |
|     |       |      |       | 3Ch = 3.250 |
|     |       |      |       | 3Dh = 3.300 |
|     |       |      |       | 3Eh = 3.350 |
|     |       |      |       | 3Fh = 3.400 |

**7.5.22 DCDC4 Register (subaddress = 0x19) [reset = 0x94]**

DCDC4 is shown in [Figure 7-48](#) and described in [Table 7-25](#).

Return to [Table 7-6](#).

Note 1: This register is password protected. For more information, see [Section 7.5.1](#).

Note 2: A 5-ms blanking time of the over-voltage and under-voltage monitoring occurs when a write is performed on the DCDC4 register.

**Note**

Power-up default may differ depending on RSEL value. See [Section 7.3.1.13](#) for details. The Reserved setting should not be selected and the output voltage settings should not be modified while the converter is operating.

**Figure 7-48. DCDC4 Register**

| 7      | 6        | 5 | 4 | 3 | 2 | 1 | 0       |
|--------|----------|---|---|---|---|---|---------|
| PFM    | RESERVED |   |   |   |   |   | DCDC4   |
| R/W-1b | R-0b     |   |   |   |   |   | R/W-14h |



**Table 7-25. DCDC4 Register Field Descriptions**

| Bit | Field    | Type | Reset | Description                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                |
|-----|----------|------|-------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7   | PFM      | R/W  | 1b    | Pulse Frequency Modulation (PFM, also known as pulse-skip-mode) enable. PFM mode improves light-load efficiency. Actual PFM mode operation depends on load condition.<br>0b = Disabled (forced PWM)<br>1b = Enabled                                                                                                                                                                                                                                                                                                                                                        |
| 6   | RESERVED | R    | 0b    |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                            |
| 5-0 | DCDC4    | R/W  | 14h   | DCDC4 output voltage setting:<br>0h = 1.175<br>1h = 1.200<br>2h = 1.225<br>3h = 1.250<br>4h = 1.275<br>5h = 1.300<br>6h = 1.325<br>7h = 1.350<br>8h = 1.375<br>9h = 1.400<br>Ah = 1.425<br>Bh = 1.450<br>Ch = 1.475<br>Dh = 1.500<br>Eh = 1.525<br>Fh = 1.550<br>10h = 1.600<br>11h = 1.650<br>12h = 1.700<br>13h = 1.750<br>14h = 1.800<br>15h = 1.850<br>16h = 1.900<br>17h = 1.950<br>18h = 2.000<br>19h = 2.050<br>1Ah = 2.100<br>1Bh = 2.150<br>1Ch = 2.200<br>1Dh = 2.250<br>1Eh = 2.300<br>1Fh = 2.3500<br>20h = 2.400<br>21h = 2.450<br>22h = 2.500<br>23h = 2.550 |

**Table 7-25. DCDC4 Register Field Descriptions (continued)**

| Bit | Field | Type | Reset | Description    |
|-----|-------|------|-------|----------------|
|     |       |      |       | 24h = 2.600    |
|     |       |      |       | 25h = 2.650    |
|     |       |      |       | 26h = 2.700    |
|     |       |      |       | 27h = 2.750    |
|     |       |      |       | 28h = 2.800    |
|     |       |      |       | 29h = 2.850    |
|     |       |      |       | 2Ah = 2.900    |
|     |       |      |       | 2Bh = 2.950    |
|     |       |      |       | 2Ch = 3.000    |
|     |       |      |       | 2Dh = 3.050    |
|     |       |      |       | 2Eh = 3.100    |
|     |       |      |       | 2Fh = 3.150    |
|     |       |      |       | 30h = 3.200    |
|     |       |      |       | 31h = 3.250    |
|     |       |      |       | 32h = 3.300    |
|     |       |      |       | 33h = 3.350    |
|     |       |      |       | 34h = 3.400    |
|     |       |      |       | 35h = reserved |
|     |       |      |       | 36h = reserved |
|     |       |      |       | 37h = reserved |
|     |       |      |       | 38h = reserved |
|     |       |      |       | 39h = reserved |
|     |       |      |       | 3Ah = reserved |
|     |       |      |       | 3Bh = reserved |
|     |       |      |       | 3Ch = reserved |
|     |       |      |       | 3Dh = reserved |
|     |       |      |       | 3Eh = reserved |
|     |       |      |       | 3Fh = reserved |

**7.5.23 SLEW Register (subaddress = 0x1A) [reset = 0x06]**

SLEW is shown in [Figure 7-49](#) and described in [Table 7-26](#).

Return to [Table 7-6](#).

**Note**

Slew-rate control applies to DCDC1 and DCDC2 only. If changing from a higher voltage to lower voltage while STRICT = 1 and converters are in a no load state, PFM bit for DCDC1 and DCDC2 must be set to 0.

**Figure 7-49. SLEW Register**

| 7      | 6      | 5        | 4 | 3 | 2      | 1 | 0 |
|--------|--------|----------|---|---|--------|---|---|
| GO     | GODSBL | RESERVED |   |   | SLEW   |   |   |
| R/W-0b | R/W-0b | R-000b   |   |   | R/W-6h |   |   |

**Table 7-26. SLEW Register Field Descriptions**

| Bit | Field    | Type | Reset | Description                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                |
|-----|----------|------|-------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7   | GO       | R/W  | 0b    | Go bit. Note: Bit is automatically reset at the end of the voltage transition.<br>0b = No change<br>1b = Initiates the transition from present state to the output voltage setting currently stored in DCDC1 and DCDC2 register. SLEW setting does apply.                                                                                                                                                                                                                                                                                                                                                                                                  |
| 6   | GODSBL   | R/W  | 0b    | Go disable bit<br>0b = Enabled<br>1b = Disabled; DCDC1 and DCDC2 output voltage changes whenever set-point is updated in DCDC1 and DCDC2 register without having to write to the GO bit. SLEW setting does apply.                                                                                                                                                                                                                                                                                                                                                                                                                                          |
| 5-3 | RESERVED | R    | 000b  |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                            |
| 2-0 | SLEW     | R/W  | 6h    | Output slew rate setting:<br>0h = 160 $\mu$ s/step (0.0625 mV/ $\mu$ s at 10 mV per step)<br>1h = 80 $\mu$ s/step (0.125 mV/ $\mu$ s at 10 mV per step)<br>2h = 40 $\mu$ s/step (0.250 mV/ $\mu$ s at 10 mV per step)<br>3h = 20 $\mu$ s/step (0.500 mV/ $\mu$ s at 10 mV per step)<br>4h = 10 $\mu$ s/step (1.0 mV/ $\mu$ s at 10 mV per step)<br>5h = 5 $\mu$ s/step (2.0 mV/ $\mu$ s at 10 mV per step)<br>6h = 2.5 $\mu$ s/step (4.0 mV/ $\mu$ s at 10 mV per step)<br>7h = Immediate; slew rate is only limited by control loop response time. Note: The actual slew rate depends on the voltage step per code. Refer to DCDCx registers for details. |

#### 7.5.24 LDO1 Register (subaddress = 0x1B) [reset = 0x33]

LDO1 is shown in [Figure 7-50](#) and described in [Table 7-27](#).

Return to [Table 7-6](#).

Note 1: This register is password protected. For more information, see [Section 7.5.1](#).

Note 2: A 5-ms blanking time of the over-voltage and under-voltage monitoring occurs when a write is performed on the LDO1 register.

**Figure 7-50. LDO1 Register**

|          |   |   |         |   |   |   |   |
|----------|---|---|---------|---|---|---|---|
| 7        | 6 | 5 | 4       | 3 | 2 | 1 | 0 |
| RESERVED |   |   | LDO1    |   |   |   |   |
| R-00b    |   |   | R/W-33h |   |   |   |   |

**Table 7-27. LDO1 Register Field Descriptions**

| Bit | Field    | Type | Reset | Description |
|-----|----------|------|-------|-------------|
| 7-6 | RESERVED | R    | 00b   |             |

**Table 7-27. LDO1 Register Field Descriptions (continued)**

| Bit | Field | Type | Reset | Description                                                                                                                                                                                                                                                                                                                                                                                                        |
|-----|-------|------|-------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 5-0 | LDO1  | R/W  | 33h   | LDO1 output voltage setting:<br>0h = 0.900<br>1h = 0.925<br>2h = 0.950<br>3h = 0.975<br>4h = 1.000<br>5h = 1.025<br>6h = 1.050<br>7h = 1.075<br>8h = 1.100<br>9h = 1.125<br>Ah = 1.150<br>Bh = 1.175<br>Ch = 1.200<br>Dh = 1.225<br>Eh = 1.250<br>Fh = 1.275<br>10h = 1.300<br>11h = 1.325<br>12h = 1.350<br>13h = 1.375<br>14h = 1.400<br>15h = 1.425<br>16h = 1.450<br>17h = 1.475<br>18h = 1.500<br>19h = 1.525 |

**Table 7-27. LDO1 Register Field Descriptions (continued)**

| Bit | Field | Type | Reset | Description |
|-----|-------|------|-------|-------------|
|     |       |      |       | 1Ah = 1.550 |
|     |       |      |       | 1Bh = 1.600 |
|     |       |      |       | 1Ch = 1.650 |
|     |       |      |       | 1Dh = 1.700 |
|     |       |      |       | 1Eh = 1.750 |
|     |       |      |       | 1Fh = 1.800 |
|     |       |      |       | 20h = 1.850 |
|     |       |      |       | 21h = 1.900 |
|     |       |      |       | 22h = 1.950 |
|     |       |      |       | 23h = 2.000 |
|     |       |      |       | 24h = 2.050 |
|     |       |      |       | 25h = 2.100 |
|     |       |      |       | 26h = 2.150 |
|     |       |      |       | 27h = 2.200 |
|     |       |      |       | 28h = 2.250 |
|     |       |      |       | 29h = 2.300 |
|     |       |      |       | 2Ah = 2.350 |
|     |       |      |       | 2Bh = 2.400 |
|     |       |      |       | 2Ch = 2.450 |
|     |       |      |       | 2Dh = 2.500 |
|     |       |      |       | 2Eh = 2.550 |
|     |       |      |       | 2Fh = 2.600 |
|     |       |      |       | 30h = 2.650 |
|     |       |      |       | 31h = 2.700 |
|     |       |      |       | 32h = 2.750 |
|     |       |      |       | 33h = 2.800 |
|     |       |      |       | 34h = 2.850 |
|     |       |      |       | 35h = 2.900 |
|     |       |      |       | 36h = 2.950 |
|     |       |      |       | 37h = 3.000 |
|     |       |      |       | 38h = 3.050 |
|     |       |      |       | 39h = 3.100 |
|     |       |      |       | 3Ah = 3.150 |
|     |       |      |       | 3Bh = 3.200 |
|     |       |      |       | 3Ch = 3.250 |
|     |       |      |       | 3Dh = 3.300 |
|     |       |      |       | 3Eh = 3.350 |
|     |       |      |       | 3Fh = 3.400 |

#### 7.5.25 SEQ1 Register (subaddress = 0x20) [reset = 0x00]

SEQ1 is shown in [Figure 7-51](#) and described in [Table 7-28](#).

Return to [Table 7-6](#).

Password protected.

**Figure 7-51. SEQ1 Register**

| 7      | 6      | 5      | 4      | 3      | 2      | 1      | 0      |
|--------|--------|--------|--------|--------|--------|--------|--------|
| DLY8   | DLY7   | DLY6   | DLY5   | DLY4   | DLY3   | DLY2   | DLY1   |
| R/W-0b | R/W-0b | R/W-0b | R/W-0b | R/W-0b | R/W-0b | R/W-0b | R/W-0b |

**Table 7-28. SEQ1 Register Field Descriptions**

| Bit | Field | Type | Reset | Description                                                                   |
|-----|-------|------|-------|-------------------------------------------------------------------------------|
| 7   | DLY8  | R/W  | 0b    | Delay8 (occurs after Strobe 8 and before Strobe 9.)<br>0b = 2 ms<br>1b = 5 ms |
| 6   | DLY7  | R/W  | 0b    | Delay7 (occurs after Strobe 7 and before Strobe 8.)<br>0b = 2 ms<br>1b = 5 ms |
| 5   | DLY6  | R/W  | 0b    | Delay6 (occurs after Strobe 6 and before Strobe 7.)<br>0b = 2 ms<br>1b = 5 ms |
| 4   | DLY5  | R/W  | 0b    | Delay5 (occurs after Strobe 5 and before Strobe 6.)<br>0b = 2 ms<br>1b = 5 ms |
| 3   | DLY4  | R/W  | 0b    | Delay4 (occurs after Strobe 4 and before Strobe 5.)<br>0b = 2 ms<br>1b = 5 ms |
| 2   | DLY3  | R/W  | 0b    | Delay3 (occurs after Strobe 3 and before Strobe 4.)<br>0b = 2 ms<br>1b = 5 ms |
| 1   | DLY2  | R/W  | 0b    | Delay2 (occurs after Strobe 2 and before Strobe 3.)<br>0b = 2 ms<br>1b = 5 ms |
| 0   | DLY1  | R/W  | 0b    | Delay1 (occurs after Strobe 1 and before Strobe 2.)<br>0b = 2 ms<br>1b = 5 ms |

**7.5.26 SEQ2 Register (subaddress = 0x21) [reset = 0x00]**

SEQ2 is shown in [Figure 7-52](#) and described in [Table 7-29](#).

Return to [Table 7-6](#).

Password protected.

**Figure 7-52. SEQ2 Register**

|         |            |   |   |   |   |   |         |
|---------|------------|---|---|---|---|---|---------|
| 7       | 6          | 5 | 4 | 3 | 2 | 1 | 0       |
| DLYFCTR | RESERVED   |   |   |   |   |   | DLY9    |
| R/W -0b | R-000 000b |   |   |   |   |   | R/W -0b |

**Table 7-29. SEQ2 Register Field Descriptions**

| Bit | Field    | Type | Reset    | Description                                                                                                                                               |
|-----|----------|------|----------|-----------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7   | DLYFCTR  | R/W  | 0b       | Power-down delay factor:<br>0b = 1x<br>1b = 10x (delay times are multiplied by 10x during power-down.)<br>Note: DLYFCTR has no effect on power-up timing. |
| 6-1 | RESERVED | R    | 000 000b |                                                                                                                                                           |
| 0   | DLY9     | R/W  | 0b       | Delay9 (occurs after Strobe 9 and before Strobe 10.)<br>0b = 2 ms<br>1b = 5 ms                                                                            |

### 7.5.27 SEQ3 Register (subaddress = 0x22)[reset = 0x86]

SEQ3 is shown in [Figure 7-53](#) and described in [Table 7-30](#).

Return to [Table 7-6](#).

Password protected.

**Figure 7-53. SEQ3 Register**

| 7       | 6 | 5 | 4 | 3       | 2 | 1 | 0 |
|---------|---|---|---|---------|---|---|---|
| DC2_SEQ |   |   |   | DC1_SEQ |   |   |   |
| R/W-8h  |   |   |   | R/W-6h  |   |   |   |

**Table 7-30. SEQ3 Register Field Descriptions**

| Bit | Field   | Type | Reset | Description                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                   |
|-----|---------|------|-------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7-4 | DC2_SEQ | R/W  | 8h    | DCDC2 enable STROBE:<br>0h = Rail is not controlled by sequencer.<br>1h = Rail is not controlled by sequencer.<br>2h = Rail is not controlled by sequencer.<br>3h = Enable at STROBE 3.<br>4h = Enable at STROBE 4.<br>5h = Enable at STROBE 5.<br>6h = Enable at STROBE 6.<br>7h = Enable at STROBE 7.<br>8h = Enable at STROBE 8.<br>9h = Enable at STROBE 9.<br>Ah = Enable at STROBE 10.<br>Bh = Rail is not controlled by sequencer.<br>Ch = Rail is not controlled by sequencer.<br>Dh = Rail is not controlled by sequencer.<br>Eh = Rail is not controlled by sequencer.<br>Fh = Rail is not controlled by sequencer. |
| 3-0 | DC1_SEQ | R/W  | 6h    | DCDC1 enable STROBE:<br>0h = Rail is not controlled by sequencer.<br>1h = Rail is not controlled by sequencer.<br>2h = Rail is not controlled by sequencer.<br>3h = Enable at STROBE 3.<br>4h = Enable at STROBE 4.<br>5h = Enable at STROBE 5.<br>6h = Enable at STROBE 6.<br>7h = Enable at STROBE 7.<br>8h = Enable at STROBE 8.<br>9h = Enable at STROBE 9.<br>Ah = Enable at STROBE 10.<br>Bh = Rail is not controlled by sequencer.<br>Ch = Rail is not controlled by sequencer.<br>Dh = Rail is not controlled by sequencer.<br>Eh = Rail is not controlled by sequencer.<br>Fh = Rail is not controlled by sequencer. |

### 7.5.28 SEQ4 Register (subaddress = 0x23) [reset = 0x84]

SEQ4 is shown in [Figure 7-54](#) and described in [Table 7-31](#).

Return to [Table 7-6](#).

Password protected.

**Figure 7-54. SEQ4 Register**

| 7       | 6 | 5 | 4 | 3       | 2 | 1 | 0 |
|---------|---|---|---|---------|---|---|---|
| DC4_SEQ |   |   |   | DC3_SEQ |   |   |   |
| R/W-8h  |   |   |   | R/W-4h  |   |   |   |

**Table 7-31. SEQ4 Register Field Descriptions**

| Bit | Field   | Type | Reset | Description                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                   |
|-----|---------|------|-------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7-4 | DC4_SEQ | R/W  | 8h    | DCDC4 enable STROBE:<br>0h = Rail is not controlled by sequencer.<br>1h = Rail is not controlled by sequencer.<br>2h = Rail is not controlled by sequencer.<br>3h = Enable at STROBE 3.<br>4h = Enable at STROBE 4.<br>5h = Enable at STROBE 5.<br>6h = Enable at STROBE 6.<br>7h = Enable at STROBE 7.<br>8h = Enable at STROBE 8.<br>9h = Enable at STROBE 9.<br>Ah = Enable at STROBE 10.<br>Bh = Rail is not controlled by sequencer.<br>Ch = Rail is not controlled by sequencer.<br>Dh = Rail is not controlled by sequencer.<br>Eh = Rail is not controlled by sequencer.<br>Fh = Rail is not controlled by sequencer. |
| 3-0 | DC3_SEQ | R/W  | 4h    | DCDC3 enable STROBE:<br>0h = Rail is not controlled by sequencer.<br>1h = Rail is not controlled by sequencer.<br>2h = Rail is not controlled by sequencer.<br>3h = Enable at STROBE 3.<br>4h = Enable at STROBE 4.<br>5h = Enable at STROBE 5.<br>6h = Enable at STROBE 6.<br>7h = Enable at STROBE 7.<br>8h = Enable at STROBE 8.<br>9h = Enable at STROBE 9.<br>Ah = Enable at STROBE 10.<br>Bh = Rail is not controlled by sequencer.<br>Ch = Rail is not controlled by sequencer.<br>Dh = Rail is not controlled by sequencer.<br>Eh = Rail is not controlled by sequencer.<br>Fh = Rail is not controlled by sequencer. |

### 7.5.29 SEQ5 Register (subaddress = 0x24) [reset = 0x10]

SEQ5 is shown in [Figure 7-55](#) and described in [Table 7-32](#).

Return to [Table 7-6](#).

Password protected.

**Figure 7-55. SEQ5 Register**

| 7        | 6 | 5       | 4 | 3        | 2 | 1       | 0 |
|----------|---|---------|---|----------|---|---------|---|
| RESERVED |   | DC6_SEQ |   | RESERVED |   | DC5_SEQ |   |



**Figure 7-55. SEQ5 Register (continued)**

|      |        |      |        |
|------|--------|------|--------|
| R-0h | R/W-1h | R-0h | R/W-1h |
|------|--------|------|--------|

**Table 7-32. SEQ5 Register Field Descriptions**

| Bit | Field    | Type | Reset | Description                                                                                                                                                                                                                                                                                                   |
|-----|----------|------|-------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7-6 | RESERVED | R    | 0h    |                                                                                                                                                                                                                                                                                                               |
| 5-4 | DC6_SEQ  | R/W  | 1h    | DCDC6 enable STROBE. Note: STROBE 1 and STROBE 2 are executed only if FSEAL = 0. DCDC5 and 6 cannot be disabled by sequencer once freshness seal is broken.<br>0h = Rail is not controlled by sequencer.<br>1h = Enable at STROBE 1.<br>2h = Enable at STROBE 2.<br>3h = Rail is not controlled by sequencer. |
| 3-2 | RESERVED | R    | 0h    |                                                                                                                                                                                                                                                                                                               |
| 1-0 | DC5_SEQ  | R/W  | 1h    | DCDC5 enable STROBE. Note: STROBE 1 and STROBE 2 are executed only if FSEAL = 0. DCDC5 and 6 cannot be disabled by sequencer once freshness seal is broken.<br>0h = Rail is not controlled by sequencer.<br>1h = Enable at STROBE 1.<br>2h = Enable at STROBE 2.<br>3h = Rail is not controlled by sequencer. |

### 7.5.30 SEQ6 Register (subaddress = 0x25) [reset = 0x88]

SEQ6 is shown in [Figure 7-56](#) and described in [Table 7-33](#).

Return to [Table 7-6](#).

Password protected.

**Figure 7-56. SEQ6 Register**

|         |   |   |   |          |   |   |   |
|---------|---|---|---|----------|---|---|---|
| 7       | 6 | 5 | 4 | 3        | 2 | 1 | 0 |
| LS1_SEQ |   |   |   | LDO1_SEQ |   |   |   |
| R/W-8h  |   |   |   | R/W-8h   |   |   |   |

**Table 7-33. SEQ6 Register Field Descriptions**

| Bit | Field   | Type | Reset | Description                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                 |
|-----|---------|------|-------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7-4 | LS1_SEQ | R/W  | 8h    | LS1 enable STROBE:<br>0h = Rail is not controlled by sequencer.<br>1h = Rail is not controlled by sequencer.<br>2h = Rail is not controlled by sequencer.<br>3h = Enable at STROBE 3.<br>4h = Enable at STROBE 4.<br>5h = Enable at STROBE 5.<br>6h = Enable at STROBE 6.<br>7h = Enable at STROBE 7.<br>8h = Enable at STROBE 8.<br>9h = Enable at STROBE 9.<br>Ah = Enable at STROBE 10.<br>Bh = Rail is not controlled by sequencer.<br>Ch = Rail is not controlled by sequencer.<br>Dh = Rail is not controlled by sequencer.<br>Eh = Rail is not controlled by sequencer.<br>Fh = Rail is not controlled by sequencer. |

**Table 7-33. SEQ6 Register Field Descriptions (continued)**

| Bit | Field    | Type | Reset | Description                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                  |
|-----|----------|------|-------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 3-0 | LDO1_SEQ | R/W  | 8h    | LDO1 enable STROBE:<br>0h = Rail is not controlled by sequencer.<br>1h = Rail is not controlled by sequencer.<br>2h = Rail is not controlled by sequencer.<br>3h = Enable at STROBE 3.<br>4h = Enable at STROBE 4.<br>5h = Enable at STROBE 5.<br>6h = Enable at STROBE 6.<br>7h = Enable at STROBE 7.<br>8h = Enable at STROBE 8.<br>9h = Enable at STROBE 9.<br>Ah = Enable at STROBE 10.<br>Bh = Rail is not controlled by sequencer.<br>Ch = Rail is not controlled by sequencer.<br>Dh = Rail is not controlled by sequencer.<br>Eh = Rail is not controlled by sequencer.<br>Fh = Rail is not controlled by sequencer. |

**7.5.31 SEQ7 Register (subaddress = 0x26) [reset = 0x08]**

SEQ7 is shown in [Figure 7-57](#) and described in [Table 7-34](#).

Return to [Table 7-6](#).

Password protected.

**Figure 7-57. SEQ7 Register**

|          |   |   |   |          |   |   |   |
|----------|---|---|---|----------|---|---|---|
| 7        | 6 | 5 | 4 | 3        | 2 | 1 | 0 |
| GPO3_SEQ |   |   |   | GPO1_SEQ |   |   |   |
| R/W-0h   |   |   |   | R/W-8h   |   |   |   |

**Table 7-34. SEQ7 Register Field Descriptions**

| Bit | Field    | Type | Reset | Description                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                  |
|-----|----------|------|-------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 7-4 | GPO3_SEQ | R/W  | 0h    | GPO3 enable STROBE:<br>0h = Rail is not controlled by sequencer.<br>1h = Rail is not controlled by sequencer.<br>2h = Rail is not controlled by sequencer.<br>3h = Enable at STROBE 3.<br>4h = Enable at STROBE 4.<br>5h = Enable at STROBE 5.<br>6h = Enable at STROBE 6.<br>7h = Enable at STROBE 7.<br>8h = Enable at STROBE 8.<br>9h = Enable at STROBE 9.<br>Ah = Enable at STROBE 10.<br>Bh = Rail is not controlled by sequencer.<br>Ch = Rail is not controlled by sequencer.<br>Dh = Rail is not controlled by sequencer.<br>Eh = Rail is not controlled by sequencer.<br>Fh = Rail is not controlled by sequencer. |

**Table 7-34. SEQ7 Register Field Descriptions (continued)**

| Bit | Field    | Type | Reset | Description                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                         |
|-----|----------|------|-------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 3-0 | GPO1_SEQ | R/W  | 8h    | <p>GPO1 enable STROBE:</p> <p>0h = Rail is not controlled by sequencer.</p> <p>1h = Rail is not controlled by sequencer.</p> <p>2h = Rail is not controlled by sequencer.</p> <p>3h = Enable at STROBE 3.</p> <p>4h = Enable at STROBE 4.</p> <p>5h = Enable at STROBE 5.</p> <p>6h = Enable at STROBE 6.</p> <p>7h = Enable at STROBE 7.</p> <p>8h = Enable at STROBE 8.</p> <p>9h = Enable at STROBE 9.</p> <p>Ah = Enable at STROBE 10.</p> <p>Bh = Rail is not controlled by sequencer.</p> <p>Ch = Rail is not controlled by sequencer.</p> <p>Dh = Rail is not controlled by sequencer.</p> <p>Eh = Rail is not controlled by sequencer.</p> <p>Fh = Rail is not controlled by sequencer.</p> |

## 8 Application and Implementation

### Note

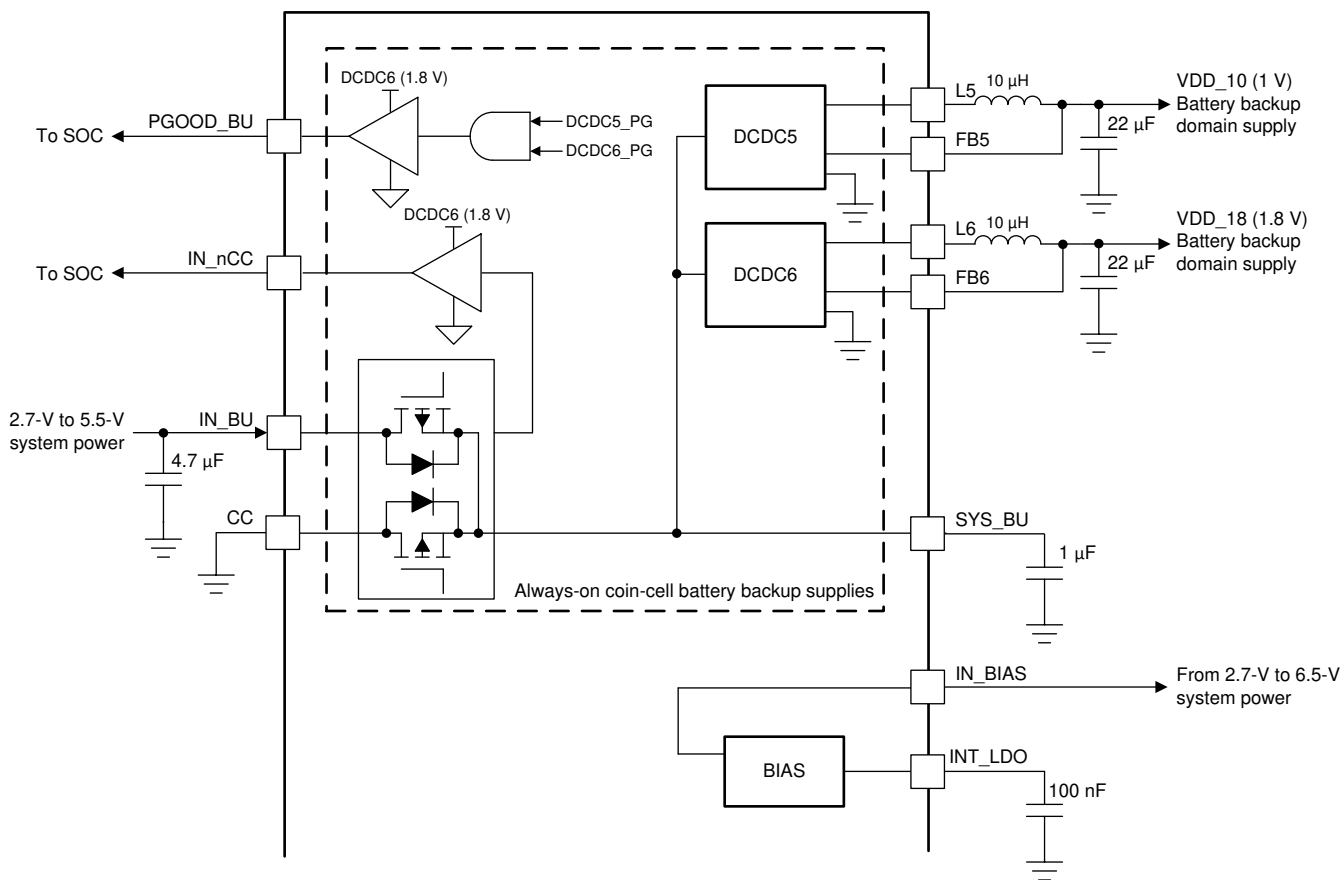
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

### 8.1 Application Information

The TPS6521835 is designed to pair with NXP i.MX 6ULL, 6ULZ, and 6UltraLite processors. The typical application in [Section 8.2](#) is based on and uses terminology consistent with the Sitara™ family of processors.

#### 8.1.1 Applications Without Backup Battery

In applications that require always-on supplies but no battery backup, the CC input to the power path must be connected to ground.



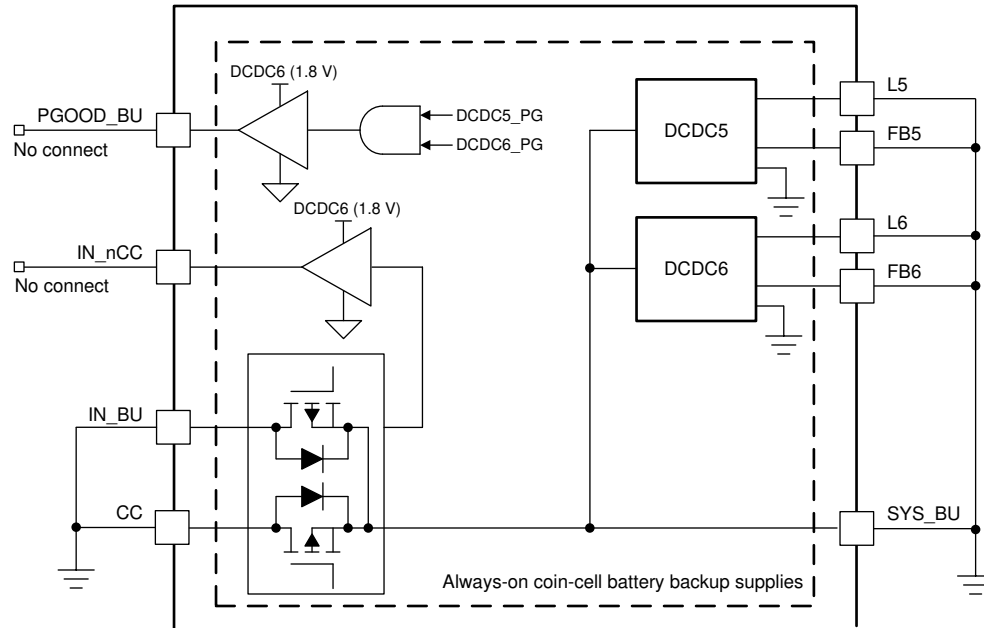
**Figure 8-1. CC Input to Power Path**

### Note

In applications without backup battery, CC input must be tied to ground.

### 8.1.2 Applications Without Battery Backup Supplies

In applications that do not require always-on supplies, both inputs and the output of the power-path can simply be grounded. All pins related to DCDC5 and DCDC6 are also tied to ground, and PGOOD\_BU and IN\_nCC are kept floating. With the backup supplies completely disabled, the FSEAL bit in the STATUS register is undefined and should be ignored.

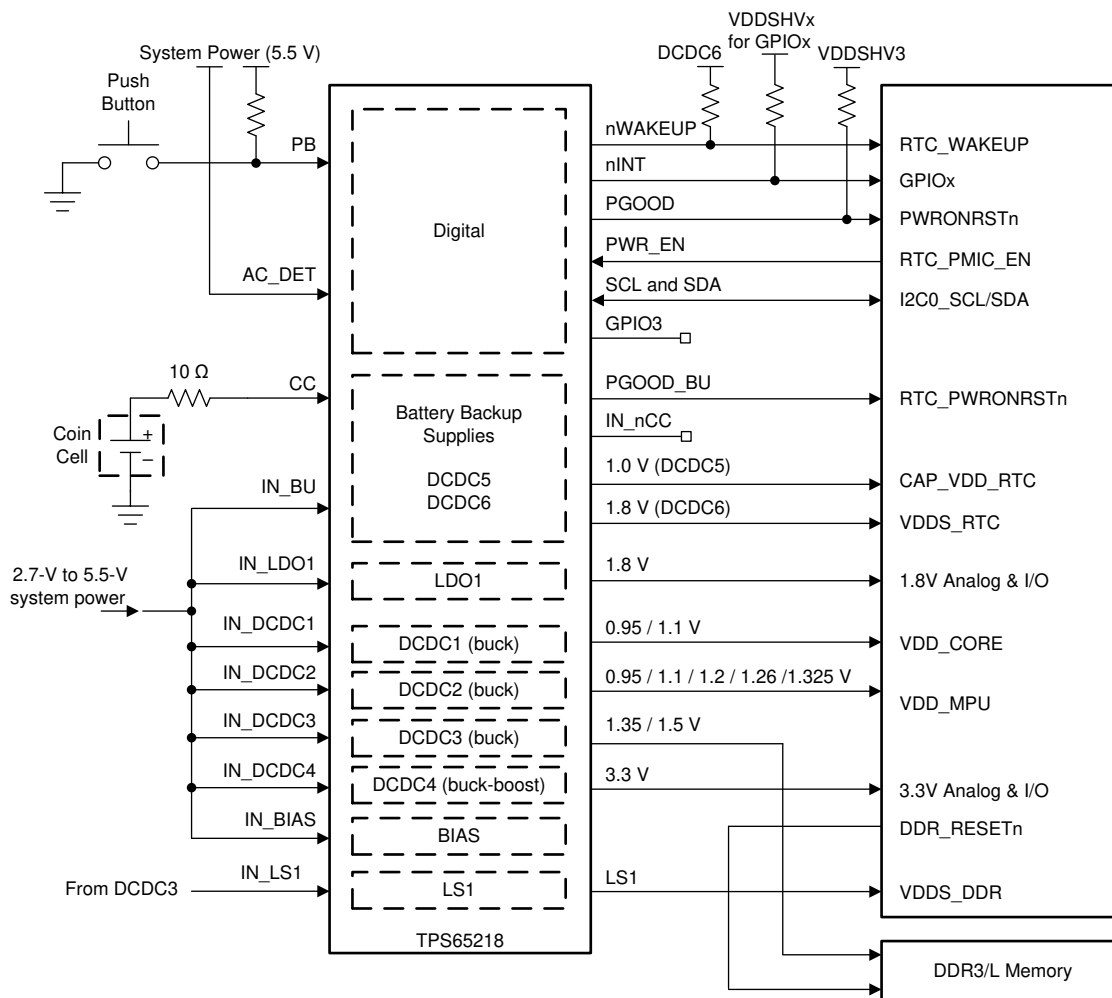


**Figure 8-2. DCDC5 and DCDC6 Pins**

#### Note

In applications that do not require always-on supplies, PGOOD\_BU and IN\_nCC can be kept floating. All other pins are tied to ground.

## 8.2 Typical Application



- A. Block diagram shows TPS65218D0 powering AM437x processor. For TPS6521835, refer to this [Tech Note](#). For TPS6521815, the wiring is not predefined and is programmed for the specific processor in the application.

**Figure 8-3. Typical Application Schematic for TPS65218D0**

## 8.2.1 Design Requirements

Table 8-1 lists the design requirements.

**Table 8-1. Design Parameters for TPS65218D0 <sup>(1)</sup>**

|       | VOLTAGE | SEQUENCE |
|-------|---------|----------|
| DCDC1 | 1.1 V   | 8        |
| DCDC2 | 1.1 V   | 9        |
| DCDC3 | 1.2 V   | 5        |
| DCDC4 | 3.3 V   | 7        |
| DCDC5 | 1.0 V   | 2        |
| DCDC6 | 1.8 V   | 1        |
| LDO1  | 1.8 V   | 3        |

(1) Default output voltages shown for TPS65218D0. For other TPS65218xx variants, refer to DCDC1-4 and LDO1 registers in [Section 7.5.4](#).

## 8.2.2 Detailed Design Procedure

### 8.2.2.1 Output Filter Design

The step down converters (DCDC1, DCDC2, and DCDC3) on TPS6521835 are designed to operate with effective inductance values in the range of 1 to 2.2  $\mu\text{H}$  and with effective output capacitance in the range of 10 to 100  $\mu\text{F}$ . The internal compensation is optimized to operate with an output filter of  $L = 1.5 \mu\text{H}$  and  $C_{\text{OUT}} = 10 \mu\text{F}$ .

The buck boost converter (DCDC4) on TPS6521835 is designed to operate with effective inductance values in the range of 1.2 to 2.2  $\mu\text{H}$ . The internal compensation is optimized to operate with an output filter of  $L = 1.5 \mu\text{H}$  and  $C_{\text{OUT}} = 47 \mu\text{F}$ .

The two battery backup converters (DCDC5 and DCDC6) are designed to operate with effective inductance values in the range of 4.7 to 22  $\mu\text{H}$ . The internal compensation is optimized with an output filter of  $L = 10 \mu\text{H}$  and  $C_{\text{OUT}} = 20 \mu\text{F}$ .

Larger or smaller inductor/capacitance values can be used to optimize performance of the device for specific operation conditions.

### 8.2.2.2 Inductor Selection for Buck Converters

The inductor value affects its peak to peak ripple current, the PWM to PFM transition point, the output voltage ripple, and the efficiency. The selected inductor must be rated for its DC resistance and saturation current. The inductor ripple current ( $\Delta I_L$ ) decreases with higher inductance and increases with higher  $V_{\text{IN}}$  or  $V_{\text{OUT}}$ . [Equation 1](#) calculates the maximum inductor current ripple under static load conditions. The saturation current of the inductor should be rated higher than the maximum inductor current as calculated with [Equation 2](#). This is recommended as during heavy load transient the inductor current will rise above the calculated value.

$$\Delta I_L = V_{\text{OUT}} \times \frac{1 - \frac{V_{\text{OUT}}}{V_{\text{IN}}}}{L \times f} \quad (1)$$

$$I_{L\text{max}} = I_{\text{OUTmax}} + \frac{\Delta I_L}{2} \quad (2)$$

where

- $F$  = Switching frequency
- $L$  = Inductor value
- $\Delta I_L$  = Peak-to-peak inductor ripple current
- $I_{L\text{max}}$  = Maximum inductor current

The following inductors have been used with the TPS6521835 (see [Table 8-2](#)).

**Table 8-2. List of Recommended Inductors**

| PART NUMBER                                     | VALUE                               | SIZE (mm) [L × W × H]            | MANUFACTURER |
|-------------------------------------------------|-------------------------------------|----------------------------------|--------------|
| <b>INDUCTORS FOR DCDC1, DCDC2, DCDC3, DCDC4</b> |                                     |                                  |              |
| SPM3012T-1R5M                                   | 1.5 $\mu$ H, 2.8 A, 77 m $\Omega$   | 3.2 × 3.0 × 1.2                  | TDK          |
| IHLP1212BZER1R5M11                              | 1.5 $\mu$ H, 4.0 A, 28.5 m $\Omega$ | 3.6 × 3.0 × 2.0                  | Vishay       |
| <b>INDUCTORS FOR DCDC5, DCDC6</b>               |                                     |                                  |              |
| MLZ2012N100L                                    | 10 $\mu$ H, 110 mA, 300 m $\Omega$  | 2012 / 0805 (2.00 × 1.25 × 1.25) | TDK          |
| LQM21FN100M80                                   | 10 $\mu$ H, 100 mA, 300 m $\Omega$  | 2012 / 0805 (2.00 × 1.25 × 1.25) | Murata       |

### 8.2.2.3 Output Capacitor Selection

The hysteretic PWM control scheme of the TPS6521835 switching converters allows the use of tiny ceramic capacitors. Ceramic capacitors with low ESR values have the lowest output voltage ripple and are recommended. The output capacitor requires either an X7R or X5R dielectric.

At light load currents the converter operates in power save mode, and the output voltage ripple is dependent on the output capacitor value and the PFM peak inductor current. Higher output capacitor values minimize the voltage ripple in PFM Mode and tighten DC output accuracy in PFM mode.

The two battery backup converters (DCDC5 and DCDC6) always operate in PFM mode. For these converters, a capacitor of at least 20  $\mu$ F is recommended on the output to help minimize voltage ripple.

The buck-boost converter requires additional output capacitance to help maintain converter stability during high load conditions. At least 40  $\mu$ F of output capacitance is recommended and an additional 100-nF capacitor can be added to further filter output ripple at higher frequencies.

[Table 8-2](#) lists the recommended capacitors.

**Table 8-3. List of Recommended Capacitors**

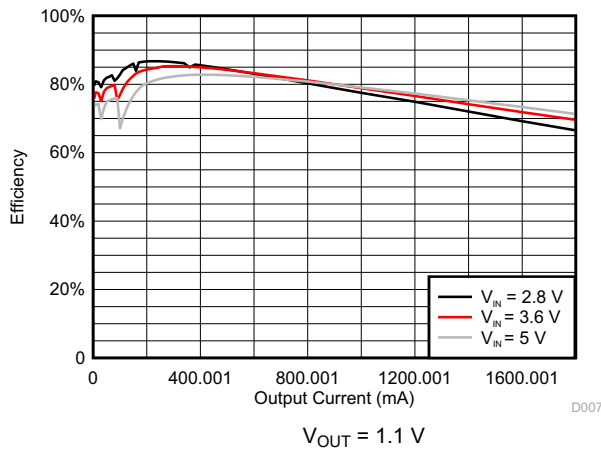
| PART NUMBER                                              | VALUE       | SIZE (mm) [L × W × H]           | MANUFACTURER |
|----------------------------------------------------------|-------------|---------------------------------|--------------|
| <b>CAPACITORS FOR VOLTAGES UP TO 5.5 V<sup>(1)</sup></b> |             |                                 |              |
| GRM188R60J105K                                           | 1 $\mu$ F   | 1608 / 0603 (1.6 × 0.8 × 0.8)   | Murata       |
| GRM21BR60J475K                                           | 4.7 $\mu$ F | 2012 / 0805 (2.0 × 1.25 × 1.25) | Murata       |
| GRM31MR60J106K                                           | 10 $\mu$ F  | 3216 / 1206 (3.2 × 1.6 × 1.6)   | Murata       |
| GRM31CR60J226K                                           | 22 $\mu$ F  | 3216 / 1206 (3.2 × 1.6 × 1.6)   | Murata       |
| <b>CAPACITORS FOR VOLTAGES UP TO 3.3 V<sup>(1)</sup></b> |             |                                 |              |
| GRM21BR60J106K                                           | 10 $\mu$ F  | 2012 / 0805 (2.0 × 1.25 × 1.25) | Murata       |

(1) The DC bias effect of ceramic capacitors must be considered when selecting a capacitor.

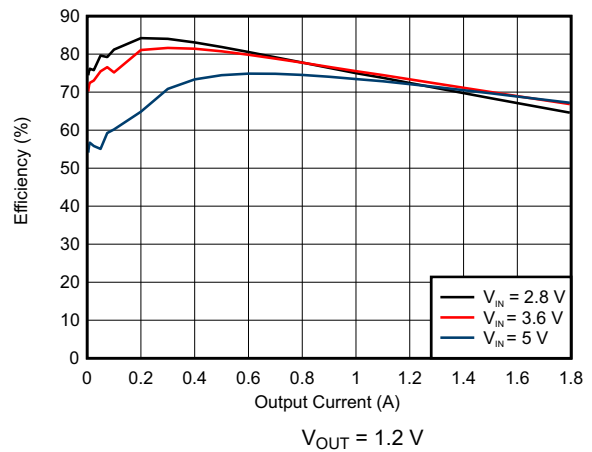


## 8.2.3 Application Curves

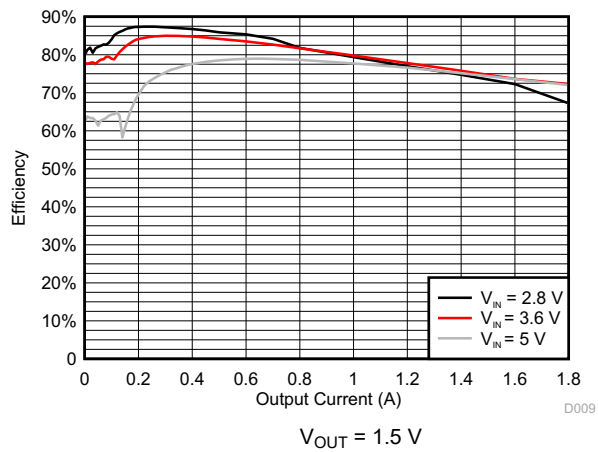
at  $T_J = 25^\circ\text{C}$  unless otherwise noted



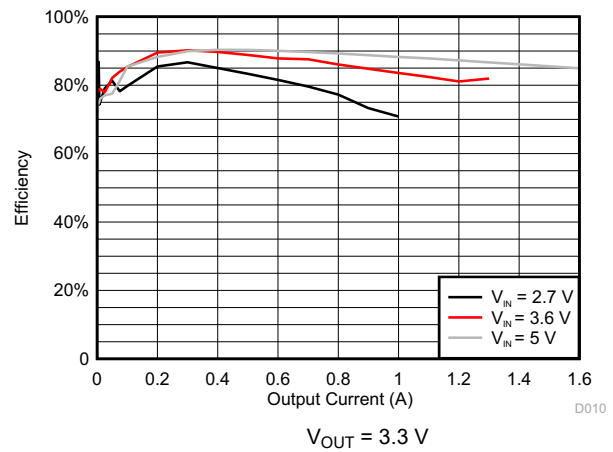
**Figure 8-4. DCDC1/DCDC2 Efficiency**



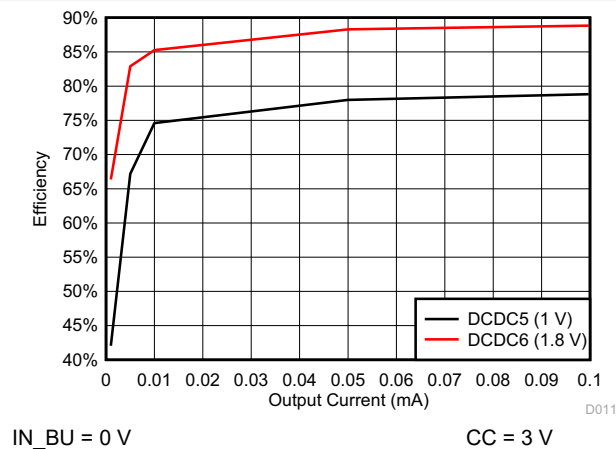
**Figure 8-5. DCDC3 Efficiency**



**Figure 8-6. DCDC3 Efficiency**



**Figure 8-7. DCDC4 Efficiency**



**Figure 8-8. DCDC5/DCDC6 Efficiency**

## 9 Power Supply Recommendations

The device is designed to operate with an input voltage supply range between 2.7 V and 5.5 V. This input supply can be from a single cell Li-Ion battery or other externally regulated supply. If the input supply is located more than a few inches from the additional bulk capacitance may be required in addition to the ceramic bypass capacitors. An electrolytic capacitor with a value of 47  $\mu$ F is a typical choice.

The coin cell back up input is designed to operate with an input voltage supply between 2.2 V and 3.3 V. This input should be supplied by a coin cell battery with 3-V nominal voltage.

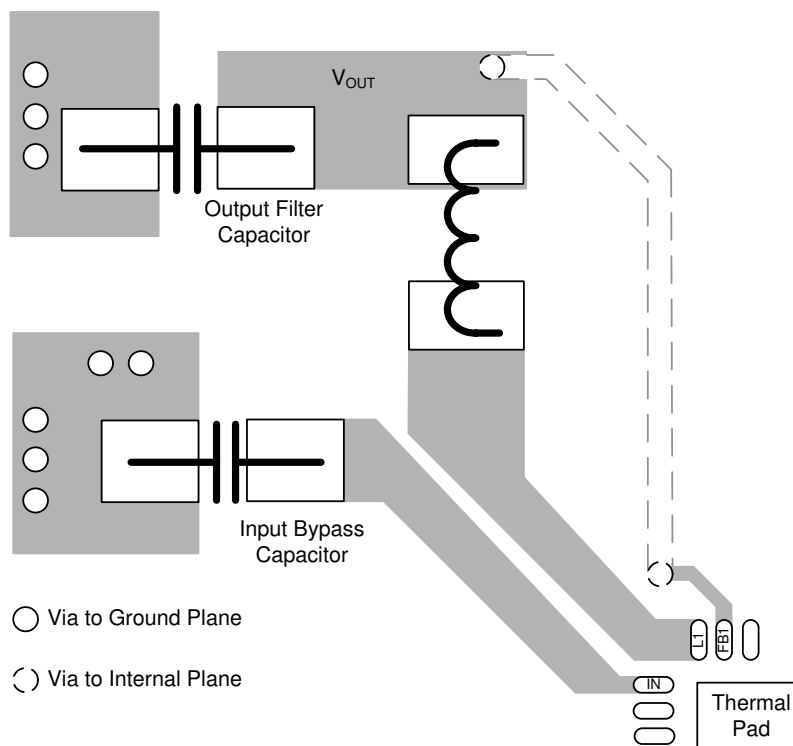
## 10 Layout

### 10.1 Layout Guidelines

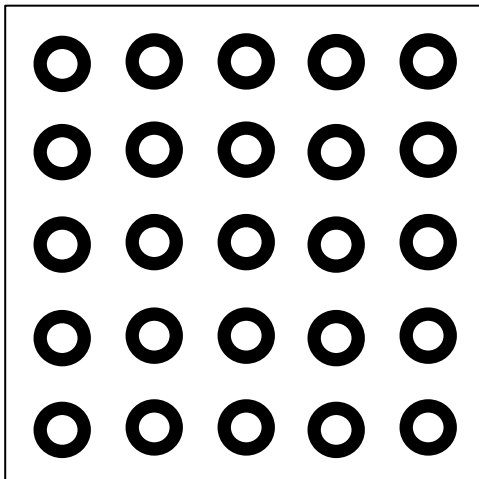
Follow these layout guidelines:

- The IN\_X pins should be bypassed to ground with a low ESR ceramic bypass capacitor. The typical recommended bypass capacitance is 4.7- $\mu$ F with a X5R or X7R dielectric.
- The optimum placement is closest to the IN\_X pins of the device. Take care to minimize the loop area formed by the bypass capacitor connection, the IN\_X pin, and the thermal pad of the device.
- The thermal pad should be tied to the PCB ground plane with a minimum of 25 vias. See Figure 10-2 for an example.
- The LX trace should be kept on the PCB top layer and free of any vias.
- The FBX traces should be routed away from any potential noise source to avoid coupling.
- DCDC4 Output capacitance should be placed immediately at the DCDC4 pin. Excessive distance between the capacitance and DCDC4 pin may cause poor converter performance.

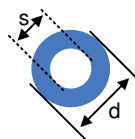
### 10.2 Layout Example



**Figure 10-1. Layout Recommendation**



Recommended Thermal Pad by size  
Hole size (s) = 8 mil  
Diameter (d) = 16 mil



**Figure 10-2. PowerPAD™ Layout Recommendation**

## 11 Device and Documentation Support

### 11.1 Documentation Support

#### 11.1.1 Related Documentation

For related documentation see the following:

- Texas Instruments, [Basic Calculation of a Buck Converter's Power Stage](#) application report
- Texas Instruments, [Design Calculations for Buck-Boost Converters](#) application report
- Texas Instruments, [Empowering Designs With Power Management IC \(PMIC\) for Processor Applications](#) application report
- Texas Instruments, [TPS65218EVM user's guide](#)
- Texas Instruments, [TPS65218 Power Management Integrated Circuit \(PMIC\) for Industrial Applications](#) application report

### 11.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 11.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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### 11.4 Trademarks

Sitara™ is a trademark of Texas Instruments.

TI E2E™ is a trademark of Texas Instruments.

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### 11.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 11.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

| Orderable part number          | Status<br>(1) | Material type<br>(2) | Package   Pins  | Package qty   Carrier | RoHS<br>(3) | Lead finish/<br>Ball material<br>(4) | MSL rating/<br>Peak reflow<br>(5) | Op temp (°C) | Part marking<br>(6) |
|--------------------------------|---------------|----------------------|-----------------|-----------------------|-------------|--------------------------------------|-----------------------------------|--------------|---------------------|
| <a href="#">TPS6521835RSLR</a> | Active        | Production           | VQFN (RSL)   48 | 2500   LARGE T&R      | Yes         | NIPDAU                               | Level-3-260C-168 HR               | -40 to 105   | T6521835            |
| TPS6521835RSLR.A               | Active        | Production           | VQFN (RSL)   48 | 2500   LARGE T&R      | Yes         | NIPDAU                               | Level-3-260C-168 HR               | -40 to 105   | T6521835            |
| <a href="#">TPS6521835RSLT</a> | Active        | Production           | VQFN (RSL)   48 | 250   SMALL T&R       | Yes         | NIPDAU                               | Level-3-260C-168 HR               | -40 to 105   | T6521835            |
| TPS6521835RSLT.A               | Active        | Production           | VQFN (RSL)   48 | 250   SMALL T&R       | Yes         | NIPDAU                               | Level-3-260C-168 HR               | -40 to 105   | T6521835            |

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

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## GENERIC PACKAGE VIEW

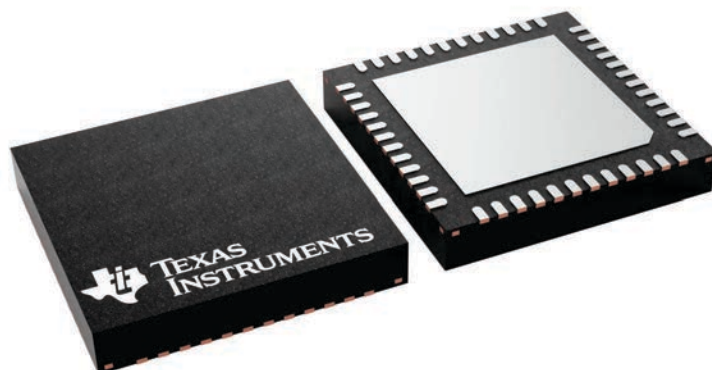
**RSL 48**

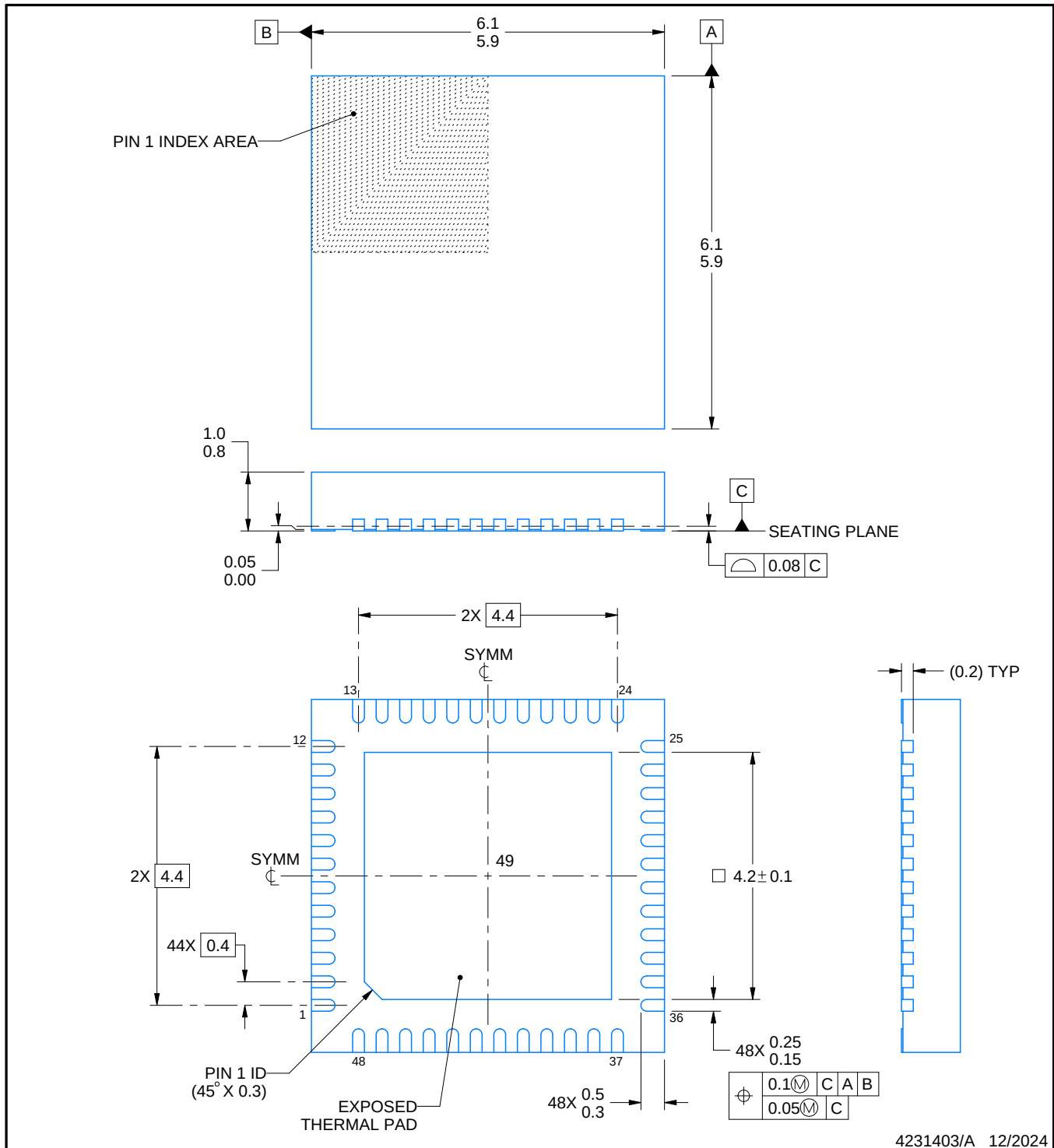
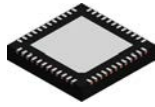
**VQFN - 1 mm max height**

6 x 6, 0.4 mm pitch

QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.





## NOTES:

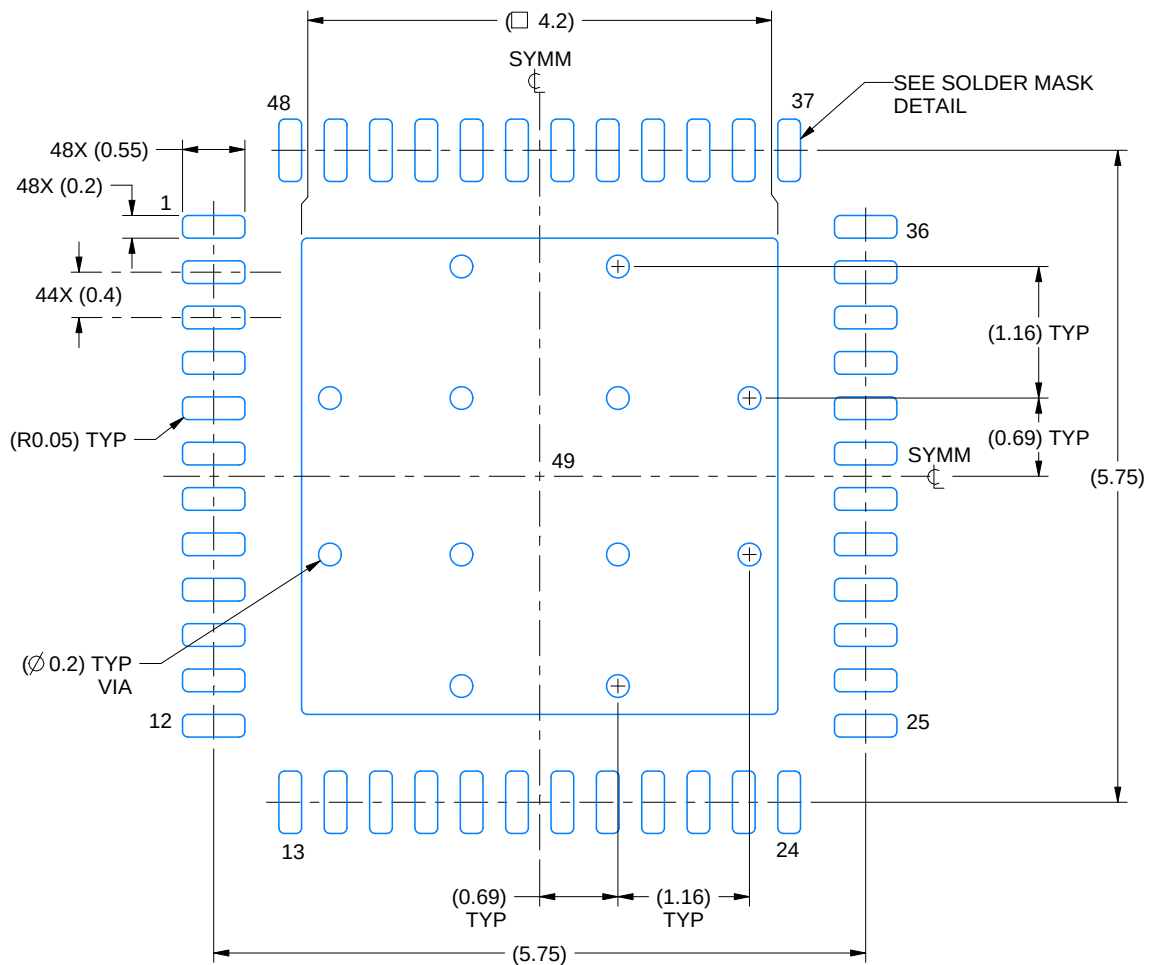
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

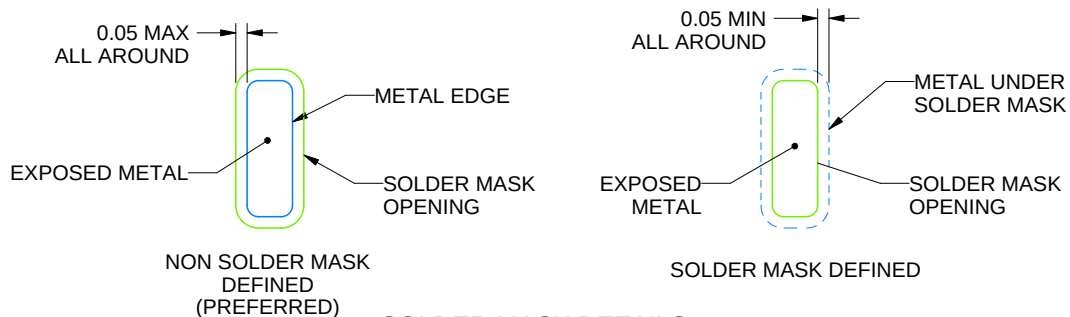
RSL0048G

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 15X



SOLDER MASK DETAILS

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NOTES: (continued)

- This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).
- Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

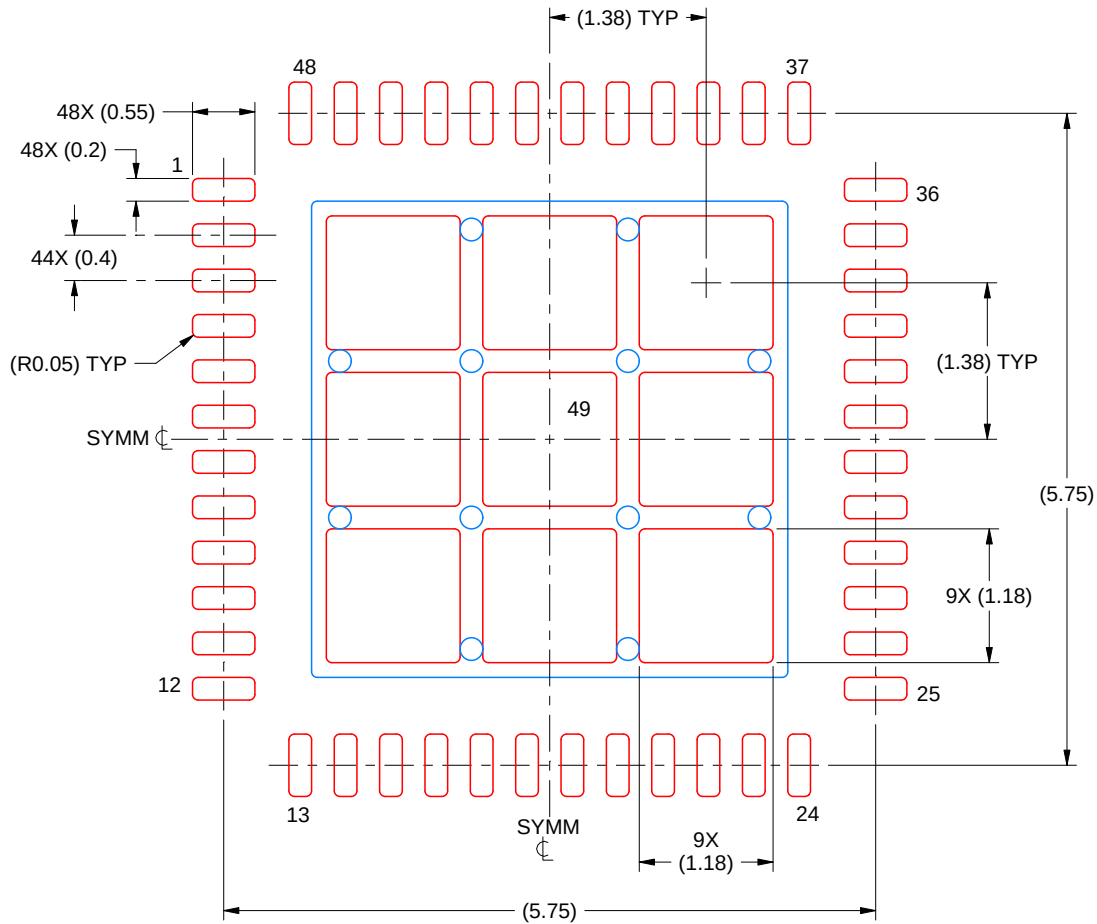


# EXAMPLE STENCIL DESIGN

RSL0048G

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.1 MM THICK STENCIL  
SCALE: 15X

EXPOSED PAD 49  
71% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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